

# COMPANY CONFIDENTIAL

## CONTENTS

1	DOCUMENT CONVENTIONS .....	3
2	SERVICE LEVELS .....	3
3	PRODUCT DESCRIPTION .....	4
4	TECHNICAL SPECIFICATION .....	4
5	RECOMMENDED TOOLS AND MATERIALS .....	6
6	RECOMMENDED TEST EQUIPMENT .....	7
7	CIRCUIT OPERATIONAL DESCRIPTIONS .....	8
	<u>CIRCUIT OPERATIONAL DESCRIPTION - CONNECTIONS</u> .....	9
	7.1 System Connector .....	9
	7.4 Battery Pack Interface .....	9
	<u>CIRCUIT OPERATIONAL DESCRIPTION - POWER</u> .....	11
	7.5 Power On .....	11
	7.6 Power Off .....	11
	7.7 Regulators .....	11
	7.8 Buzzer Amplifier .....	12
	7.10 8-Bit Serial Register .....	12
	7.11 +5V Regulator .....	12
	7.12 Charger Control .....	12
	<u>CIRCUIT OPERATIONAL DESCRIPTION - PROCESSOR</u> .....	14
	7.13 Microprocessor .....	14
	7.14 SIM Processor .....	16
	7.15 External EEPROM .....	16
	<u>CIRCUIT OPERATIONAL DESCRIPTION - BASEBAND</u> .....	18
	7.16 Receive Audio .....	18
	7.16 Transmit Audio .....	19
	7.18 EXTIN .....	20
	7.19 Y-Loop .....	20
	7.20 FFSK Demodulation .....	20
	7.21 FFSK Modulation .....	20
	7.22 DTMF Encode .....	21
	7.23 Digital to Analogue Converters .....	21
	7.24 Oscillator .....	21
	7.25 Control Logic .....	21
	<u>CIRCUIT OPERATIONAL DESCRIPTION - RECEIVER</u> .....	22
	7.26 LNA .....	23
	7.27 RF Attenuator .....	23
	7.28 RF Band Pass Filter .....	23
	7.29 1st Mixer .....	23
	7.30 1st IF Filter .....	23
	7.31 1st IF Amplifier .....	23
	7.32 2nd LO X3 Freq Multiplier .....	24
	7.33 RX IF Demodulator .....	24
	7.34 RSSI .....	24
	<u>CIRCUIT OPERATIONAL DESCRIPTION - SYNTHESISER</u> .....	26
	7.37 Transmitter Modulation .....	27
	7.38 RX Synthesiser .....	27
	7.39 VTX Regulator .....	27
	7.40 3VIF Regulator .....	27
	7.41 3VRX Switch .....	27
	<u>CIRCUIT OPERATIONAL DESCRIPTION - TRANSMITTER</u> .....	30
	7.42 Attenuator .....	30
	7.43 Gain Controlled Amplifier .....	30
	7.44 TX Interstage Band Pass Filter .....	30
	7.45 TX Power Amplifier .....	30
	7.46 Duplexer .....	30

# COMPANY CONFIDENTIAL

7.47	External Antenna Socket .....	30
7.48	Unity Gain Buffer .....	31
<b>8</b>	<b>CALIBRATION PROCEDURE .....</b>	<b>33</b>
8.1	Equipment Required .....	33
8.2	Connecting the Equipment .....	33
8.3	Starting up the Diagnostics Software .....	33
8.4	Get Phone Details .....	33
8.5	Main Menu .....	34
8.6	Calibration Menu .....	34
8.7	TX Frequency .....	34
8.8	RX RSSI .....	34
8.9	TX Power .....	34
8.10	RX Audio Level .....	35
8.11	TX Max Deviation .....	35
8.12	TX Audio Deviation .....	35
8.13	FFSK Deviation .....	36
8.14	SAT Dev .....	36
<b>9</b>	<b>PROGRAMMING PROCEDURE .....</b>	<b>38</b>
9.1	Equipment Required .....	38
9.2	Connecting the Equipment .....	38
9.3	Starting up the Diagnostics Software .....	38
9.4	Get Phone Details .....	39
9.5	Main Menu .....	39
9.6	Programming .....	39
<b>10</b>	<b>BASIC SERVICING PROCEDURE - .....</b>	<b>41</b>
10.1	Removing the Battery Pack .....	41
10.2	Removing the Volume Button .....	41
10.3	Removing the Back Moulding .....	42
10.4	Removing the PCB .....	42
10.5	Changing the Cover Moulding .....	43
10.6	Changing the Keymat .....	43
10.7	Changing the Microphone .....	44
10.8	Changing the Speaker .....	44
10.9	Changing the LCD Panel .....	45
10.10	Reassembling the phone .....	46
<b>11</b>	<b>FAULT DIAGNOSIS .....</b>	<b>48</b>
<b>12</b>	<b>MECHANICAL ASSEMBLY DIAGRAMS AND PARTS LISTS .....</b>	<b>49</b>
<b>13</b>	<b>CIRCUIT DIAGRAMS, PCB ASSEMBLY DIAGRAMS AND PARTS LISTS .....</b>	<b>51</b>
<b>14</b>	<b>ORDERING SPARE PARTS .....</b>	<b>80</b>
<b>15</b>	<b>RETURNING UNITS/ASSEMBLIES TO TELLIT COMMUNICATIONS LIMITED .....</b>	<b>80</b>
<b>16</b>	<b>SERVICE REPORTS .....</b>	<b>80</b>
<b>17</b>	<b>A66 BLOCK DIAGRAM DESCRIPTION .....</b>	<b>81</b>
	INTRODUCTION .....	81
17.1	Transmitter .....	81
17.2	Receiver .....	81
17.3	Synthesiser .....	82
17.4	BaseBand Processor .....	83
17.5	Processor .....	84
17.6	Power .....	85
17.7	Connections .....	86

# COMPANY CONFIDENTIAL

## 1 Document Conventions

1.1 In this Service Manual certain conventions are used to indicate where precautions are required.

1.2 The following provides an example of a warning.

***Warning – Do not dispose of cells in fire.***

Failure to observe a warning may result in injury or death.

1.3 The following provides an example of a caution.

***Caution – Do not short-circuit the terminals of the battery pack.***

Failure to observe a caution may result in damage to equipment.

1.4 The following provides an example of a notice.

***Note - Check the integrity of the coaxial cable before making SINAD measurements***

Notes are provided as advice and guidance to service personnel.

## 2 Service Levels

2.1 Tellit Communications Limited provides support to Service Engineers who have been approved and trained for the maintenance of its products. Three levels of service are provided as follows:

1

2.2 Service Level 1 – This service level applies if the Distributor's personnel have received no product specific training or if the perceived fault is outside the Distributor's level of competence. An equivalent product from the Company's exchange stock held by the Distributor will replace the product.

2

2.3 Service Level 2 – This service level applies if the Distributor's personnel been trained and authorised to perform service to level 2 on the product. This level enables the Distributor to replace parts down to module level. Typically this would include replacing external mechanical parts, replacing speaker, microphone, LCD Display panel etc.

3

2.4 Service Level 3 – This service level applies if the Distributor's personnel have been trained and authorised to perform service to level 3 on the product. This level provides for service down to electrical component level. Products having faulty PCBs or other components may be repaired as required.

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## 3 Product Description

3.1 The A66 is a compact high performance Low Emission Mobile Station (LEMS) intended for use within mobile networks conforming to the Nordic Mobile Telephone 450 MHz (NMT 450) standard. Several versions of the A66, as detailed in Table 3-1, are provided intended for use in a variety of national versions of the NMT 450 system. These different versions of the equipment use different transmit and receive radio frequencies as required for use in the country specific versions of the NMT 450 system.

3.2 To be continued!

## 4 Technical Specification

4.1 Environmental

Operational Temperature Range: -10°C to +55°C

Transmitter:

RF Power Output: 100 mW  $\pm$  3dB

Maximum Frequency Error:  $\pm$  2.5 kHz, -10°C to +55°C

Spurious Emissions:

	100 kHz – 1GHz	1-4 GHz
Transmitter ON	<0.25 $\mu$ W	<1 $\mu$ W
Transmitter in standby mode	<2 nW	<20 nW

Maximum frequency deviation:  $\pm$  4.7 kHz

Adjacent channel power: Better than 70 dB below carrier

Tx Harmonic distortion: <5%

4.2 Supervisory Tone Deviation  $\pm$ 300 Hz Nominal.

4.3 Receiver:

RF Sensitivity – 117 dBm (20 dB SINAD) +15°C to +45°C

- 114 dBm (20 dB SINAD) -10°C to +15°C and +35°C to +55°C

Duplex Sensitivity Degradation: <3 dB

Adjacent channel selectivity: >64 dB under normal test conditions (+15° to +35°C)

>60 dB under extreme conditions (-10°C and +55°C)

Spurious response rejection: >67 dB outside NMT band; >60 within

Intermodulation Rejection: >63 dB

Blocking Level: >85 dBuV EMF

4.4 Spurious emissions:

100 kHz – 1GHz	1 GHz – 4 GHz
< 2 nW	< 20 nW

Harmonic distortion: < 5%

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Country	Band	TX Start Channel	TX Stop Channel	Channel Numbering	Start Freq TX Extended Band	Stop Freq TX Extended Band	Channel Numbering Extended Band	Reverse Channel Numbering	Channel Spacing	Interleaving	Y1	Y3	Z	International Prefix	Country Code
Romania	1:3	453.000	457.475	1 - 180					25 kHz	No	5	3	4		

Table 3-1

## 5 Recommended Tools and Materials

All service to be carried out on an  
Anti-Static Workbench complete with the following:  
Conductive work surface and Wrist strap

2

5.1 **Level 2 Service** - The following hand tools will be required:

- 5.1.1 Small Torx™ screwdriver size T6 X 60
- 5.1.2 Torque Driver with T6 X 60 adapter – with torque range set to 0.32 Nm
- 5.1.3 Small Jeweller's screwdriver
- 5.1.4 Small tweezers

5.2 The following consumable materials will be required:

- 5.2.1 Anti-Stat foam cleaner – Ambersil or Servisol
- 5.2.2 IPA – RS 106-970
- 5.2.3 Anti-Static bags

3

5.3 **Level 3 Service** – The following additional hand tools will be required:

- 5.3.1 Small side cutters
- 5.3.2 Small fine pointed tweezers – RS 549-628
- 5.3.3 Soldering/desoldering station – SMD soldering and rework – Metcal SP200 SMT – 1160 Hako
- 5.3.4 Scalpel Swan Morton No 5 + Blades
- 5.3.5 Bench Light Magnifier

5.4 The following consumable materials will be required:

- 5.4.1 Solder wire – LMP Sn63 Pb 37 Ø 0.4mm. Or Multicore Smart wire RS 419-503
- 5.4.2 Solder Wick – Chemwick
- 5.4.3 Flux pen Alpha Metals NR205
- 5.4.4 Stiff cleaning brush
- 5.4.5 Soldering Iron tip cleaner – RS561-533

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## 6 Recommended Test Equipment

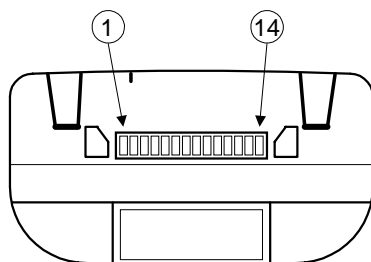
6.1 The following test equipment will be required:

Item	Description	Tellit P/n	Qty	Remarks
1	IBM Compatible PC with Pentium 100 or higher fitted with 32 MB RAM and CD ROM Drive and Mouse.		1	
2*	Cable Assembly 9W D Plug – 9W D Socket.	xxxxx	1	
3*	Cable Assembly 25W D Plug – 25W D Socket.	xxxxx	1	
4*	Mains Charger	xxxxx	1	
5	RF Communications Test Set		1	HP 8920B or similar
6*	Cable Assembly 50Ω SMA Plug - 50Ω A66 Antenna Connector	xxxxx	1	
7	Power Supply Unit 12V dc Hum & Noise <50 mV pp		1	
8*	Test Interface Box A66/A77	xxxxx	1	
9*	Cable Assembly 37W D Plug – 37W D socket	xxxxx	1	
10*	Test Fixture A66 Phone	xxxxx	1	
11*	Test Fixture A66 PCB	xxxxx	1	
12	Coaxial Adapter SMA Socket – N Plug		1	
13*	Coaxial Lead Assembly 50Ω BNC Plug - 50Ω BNC Plug	xxxxx	1	
14	Digital Multimeter		2	
15*	Test Lead 4mm Plug – 4mm Plug Red	xxxxx	3	
16*	Test Lead 4mm Plug – 4mm Plug Black	xxxxx	3	

6.2 Items marked with an asterisk are available from Tellit either individually, quoting the Tellit p/n given in the table above or as a complete kit quoting Tellit p/n xxxxx.

7 Circuit Operational Descriptions

I/O Specification for A66 terminal



PIN #	NAME	FUNCTION IN A66	LEVELS
1	CHG_IN	Positive charge voltage (INPUT)	+5.7V to + 6.2Volt Current limited to 800mA +/-10%
2	CHG_IN	Used in parallel with pin 1	
3	ID	External resistor value to GND. Indicates accessory connected.	Portable Handsfree = 10kohm +/-1% Service equipment=120k +/-1% (22,33,56,82k are future values)
4	TXD	Asynchronous data / MISO (OUTPUT)	HIGH= Min 2.2V @ 2mA LOW= Max 0.7V @ 2mA
5	SCK	**SPI buss clock (INPUT)	1.6V < HIGH < 3.3V -0.5V ≤ LOW ≤ 0.5V
6	RXD	Asynchronous data / MOSI (INPUT)	1.6V < HIGH < 3.3V -0.5V ≤ LOW ≤ 0.5V
7	* HOOK_C or RESET	Hook control Not for placing outgoing calls! Pull-up, 100k to +3V  Negative voltage puts phone into Reset mode. (INPUT)	1.6V < HIGH < 3.3V -0.5V ≤ LOW ≤ 0.5V Low > 60ms changes state  -2V to -4V
8	HOOK	Hook status indication (OUTPUT)	HIGH= Min 2.2V @ 2mA LOW = Max 0.7V @ 2mA Off hook = HIGH
9	+3VDIG	+3V (OUTPUT)	≥ 2.7 Volt @ Max 2mA
10	AF_OUT	Analog audio (OUTPUT)	1Khz @ +/-3kHz dev = 45mVRMS (EMF) Can drive >10k//<50pF
11	AGND	Analog ground	0 volt
12	AF_IN	Analog audio AC coupled (INPUT)	1kHz @ 250mVRMS = ± 3kHz dev Z <sub>in</sub> > 100k
13	GND	Used in parallel with pin 14	
14	GND	Charger ground	0 volt

Table 7-1

\* Only this function in headset mode.

\*\* Used for serial for programming only. // = In parallel with



Circuit Operational Description - Connections

7.1 System Connector

The connections to the System Connector J104 are defined in Table 7-1 above.

7.2 Level Translator/Decoder

Level Translator comprising transistors Q101, Q102 and Q103 provide level translation and decoding between the **HOOK\_C/RESET** signal derived from externally connected equipment, and the **HOOK\_C** and **RESET** internal lines. The level on **HOOK\_C/RESET** is decoded according the following truth table:

HOOK_C/RESET	HOOK_C	RESET
+3V	0	1
0V	1	1
-4.5V	1	0

The **HOOK\_C/RESET** line is pulled high resistors R116 and R117 to +3 V. Under both normal and test modes of operation the **HOOK\_C/RESET** line is ether allowed to be pulled up, by the pull up resistor, or pulled low to 0V by an external device. When the line is pulled to -4.5 V, by an external device, the **/RESET** line goes to logic level 0.

The **/RESET** line is input to the reset input to the microprocessor U301 pin 20. Thus a level of -4.5 V on **HOOK\_C/REST** causes the microprocessor to execute a reset cycle.

7.3 LCD Module

The LCD Module is connected via J102. Data lines **SCL** – Serial Clock, and **SDA** – Serial Data, provide a serial data interface from the microprocessor U301 to the LCD Module. The microprocessor writes to the display over these lines.

7.4 Battery Pack Interface

Interface to the Battery Pack is via connector J101. The connections to J101 are defined in figure 7-1.

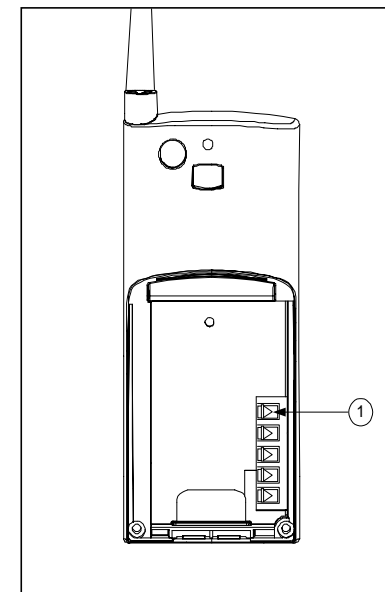
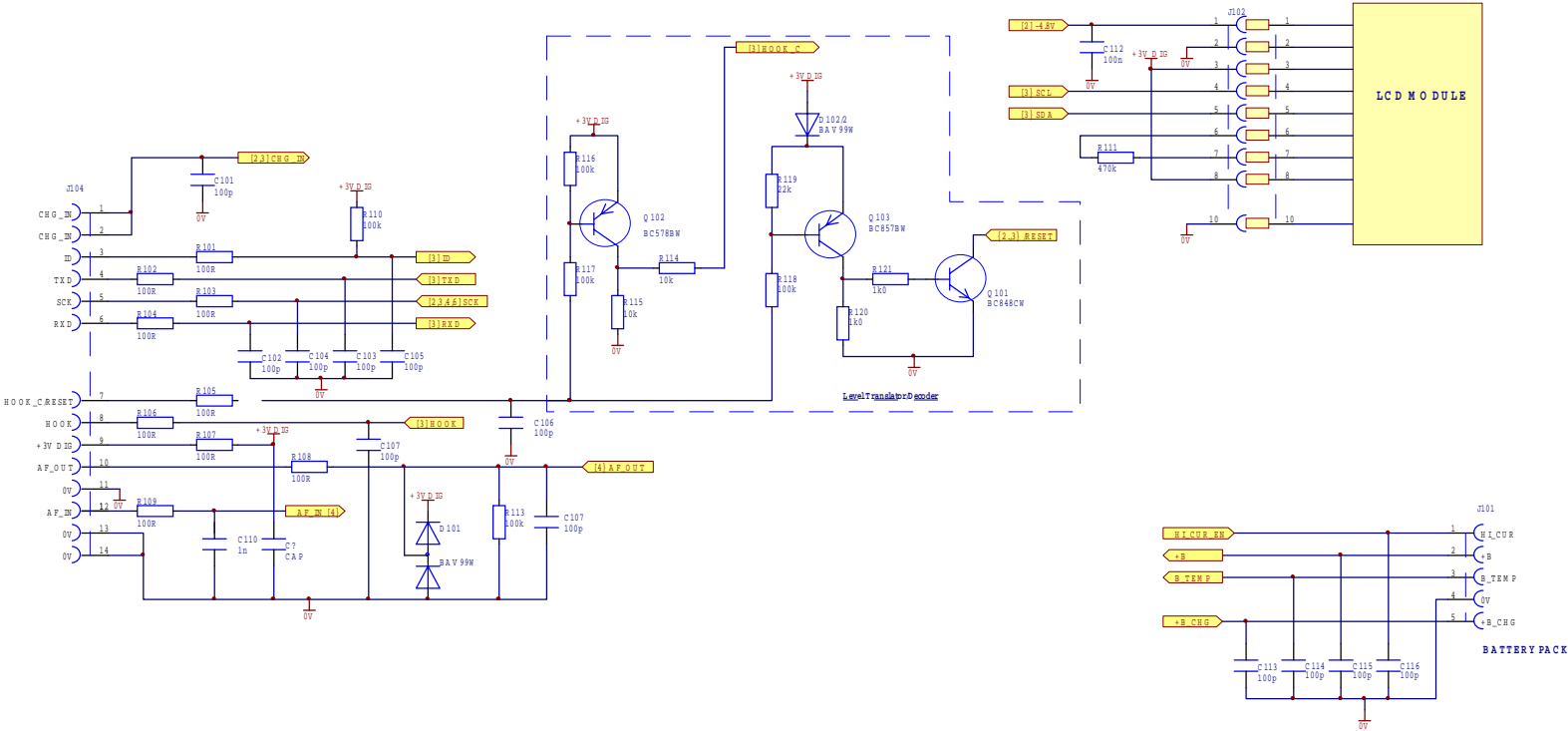


Figure 7-1



Circuit Diagram - A 66  
Connections

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## Circuit Operational Description - Power

### 7.5 Power On

The supply input to U201 is derived from the output of the Battery Pack via line **+B**. A voltage of at least 1.5 V is present on this line whenever a battery pack is connected to the phone or if the phone is connected to a charger. With the phone switched off the line **/+BATT\_ON** is pulled high via a pull up resistor within U210 connected to pin 48. Under the initial condition the **/RESET** line is held low.

The normal power on sequence is initiated when the user presses the **ON** key shown on the Processors circuit. Pressing the ON key causes transistor Q301 on the Processor circuit to turn on pulling the **/+BATT\_ON** line low. Simultaneously signal line **B\_TEMP** on the Processor circuit pulled high via diode D314. The signal **B\_TEMP** is routed to the Battery Pack via J101 pin 3 on the Connections circuit and causes the DC/DC Converter stage within the Battery Pack to start-up thus outputting a voltage of +3.3 V to the **+B** line. The **+B** line provides power supply to U201.

When U201 recognises that **/+BATT\_ON** is low it checks the output voltage of LDO Reg L. If the output voltage of regulator LDO Reg L is

above 2.93 V i.e. the regulator is producing an output voltage above the Under Voltage Lockout (UVLO) a time out period of 250 ms is started. At the end of this 250 ms period the **/RESET** line goes high which releases the reset condition from the microprocessor thus allowing normal program execution to proceed.

### 7.6 Power Off

U202 comprises an 8-bit serial input shift register with output storage. Data is shifted into the register under control of the microprocessor U201 using lines **LE\_595**, **DATA\_OUT** and **SCK**. As part of its power on routine the microprocessor writes logic 1 to the Q5 bit of the shift register. Thus Q5 output of Q202 is at logic level high. The **/OFF** signal (U201 pin 33) is derived from the Q5 output of U202.

When a power down sequence is initiated the microprocessor U201 clears bit Q5 of the shift register. The logic level at U201 pin 33 thus goes to 0. U201 goes into shut down and disables its regulators at the phone powers down.

### 7.7 Regulators

Regulator LDO Reg L located within U201 provides a supply of +3V used to power the digital circuits of the phone. The regulator output voltage is present when the voltage on line **+B** is above +3.1 V.

Regulator LDO Reg A located within U201 provides a supply of +3V used to power the analogue circuits of the phone. The regulator is enabled under control of the microprocessor U301 via the control line **/EN\_+3VA**.

–4.8 V DC/DC Converter  
–4.8 V DC/DC Converter comprising U203 operates from the +3VDIG supply line and generates a supply of –4.8 V which is fed to the LCB Module (part of Connections Circuit) via line –**4.8V**. The LCD Module requires –VE supply that is a function of the ambient temperature in order to ensure adequate display contrast over the required range of ambient temperatures. The converter circuit includes a thermistor R239 that causes the converter output voltage to vary as a function of the ambient temperature as required by the LCD Module. The –4.8 V DC/DC Converter is enabled by the microprocessor U301 via signal line via **–4.8V\_EN**.

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### 7.8 Buzzer Amplifier

The Buzzer Amplifier, part of U201, comprises an audio frequency amplifier having a single ended input and bridge connected output. Buzzer tones, derived from the microprocessor U301 via the BaseBand Processor are input to the stage on signal line RINGER\_IN. The output of the Buzzer Amplifier drives the Buzzer BU1.

### 7.9 Speaker Amplifier

The Speaker Amplifier, part of U201, comprises an audio frequency amplifier having a single ended input and bridge connected output. Received audio signals, derived from the BaseBand Circuit are input to the stage via signal line **SPEAKER\_IN**. The output of the Speaker Amplifier drives the Speaker.

### 7.10 8-Bit Serial Register

8-bit Serial Register comprising U202 converts serial data from the microprocessor, sent via data/control lines **LE\_595**, **DATA\_OUT** and **SCK**, to parallel form and latches the data at outputs Q0 –Q7. The functions of each bit is as follows:

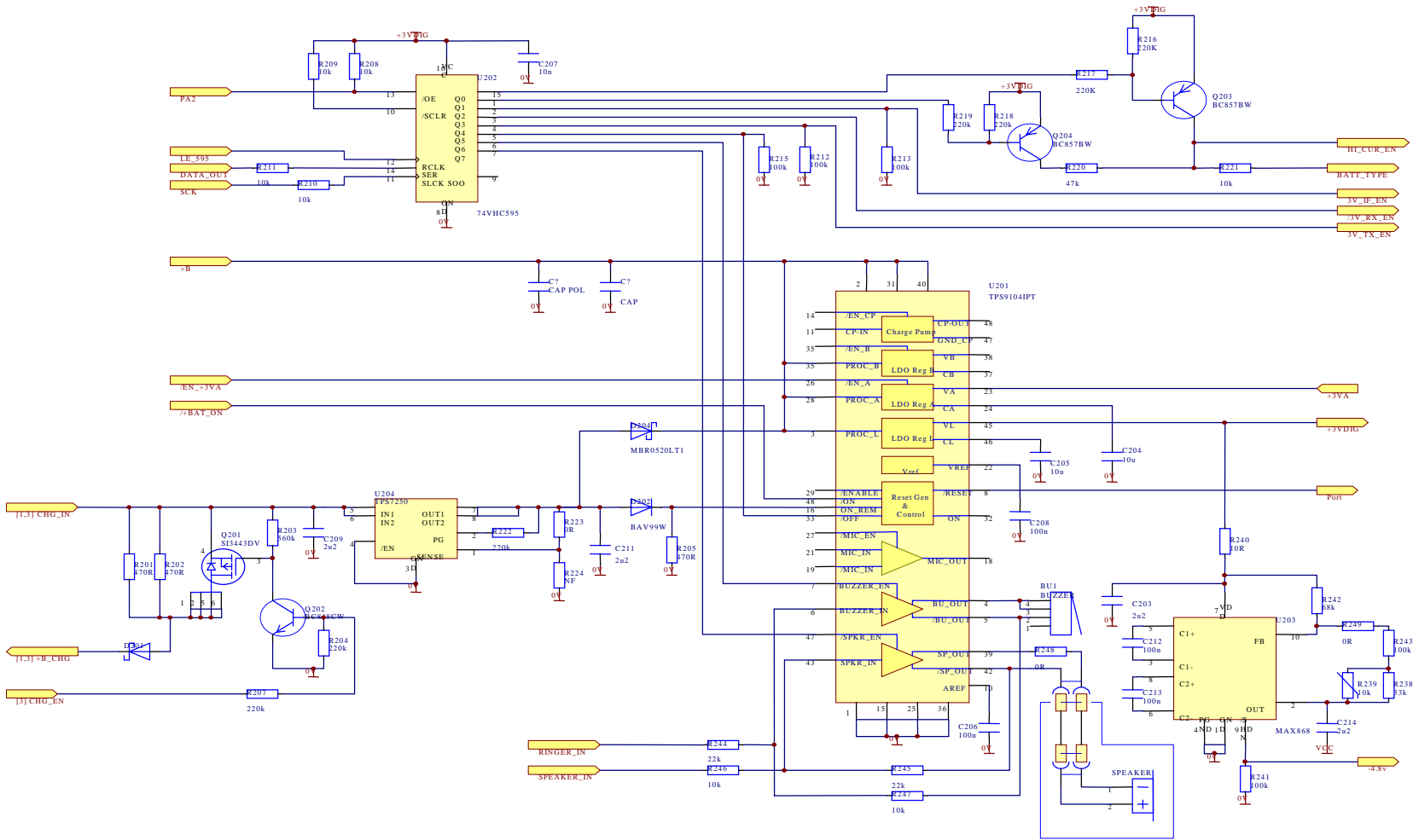
	Signal Name	Description
Q0	HI_CUR_EN	Enable the Battery Pack in high current mode.
Q1	BATT_TYP_E	Enables battery type to be read.
Q2	3V_IF_EN	Enables 3V supply to IF.
Q3	/3V_RX_EN	Enables 3V supply to RX
Q4	3V_TX_EN	Enables 3V supply to TX
Q5	/OFF	Power down
Q6	/BUZZER_EN	Enable the buzzer
Q7	/SPKR_EN	Enable the speaker

### 7.11 +5V Regulator

The 5V Regulator comprising U204 is required in order to facilitate the operation of the phone from a charger when either no battery pack is fitted or alternatively the alkaline battery pack is fitted by its cells are discharged. Under these conditions U204 provides a regulated of 5 V that is used to power the phone.

### 7.12 Charger Control

Charger Control circuit comprises transistors Q201 and Q202. Signal line CHG\_EN, derived from the microprocessor U301, turns Q201 on when fast charging is required. When fast charge is not signalled by the microprocessor by-pass resistors, R201 and R202, allow a current of the order of 25 mA to trickle into the battery pack.



**Circuit Diagram -  
Power**

Circuit Operational Description - Processor

7.13 Microprocessor

Microprocessor U301, with the exception of the calculation of SIS, provides all data processing required within the phone. Program storage is in internal Flash Memory facilitating field program upgrades. The Keyboard is serviced by the microprocessor under interrupts. Inputs INTO – INT3 being the interrupt inputs. When an interrupt is serviced the processor scans the PD0-PD3 lines in order to ascertain which key has been pressed. Output pins PA0 and PA1 drive a dual colour LED D303 providing status indicator with the following indications:  
 Green Continuous– Call in progress  
 Green Fast Flash – Incoming call  
 Green Slow Flash 3 Seconds – In service  
 Red/Green Flash - Roaming alarm  
 Red Flash – No service  
 Red Continuous – Battery low  
 Output pin PC7 drives transistor Q307, and Q308. Q307 controls the LEDs used to illuminate the Keyboard. Q308 drives the LEDs used to illuminate the LCD Display. PA0 and PA1 provide a 2-wire bi-directional interface to the External EEPROM U302. Via this interface data

is written to and read from the External EEPROM. The 2-wire serial interface is also used to write data to the LCD Module, part of Connections Circuit, via signal lines **SDA** and **SCL**. Output PA5 provides a signal to the Charger Control (part of Power Circuit) via signal line **CHG\_EN** used to enable fast charging of the battery pack. A logic level high on the line enables fast charging of the battery pack. Output PA6 provides a signal used to enable the –4.8 V DC/DC Converter (part of Power Circuit). A logic level high on the line enables the –4.8 V DC/DC Converter. Input PA7, via Q304, is used to detect that a charger is connected to the phone. When a charger is present signal line CHG\_IN, from System Connector J104 pins 1&2 will be at the charger output voltage. This voltage, via resistor R309, will cause transistor Q304 to turn on pulling input pin PA7 low. When no charger is present PA7 will be high. Input PF0 is used to input the state of the **HOOK\_C** signal derived from System Connector J104 pin 7 via Q102 on the Power Circuit. A logic level low signals off hook.

Input PF1 via signal line BATT\_TYPE operates as an analogue input to the microprocessor. When the processor executes the Get\_Battery\_Type routine transistor Q204 on the Power Circuit is briefly turned on connecting the top end of resistor R220 to +3V. Resistor R220 in conjunction with the Battery Identity Resistor, mounted in the battery pack, form a potential divider. Analogue input PF1 reads the voltage output of the potential divider and determines battery type according to the following table:

Battery Type	ID Resistor	Voltage
NiMH	15k	0.725 V
Alkaline	100k	2.04 V

Analogue input PF2 inputs the Received Signal Strength Indicator (RSSI) signal derived from the Receiver Circuit. Analogue input PF3 is used to input the phone's internal temperature. Temperature measuring circuit, comprising thermistor R380 and resistor R348, form a potential divider fed from the +3VDIG supply. Thus the nominal voltage input to PF3 is a function of internal temperature according to the following table:

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Temperature	Voltage
-10°C	2.452 V
0°C	2.215 V
+10°C	1.940 V
+20°C	1.646 V
+30°C	1.358 V
+40°C	1.094 V
+50°C	0.867 V
+60°C	0.680 V

Input PF4 – Not implemented.

Analogue input PF5 is used to monitor the temperature of the Battery Pack. Such measurement is required as part of the battery management's charge termination algorithm and also to ensure that fast charging is disallowed if the cell temperature is less than 0°C or greater than +45°C. The following table shows the typical relationship between cell temperature and the nominal voltage at PF5.

Cell Temp	Voltage at PF5
-10°C	2.563 V
0°C	2.342 V
+10°C	2.086 V
+20°C	1.822 V
+30°C	1.577 V
+40°C	1.366 V
+50°C	1.202 V

Analogue input PF6 is used to measure the battery pack cell voltage. When the

+3VDIG supply is present, i.e. phone powered on, transistor Q306 is turned on thus turning on transistor Q305. With Q305 on the voltage present on signal line **+B\_CHG**, which is the voltage directly across the cells, is divided by potential divider comprising resistors R313 and R317.

RXD data input to the microprocessor accepts serial data from the System Connector pin 2.

TXD data output from the microprocessor sends serial data to the System Connector pin 4.

PF7 analogue input reads the resistance between System Connector J104 pin 3 and 0V. Each type of accessory is provided with a distinctive value of ID resistor as shown in the table below. By this means the microprocessor determine which accessory is connected.

Accessory Type	ID Resistance
Charger	Open.
Portable Handsfree	10k

PE2 outputs signal /EN+3VA that is used to enable LDO Reg A on the Power Circuit.

PE3 inputs FFSK\_DET from the FFSK Demodulator on the BaseBand Circuit. FFSK\_DET indicates that FFSK data is being received.

PE4 inputs TX\_DATA\_CLK from the FFSK Modulator part of the BaseBand Circuit. Data is valid on the rising edge of TX\_DATA\_CLK.

PE5 inputs RX\_DATA\_CLK from the FFSK Demodulator part of the BaseBand Circuit. Data is valid in the rising edge of RX\_DATA\_CLK.

PE6 – Not used.

PE7 outputs hook status to the System Connector pin 8. Logic level high indicates off-hook.

PB0 output /CS\_AKM enables the BaseBand Processor chip U410 for control over the serial lines comprising DATA\_OUT, DATA\_IN and SCK. A logic level low on the line enables serial communication.

**PB1** outputs serial clock **SCK** to the BaseBand Processor chip U401 and the serial clock input of the SIM Processor. Data on **DATA\_IN** and **DATA\_OUT**, to /from the BaseBand Processor **is** valid on the rising edge of **SCK**. The connection to the serial clock input of the SIM Processor is used to clock data into and out of that device.

PB2 outputs serial control data to the BaseBand Processor chip U401 and serial data into the SIM Processor.

PB3 inputs serial data from the BaseBand Processor chip U401 and serial data from the SIM Processor.

PB4 outputs an enable signal to the SIM Processor. When enabled the SIM

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Processor can communicate with the microprocessor.

PB5 outputs SYNTH\_LOAD to the Synthesiser. When SYNTH\_LOAD goes high data sent to the synthesiser's registers is latched into registers.

PB6 outputs LE\_595 provides a latch enable signal to 8-bit Shift Register U202 on the Power Circuit. On the rising edge of LE\_585 data in the shift register is transferred to the devices output latches.

PB7 outputs the buzzer signal via signal line BUZZER.

PD4 outputs TX\_DATA to the FFSK Modulator part of the BaseBand Processor.

PD5 outputs TX\_DATA\_EN to enable the FFSK Modulator part of the BaseBand Processor for the transmission of FFSK data.

PD6 inputs **RX\_DATA** from the FFSK Demodulator part of the BaseBand Processor.

PD7 – Not used.

Quartz crystal X301, operating at a frequency of 4.8 MHz, provides the main clock for the microprocessor. Signal line **4.8MHz** provides clock signal to the BaseBand Processor. Ceramic resonator X302 operating at a frequency of 32.788 kHz provides a clock for the microprocessor used when in sleep mode i.e. when the phone is in power down. Operating at the lower clock rate significantly reduces the power consumption when in sleep mode.

### 7.14 SIM Processor

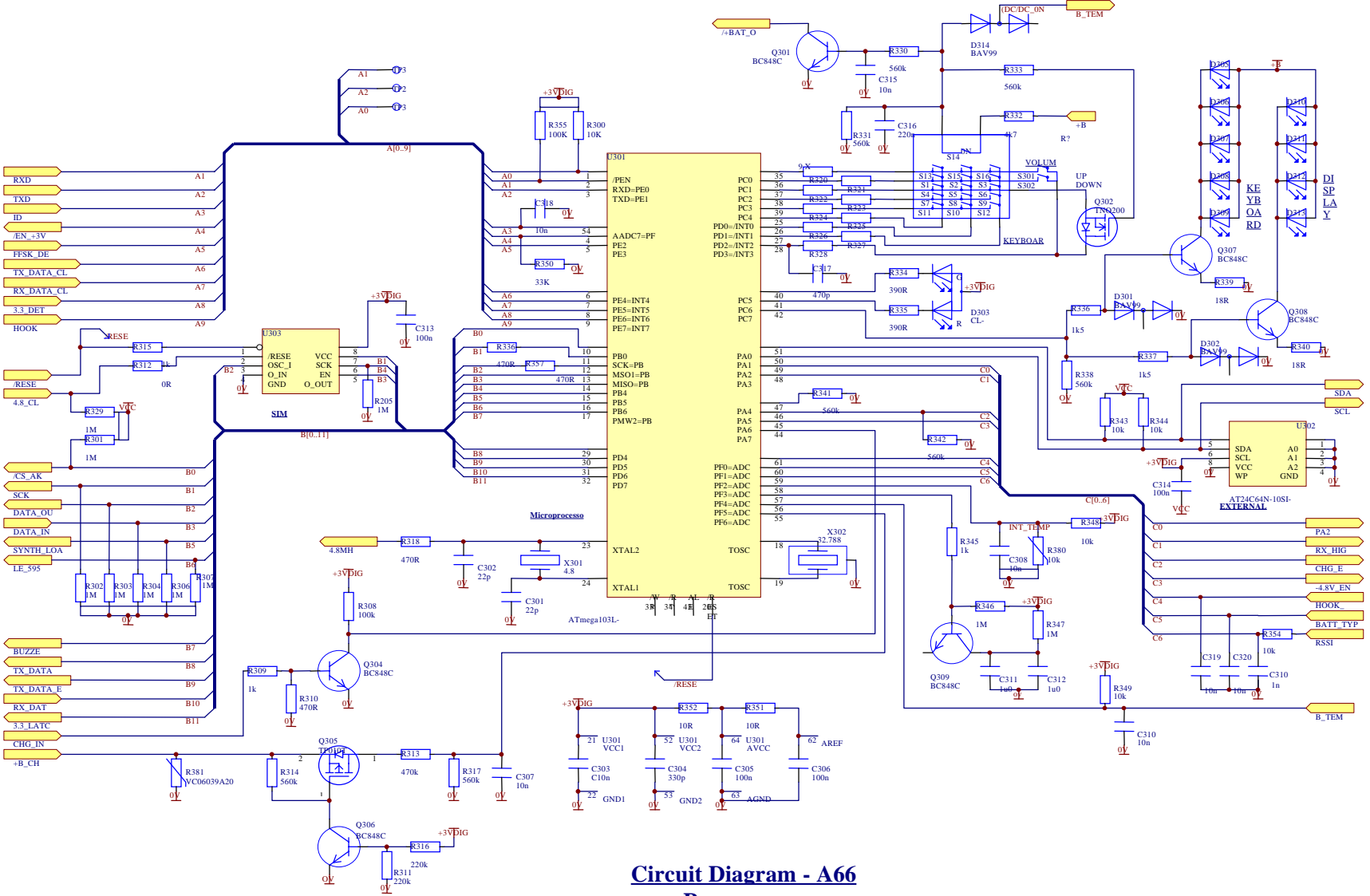
The SIM Processor U303 comprises an 8-bit microprocessor. Tellit programs the device with a secret authentication code (SAK). During authentication the MS receives a number RAND (Random Challenge) from the MTX. From RAND the SIM Processor calculates 2 numbers, SRES and B-Key. SRES (Signed Response) is sent to the MTX to confirm the mobile station's identity

and B-key is used to encrypt the B-subscriber's number. When the SAK is programmed into the device a separate and unrelated SIM module serial number, the SIS number, is also generated. This SIS number appears on the equipment label affixed to the rear of the phone. **In the event of failure of the SIM Processor a replacement device, programmed by Tellit, must be obtained.** The replacement SIM Processor will be shipped with a replacement equipment label bearing a new SIS number. **When the phone is commissioned it is important that the old SIS number be de-registered and the new SIS number registered with the system operator.**

### 7.15 External EEPROM

The External EEPROM provides non-volatile memory for such as the Phone Book and other customer configurations.





**Circuit Diagram - A66**  
**Processor**

Circuit Operational Description - BaseBand

7.16 Receive Audio

Receive audio, derived from the Demodulator is input via signal line **RX\_AUDIO** into AMP2 (part of U401). Resistors R407 and R408 set the mid-band gain of the stage. The output of the stage is input the anti-aliasing filter AAF2.

The anti-aliasing filter AAF2 removes components of the receive audio at frequencies higher than twice the high frequency cut-off point of the band pass filters (above 7.8 kHz). The output of AAF2 is input to Digital Gain Control VR5.

VR5 provides a variable gain stage, controlled by the microprocessor (U301) over the serial control bus comprising **DATA\_OUT**, **SCK**, **DATA\_IN** and **/CS\_AKM**. The gain of the stage may be adjusted in steps of 0.4 dB over the range -6.0 dB to +6.4 dB. The output of **VR5** is input to de-emphasis circuit **D/E**.

The de-emphasis circuit D/E provides a -6-dB/octave-frequency response over the frequency range of 300 Hz to 3.4 kHz. The output of D/E is input to switch **RXAUDION**. Switch **RXAUDION** is controlled by the microprocessor (U301) via the serial control bus, Thus the Thus the

microprocessor may mute the received audio when not required. The output of the RXAUDION is output to U401 pin 18 and thence to C414.

C424 couples the receive audio into U401 pin 9 (EXPIN). This pin provides input to the expander stage **EXP**. The expander provides amplitude expansion of the receive audio signal such for a 1 dB change in level at the expander input there is a 2 dB change in level at the expander output. The expander may be by-passed by means of switch **EXPON** under control of the microprocessor (U301) via the serial control bus. The output of EXPON is input to digital gain control stage VR6.

**VR6** provides a variable gain stage controlled by the microprocessor (U301) over the serial control bus. The gain of the stage may be adjusted in steps of 0.5 dB over the range -1.5 dB to +2.0 dB. The output of VR6 is input to switch **RXMUTE**.

Switch **AUDILOOPON** – **DTMFRXON** – **RXMUTE** – **EXTRON** in conjunction with the summing junction ADD4 allows the microprocessor to control the summation of other audio signals with the receive audio. These addition signals are:

**AUDILOOPON** – allows the TX audio from the microphone circuit to be routed to the speaker and **AF\_OUT** line.

**DTMFRXON** – allows DTMF tones from the **DTMF GEN** to be routed to the speaker and **AF\_OUT** line.

**RXAUION** – allows the receive audio to be routed to the speaker and **AF\_OUT** line.

**EXTRON** – allows the **BUZZER** signal, generated by microprocessor (U301) to be routed to the **RINGER\_IN** line.

The output of ADD4 is input to Digital Gain Control **VR10**.

VR10 provides a variable gain stage controlled by the microprocessor (U301) over the serial control bus. The gain of the stage may be adjusted in steps of 3 dB over the range -30 dB to +30 dB. The stage provides the user's receive volume control. The output of VR10 is input to amplifier **AMP4**.

**AMP4** provides a unity gain buffer to drive signal line **SPEAKER\_IN** and U401 pin 19 (**RECIN**). The output of **RECAMP** drives signal line **AF\_OUT** that is route to pin 10 of System Connector J104.

## 7.16 Transmit Audio

An electret microphone is used. DC bias required to power the microphone is derived from the **+3VA** line via R401. C401 provides decoupling of the bias voltage so as to remove noise present on the +3VA supply. Resistor R402 provides the load across which the microphone output voltage is developed. This output voltage is coupled into the **AMP1** (part of U401). Resistors R405 and R404 define the voltage gain of AMP1. The output of **AMP1** is input to switch **MICON**. Switch MICON is controlled by the microprocessor U301 via the serial control bus. The output of MICON is input to **ADD1/VR1**. VR1/ADD1 sums the input signals, as selected by switch MICON – EXTINON – DTMFTXON and provides a gain controlled stage controlled from the microprocessor U301 via the serial control bus. The gain of the stage is adjustable over the range – 3.5 dB to +4.0 dB in steps of 0.5 dB. The output of VR1 is routed to U401 pin 59. A bandpass filter within VR1 defines the TX audio speech bandwidth of 300 Hz to 3.4 kHz. U401 pin 59 is connected to the input pin of **AMP6**, which provides a unity gain amplifier. Resistors R411 and R414 define the voltage gain of the

stage. The output of **AMP6** is coupled into U401 pin 58 via capacitor C410. The signal input at U401 pin 58 is routed to the input of digital gain control **ATT1**. The stage gain of **ATT1** is controlled by the microprocessor U301 via the serial control bus. The gain of the stage may be adjusted over the range –22.0 dB to 0.0 dB in steps of 0.5 dB. The output of **ATT1** is input to the compressor stage **COMP**. The compressor provides amplitude compression of the transmit audio signal such for a 2 dB change in level at the compressor input there is a 1 dB change in level at the compressor output. The compressor may be bypassed by switch **COMPON** under control of the microprocessor U301 via the serial control bus. The output of COMPON is connected to VR2. **VR2** provides a variable gain stage controlled by the microprocessor (U301) over the serial control bus. The gain of the stage may be adjusted in steps of 0.3 dB over the range –2.1 dB to +2.4 dB. The output of VR2 is input to pre-emphasis and limiter stage **P/E & Limit**. The **P/E & Limit** stage provides a +6 dB/octave pre-emphasis over the frequency range 300 Hz to 3.4 kHz and includes an amplitude limiter which prevents over deviation of the transmitted carrier. Such deviation limiting is required in order to confine

the bandwidth of the transmitted signal to the allocated channel and prevent side bands from spreading into the adjacent channel. The output of the **P/E & Limiter** is input to the **LPF**. The output of the limiter can contain high order harmonics of the transmit audio signal. If not removed these high order harmonics would cause the bandwidth of the transmitted signal to be excessive. The Low Pass Filter **LPF**, having a high frequency cut-off at 3.4 kHz removes the high order harmonics. The output of the LPF is input to the Digital Gain Control Stage VR3. **VR3** provides a variable gain stage controlled by the microprocessor (U301) over the serial control bus. The gain of the stage may be adjusted in steps of 0.3 dB over the range –5.9 dB to +4.8 dB. The output of **VR3** is input to switch **TXAUDON**. Switch **TXAUDON** is controlled by the microprocessor U301 via the serial control bus. The output of **TXAUDON** is input to **ADD3** Summing Circuit. **ADD3** sums the transmit audio, the FFSK transmit data stream and the Ø signal as selected by the switch. The output of **ADD3** is input to **VR4**. **VR4** provides a variable gain stage controlled by the microprocessor (U301) over the serial control bus. The gain of the stage may be adjusted in steps of 0.3 dB over the range –4.5 dB

to +4.8 dB. The output of VR4 is input to SMF1. Smoothing Filter AMF1 suppresses components of the sampling frequency used within the digital filters of the Base Circuit. These frequency components, if not suppressed, would cause adjacent channel interference to be transmitted.

7.18 EXTIN

Transmit audio signal, derived from the System Connector J104 pin 12, via signal line **AF\_IN** is input to U401 pin 63. If the microprocessor (U301) has selected switch **EXTINON**, via the serial control bus, the audio on the **AF\_IN** line used to modulate the transmitter. When the microprocessor selects switch **EXTINON** switch **MICON** will be deselected.

7.19 Ø-Loop

During call the quality of the connection is monitored by means of the Ø-Signal originated at the Base Station. The tone is at a frequency of 3055, 3985, 4015 or 4045 Hz. The Ø-Signal is received at the MS and is input to the Base Band Circuit together with received audio on signal line **RX-AUDIO**. The received signal, consisting of both audio and Ø-signal, present at the

output of VR5 is routed to the input of **SAT BPF**. **SAT BPF** comprises a band-pass filter having a centre frequency of 4.0 kHz and a pass band of  $\pm 55$  Hz. The **SAT BPF** removes the audio signal leaving just the Ø-signal. The filtered Ø-signal is input to **VR7**. **VR7** provides a variable gain stage controlled by the microprocessor (U301) over the serial control bus. The gain of the stage may be adjusted in steps of 0.3 dB over the range -4.5 dB to +4.8 dB. The gain setting of the stage controls the deviation of the Ø-signal transmitted by the MS. The output of VR7 is input to switch **FILOOPON**.

If switch **FILOOPON** is selected the Ø-signal is summed with the transmit audio.

7.20 FFSK Demodulation

During certain times signalling and control messages are sent from the BS to the MS. These data messages are transmitted Fast Frequency Shift Keyed (FFSK) with a frequency of 1200 Hz used to denote logic level 0 and 1800 Hz used to denote logic level 1. The data is transmitted at a bit rate of 1200 bits/sec.

The received signal, consisting containing the FFSK data is input to the BaseBand Circuit via signal line **RX\_AUDIO**. At the output of de-

emphasis circuit **D/E** the received signal is input the FFSK Demodulator **FFSK DEMOD**. **The FFSK DEMOD** recovers the serial data together with a clock signal from the incoming FFSK stream. These signals are input to the microprocessor U310 via signal lines **RX\_DATA** and **RX\_DATA\_CLK** respectively.

When a FFSK signal is detected U401 pin 43 **FFSKDET** goes high signifying valid FFSK data. This signal is passed to the microprocessor via signal line **FFSK\_DET**.

7.21 FFSK Modulation

Signalling and control messages are sent from the MS to the BS. 1200 bit/sec Fast Frequency Shift Keying (FFSK) is used in order to transmit these messages.

Signal lines **TX\_DATA\_EN**, **TX\_DATA** and **TX\_DATA\_CLK** are used to transfer data from the microprocessor to the FFSK Modulator contained within U401. In order to initiate data transfer the microprocessor sets the path from the FFSK Modulator to **TX\_MOD** by opening the switch **TXAUDON**, to remove speech signals, and then setting the switch **FFSKON**. The processor then sets data line **TX\_DAT\_EN** high and sends the first data bit. U401 then starts the clock signal **TX\_DATA\_CLK** that is used by

the microprocessor to control the serial transfer of data to the FFSK Modulator. On the negative edge of **TX\_DATA\_CLK** the microprocessor places the next bit onto **TX\_DATA** line. On the positive edge of **TX\_DATA\_CLK** the data bit is read into the FFSK Modulator.

7.22 DTMF Encode

The BaseBand circuit U401 contains a Dual Tone Multi Frequency DTMF encoder – **DTMF GEN**. Data written to a register within U401 by the microprocessor U301 via serial bus comprising **/CS\_AKM – DATA\_OUT – SCK – DATA-IN** controls the sending of DTMF tones. Before sending DTMF tones the microprocessor U301 signals the BaseBand Circuit U401 to open switch **MICON**, thus removing the speech signal, sets switch **DTMFTXON** on, and then starts DTMF transmission. Once DTMF transmission is complete the microprocessor sets switch **MICON** on and sets switch **DTMFTXON** off. Whilst DTMF transmissions are in progress the microprocessor sets switch **DTMFRXON** allowing DTMF tones to be routed to U401 pin 14

(EXTOUT) and thence to the speaker and the signal line AF\_OUT.

7.23 Digital to Analogue Converters

Contained within the BaseBand Circuit U401 are 3 digital to analogue converters **D/A**. The each D/A outputs a dc analogue output level under control of the microprocessor U301 via the serial control bus. These analogue outputs are as follows;  
**POWER\_CTRL** – Used to control the attenuation of U501 on the transmitter circuit.  
**VTCXO** – Used to the tuning of the Voltage Tuned Crystal Oscillator Y601 on the Synthesiser circuit.  
**PA\_BIAS** – Used to control the gain of U502 and the dc bias current in Q501, both part of the transmitter circuit.

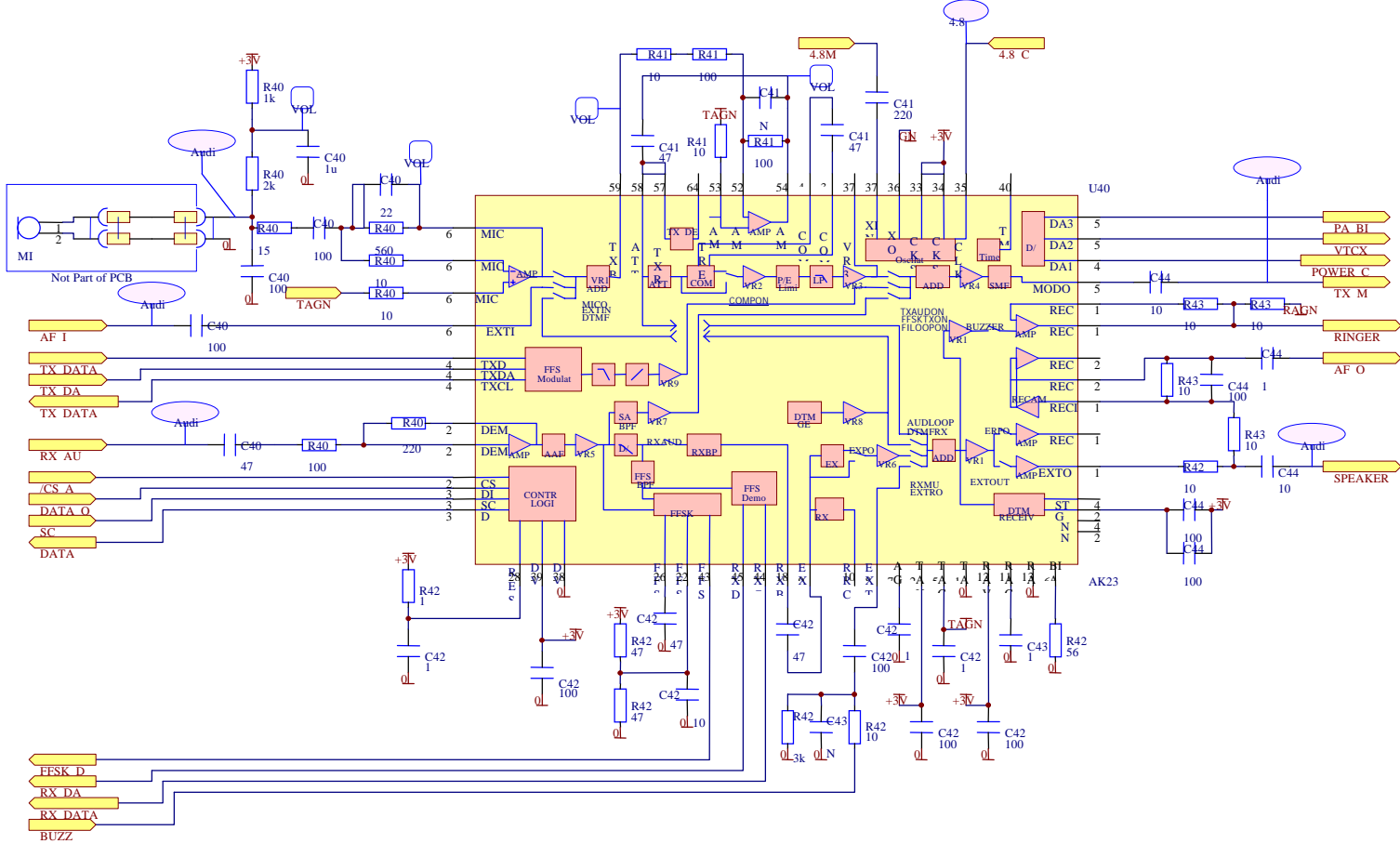
7.24 Oscillator

The **Oscillator** provides various clock signals required within the device. The device is designed to facilitate operation by means of a directly connected quartz crystal of frequency either 14.4 MHz or 4.8 MHz or from and external clock source at a frequency of either 14.4 MHz or 4.8

MHz. The logic level present at pins 36, 33 and 34 configure the device to operate from an external clock source at a frequency of 4.8 MHz. The 4.8 MHz clock source is derived from the Processor circuit via signal line **4.8MHz**.

7.25 Control Logic

Contained within the BaseBand Processor are a number of registers. These registers are used to control the configuration of the BaseBand Processor and provide temporary storage for data to be read out of and written into the device. The microprocessor U301 communicates with the BaseBand Processor over a serial bus comprising the following data lines:  
**/CS\_AKM** – When low selects the chip to allow serial transfers to and from the Control Logic.  
**DATA\_OUT** – Serial data from the microprocessor U301 to the BaseBand Processor.  
**SCK** – Serial clock from the microprocessor.  
**DATA\_IN** – Data from the BaseBand Processor to the microprocessor.



**Circuit Diagram - A66**  
**Base-Band Processor**

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## Circuit Operational Description - Receiver

### 7.26 LNA

Q701 operates as a low noise common emitter RF Amplifier. Receive signals, within the allocated NMT450 downlink band, are input to the receiver from the Duplexer part of the transmitter via signal connection **RX\_INPUT**.

Power supply to the LNA is derived from the 3VRX line under control of the microprocessor U301. The LNA may be operated at 1 of 2 possible bias points. When **RX\_HIGH** is low (approximately 0V) the dc bias point is determined by R703 and R704. These components are designed to set the bias current in Q710 to a low level. When **RX\_HIGH** is high an additional path, via R701, D700 and R702, for the flow of base bias current to Q710 is provided. This causes the dc bias current in Q701 to be set to its high level.

The output from Q701 is coupled via impedance matching capacitor C706 to the RF Attenuator.

### 7.27 RF Attenuator

RF Attenuator comprising resistors R710, R711 and R712 provides a small degree of attenuation of the RX signal, so as to both improve the intermodulation performance of the receiver and provide an impedance match into the RX BPF.

### 7.28 RF Band Pass Filter

The RF BPF passes the required downlink frequencies and rejects out-of-band signals. The insertion loss of the filter is a maximum of 3 dB over its pass-band.

### 7.29 1st Mixer

The output impedance of the RX BPF is matched into the gate 2 of the 1<sup>st</sup> Mixer (Q702) by means of dual L section impedance matching network comprising L710, C720 and L723, C729. The local oscillator injection signal is derived from the RX Synthesiser via signal line **RX\_VCO**.

The dc bias point of Q702 is determined by R732.

The drain circuit of Q702 is impedance matched into the 1st IF Filter by means of matching network comprising C733, C732, C734, L712 and C735.

### 7.30 1st IF Filter

Quartz filter, Y704, having a centre frequency of 45 MHz and a 3 dB bandwidth of 15 kHz defines the channel bandwidth of the receiver 1st IF. The insertion loss of the filter is a maximum of 3 dB over the pass-band. The terminal impedance of the 1st IF Filter is matched to the input impedance of the 1<sup>st</sup> IF Amplifier by means of impedance matching network comprising L713, C737, L721 and C748.

### 7.31 1st IF Amplifier

Cascade connected bipolar transistors Q703 and Q704 provide approximately 20 dB of voltage gain at the 1st IF frequency. Impedance matching network comprising C747 and L720 provides

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matching into the 2nd Mixer stage Input, U701 Pin 32, via C740.

### 7.32 2nd LO X3 Freq Multiplier

The output frequency, 14.85 MHz, of the VCTCXO, connected by signal line **OSC**, is frequency multiplied by Q705. The collector circuit of Q705, comprising a parallel resonant circuit, is tuned to 44.55 MHz. Thus the 3rd harmonic of the VCTCXO frequency is generated.

### 7.33 RX IF Demodulator

The output of the 1st IF Amplifier is coupled into the 2nd Mixer via C754. The 2nd Local Oscillator injection

frequency of 44.55 MHz is coupled into U701 by means of C754.

The components of the output spectrum of the 2nd Mixer (U701 pin 1) occurring at the 2nd IF frequency of 450 kHz are selected by BPF Y702 which has a centre frequency of 450 kHz.

The output of Y702 feeds the input to the 2nd IF Amplifier contained within U701 via U701 pin 4. The output 2nd IF Amplifier feeds the input of BPF Y703, also having a centre frequency of 450 kHz, providing further selectivity at the 2nd IF frequency. The output of Y703 is feed to the input of the 2<sup>nd</sup> IF Limiter Stage contained within U701. The limiter stage limits the amplitude of the received signal presented to the Demodulator thus providing

suppression of amplitude modulated signals FM signal /noise improvement.

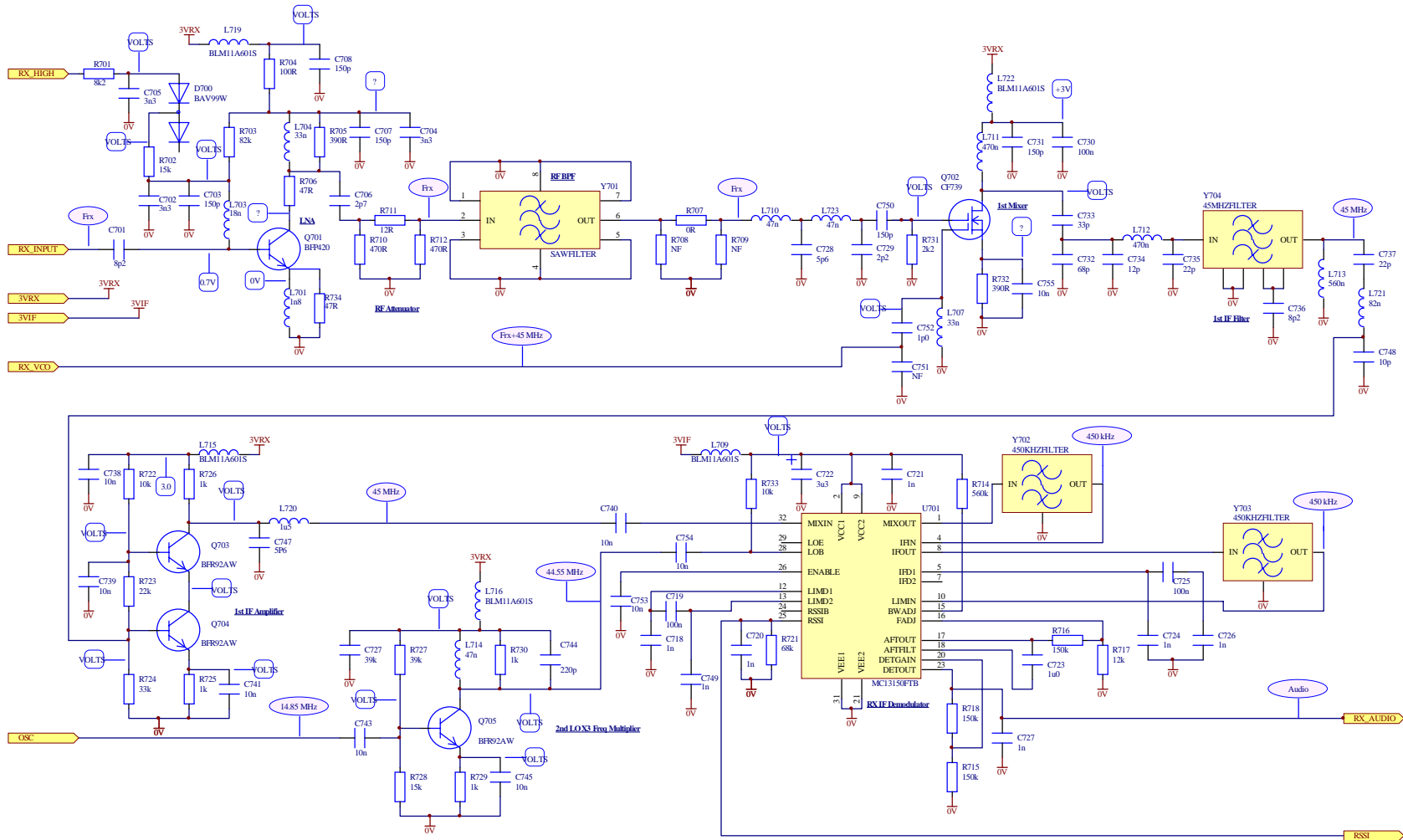
The output of the Limiter is coupled into the Demodulator.

The Demodulator converts the incoming modulated carrier to audio baseband. The audio signal is output to the BaseBand Processor via signal line **RX\_AUDIO**.

### 7.34 RSSI

U701 provides a Receive Signal Strength Indicator RSSI (U701 pin 25). The dc signal level on the RSSI line is approximately proportional to the logarithm of the received signal level. The RSSI signal is input to the microprocessor via signal line **RSSI**.





Circuit Diagram - A 66 Receiver

# COMPANY CONFIDENTIAL

## Circuit Operational Description - Synthesiser

### 7.35 Reference Oscillator

Y601 Voltage Controlled Temperature Compensated Crystal Oscillator (VCTCXO) provides the reference frequency used to determine both the TX and the RX frequencies. The oscillator produces a highly accurate output frequency of 14.85 MHz. The output frequency of the reference oscillator can be adjusted, over a frequency range of  $\pm 7$  ppm (parts per million) i.e.  $\pm 104$  Hz. by the voltage present on signal line **VCTCXO**. The voltage level on signal line **VCTCXO** is derived from the output of **D/A DA20** located on the BaseBand Circuit. During the calibration of the phone the voltage present on signal line **VCTCXO** is adjusted so as to reduce the error of the TX carrier frequency to less than  $\pm 5$  Hz. The calibration value corresponding to this error is written to the phone's EEPROM memory. When the phone is in operation the microprocessor writes the calibration value to **D/A DA20**, which outputs the correct voltage level on signal line **VCTCXO** so as to tune out the frequency error of the Reference Oscillator. The output of the Reference Oscillator is input to the reference input of the

Dual PLL Synthesiser U601 at pin 6. The output of the Reference Oscillator is also fed 2nd LO X3 Frequency Multiplier stage, located on the Receiver Circuit, where it is used to derive the injection frequency for the Receiver 2nd Mixer.

### 7.36 TX Synthesiser

The TX Synthesiser comprises a feedback system. The output of the **TX VCO** Y602 is fed back into the input of **Dual PLL Synthesiser** chip U601 at pin 5. Within U601 the TX VCO frequency is divided down by the preset ratio of the two stage RF divider chain comprising a dual modulus prescaler (P) and a divide by N counter (N). The P and N counters are programmable from the microprocessor over the serial control lines **SCK**, **DAT\_OUT** and **SYNTH\_LOAD**. Thus the microprocessor can set the division ration of the RF divider chain. The 14.85 MHz reference frequency, derived from Y601, is input to U601 pin 6 (OSCIN). Within U601 OSCIN feeds the input to a programmable divider (R) which divides the reference frequency. The R counter is programmed by the microprocessor

over the serial control lines **SCK**, **DAT\_OUT** and **SYNTH\_LOAD**. Thus the microprocessor can set the division ration of the Reference Frequency divider chain.

The output of N and the output of P are input to the two inputs of a phase detector contained within U601. The phase detector produces an output current presented at U601 pin 3 (DO1) which represents the phase error between the TX VCO frequency, and the Reference Frequency.

The output of the phase detector is input to the TX VCO Y602 control pin (CTRV) via the **TX Loop Filter** comprising C607, C608 C617, R604, R605 and C610. The Loop filter converts the output current of the synthesiser to a voltage that is input to the TX CO.

The TX VCO produces an output frequency that is a function of the control voltage present at CTRV. The polarity of the control voltage produced by the phase detector is such as to adjust the VCO to reduce the phase error between the two inputs to the phase detector to zero. When this occurs the Phase Lock Loop attains phase lock and the percentage frequency accuracy of the TX is equal

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to the percentage frequency accuracy of the reference frequency.

The output of **TX VCO** present at Y602 OUT is attenuated by resistors R607, R608 and R609 and drives the transmitter via signal line **TX\_VCO**.

### 7.37 Transmitter Modulation

The **TX VCO** Y602 provides modulation input, **MOD**. Transmit audio, derived from the BaseBand Processor, is input via signal line **TX\_MOD**. Audio signals present on **MOD** frequency modulate the **TX VCO** frequency thus producing frequency modulation of the transmitted carrier.

### 7.38 RX Synthesiser

The RX Synthesiser comprises a feedback system similar but separate to the TX Synthesiser. The output of the **RX VCO** Y603 is fed back into the input of **Dual PLL Synthesiser** chip U601 at pin 12. Within U601 the **RX VCO** frequency is divided down by the preset ratio of the two stage RF divider chain comprising a dual modulus prescaler (P) and a divide by N counter (N). The P and N counters are programmable from the microprocessor over the serial control lines **SCK**, **DAT\_OUT** and **SYNTH\_LOAD**. Thus the microprocessor can set the division ration of the RF divider chain.

The 14.85 MHz reference frequency, derived from Y601, is input to U601 pin 6 (**OSCIN**). Within U601 **OSCIN** feeds the input to a programmable divider (R) which divides the reference frequency. The R counter is programmed by the microprocessor over the serial control lines **SCK**, **DAT\_OUT** and **SYNTH\_LOAD**. Thus the microprocessor can set the division ratio of the Reference Frequency divider chain.

The output of N and the output of P are input to the two inputs of a phase detector contained within U601. The phase detector produces an output current presented at U601 pin 14 (**DO2**) which represents the phase error between the RX VCO frequency, and the Reference Frequency.

The output of the phase detector is input to the **RX VCO** Y603 control pin (**CTRV**) via the **RX Loop Filter** comprising C612, C613, R611, R612, and C615. The Loop filter converts the output current of the synthesiser to a voltage that is input to the TX CO.

The **RX VCO** produces an output frequency that is a function of the control voltage present at **CTRV**. The polarity of the control voltage produced by the phase detector is such as to reduce the phase error between the two inputs to the phase detector to zero. When this occurs the Phase Lock Loop achieves phase lock and the percentage frequency accuracy of the TX is equal to the percentage

frequency accuracy of the reference frequency.

The output of **RX VCO** present at Y603 OUT is attenuated by resistors R614, R615 and R616 and drives the local oscillator injection into the Receiver 1st Mixer via signal line **RX\_VCO**.

### 7.39 VTX Regulator

**VTX** Regulator comprising U602 provides a regulated supply of +3 V to power the low-level stages of the transmitter and the **TXVCO**. A supply of nominal voltage +3.3 V is input via line +B from the Power Circuit. The regulator is enabled by signal line **3V\_TX\_EN** derived from the microprocessor U301.

### 7.40 3VIF Regulator

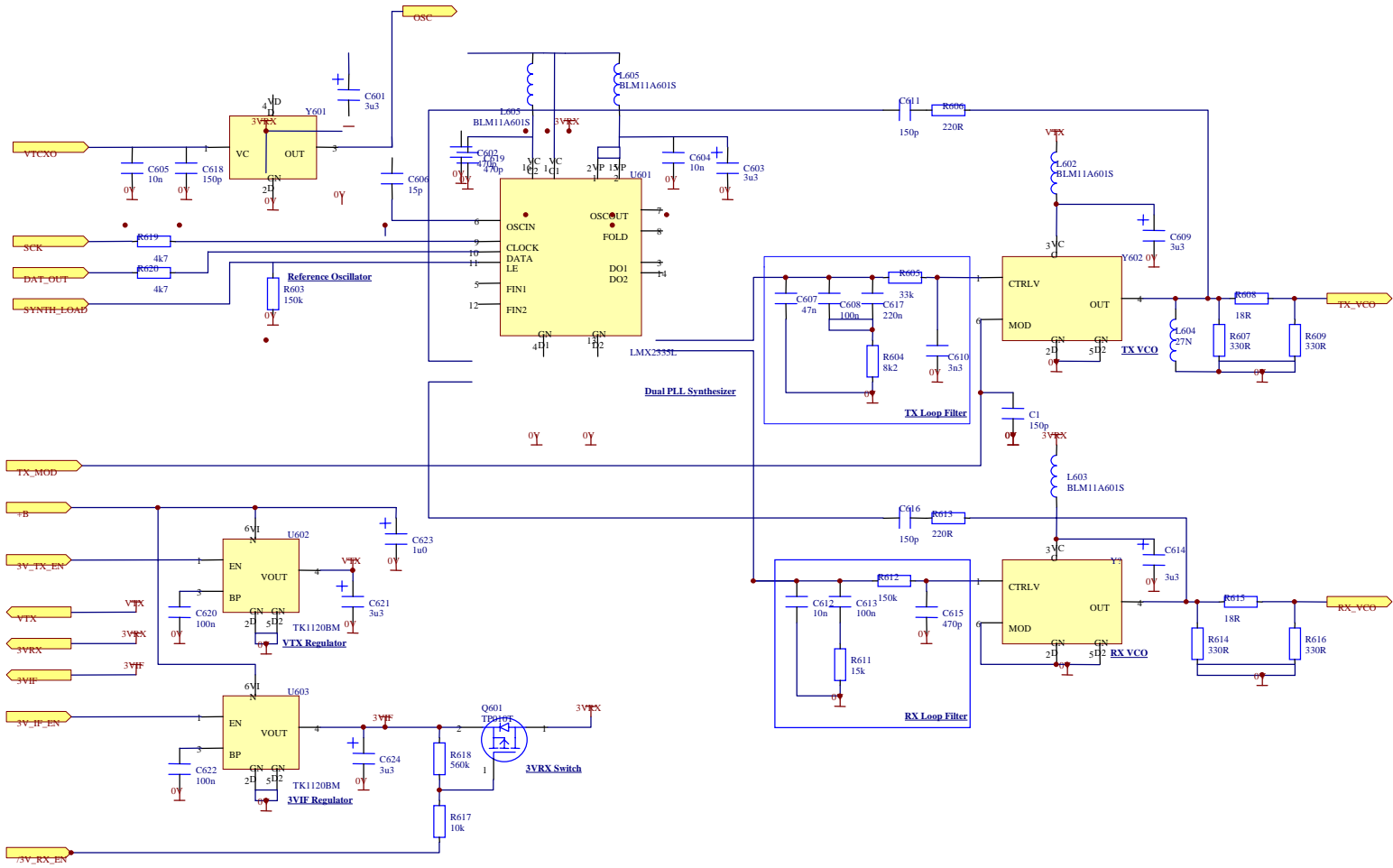
**3VIF** regulator comprising U603 provides a regulated supply of +3 V to power the IF stages of the receiver. Its input supply is derived from the +B line from the Power Circuit. The regulator is enabled by signal line **3V\_IF\_EN** derived from the microprocessor U301.

### 7.41 3VRX Switch

**3VRX** Switch comprising transistor Q601 switches the +3V output of the **3VIF** regulator to the **LNA**, **1st Mixer**, **2nd IF Amplifier**, **2nd LO X3Freq Multiplier** stages of the receiver and

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the **RXVCO** via the **3VRX** line. The switch is control by the microprocessor U301 via control line **/3V\_RX\_EN**.



Circuit Diagram - Synthesiser

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## Circuit Operational Description - Transmitter

### 7.42 Attenuator

The attenuator stage U501 provides electronically adjustable attenuation under the control of the microprocessor via analogue signal line **POWER\_CTRL**. The **TX** carrier frequency, generated by the TX Synthesiser is input to this stage, via signal line **TX\_VCO**, at an approximate level of - 6 dBm. The minimum attenuation of the stage is 2.7 dB for a **POWER\_CTRL** voltage of +3 V. The output of the Attenuator Stage is coupled to the Gain Controlled Amplifier via C503.

### 7.43 Gain Controlled Amplifier

The power gain of this stage is controlled by the microprocessor, U301; via the signal line PA-BIAS buffered by the Unity Gain Buffer (U503). The voltage on the PA\_BIAS control line controls the gain of the stage. During calibration the gain of the stage is adjusted so as to set the TX power delivered to the Antenna to 100 mW.

The output of the Gain Controlled Amplifier (U502 pin 1) is coupled to the **TX Interstage Band Pass Filter** by means of C506.

### 7.44 TX Interstage Band Pass Filter

The TX Interstage BPF (Y501) provides attenuation of the noise sidebands of the TX VCO occurring within the RX downlink band. Its insertion loss, within the uplink band of frequencies is a maximum of 3 dB.

### 7.45 TX Power Amplifier

The TX Power Amplifier provides power gain to raise the level of the transmitter output to 200 mW, which, after the loss in BPFTX of 3 dB, produces a nominal 100 mW at the antenna. The dc bias point of the stage is set by the voltage level present on control line PA\_BIAS under control of the microprocessor U301. When transmit operation is not required, i.e. during stand-by, the PA\_BIAS line is low thus turning off the dc bias to the TX Power Amplifier. This ensures that the power consumption of the TX, during stand-by is minimised. The collector supply to Q501 is derived directly from the battery pack output via line **+B**.

The output of Q501 is coupled to the input of **BPF\_TX** (Y503) via impedance transforming network comprising C516, L500 and C515.

### 7.46 Duplexer

The Duplexer comprises the TX Band Pass Filter and the RX Band Pass Filter. The Duplexer is required in order to allow the use of a common antenna for both TX and RX. Signals originating from the TX are passed through the BPF-TX with an attenuation of less than 3 dB. When TX signals reach the junction point comprising C518, L507 they are presented with impedance of the order of 50  $\Omega$  in the direction of the antenna, but much higher impedance in the direction of the receiver i.e. via L707. Thus the majority of the TX power is directed into the antenna. Receive signals arriving at the antenna, are conducted to the junction of C518 and L507. These signals see high impedance in the direction of the TX Band Pass Filter but impedance of approximately 50  $\Omega$  in the direction of the RX Band Pass Filter. Signals, within the downlink frequency band, pass through the RX Band Pass Filter with an attenuation of less than 3 dB.

### 7.47 External Antenna Socket

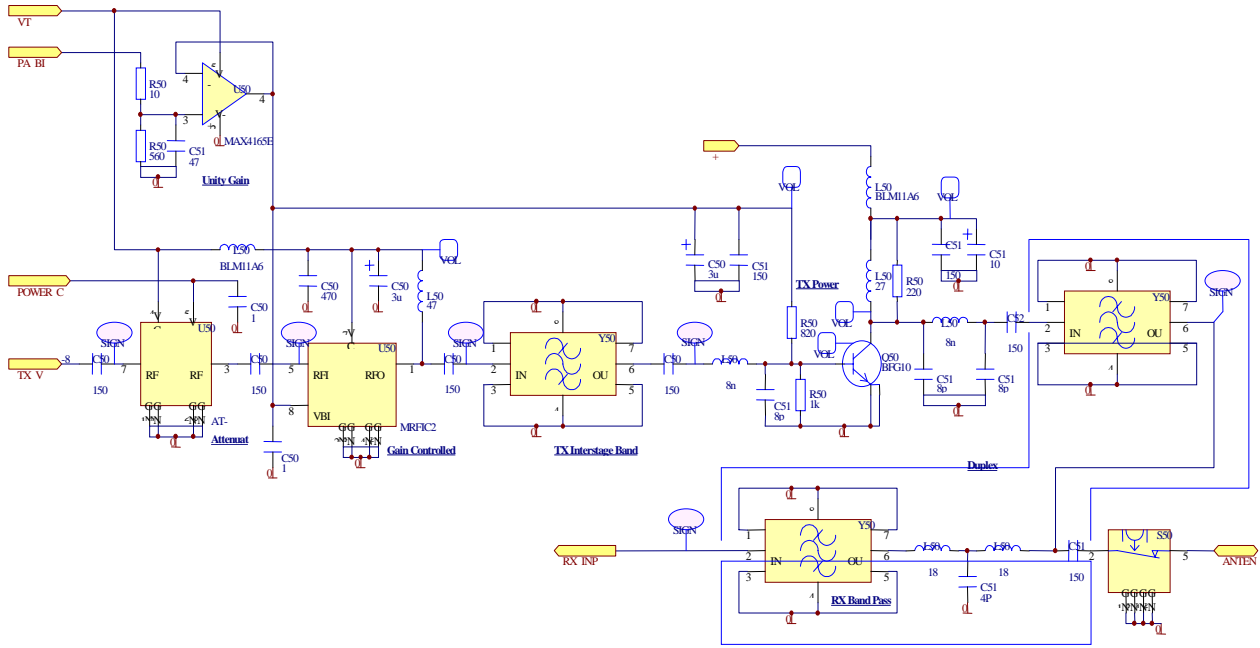
When no external antenna is connected the External Antenna Socket S501 provides a direct path to

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The integral antenna fitted to the top of the phone. When an external antenna is connected a switch within the External Antenna Socket disconnects the phone's set top antenna and connects the external antenna.

### 7.48 Unity Gain Buffer

The Unity Gain Buffer provides a non-inverting voltage gain of X1 and allows the output of the Digital to Analogue Converter (DA10), located within U401 on the BaseBand circuit, to control the level of bias current in the TX Power Amplifier via control line **PA\_BIAS**.



**Circuit Diagram - A66**  
**Transmitter**



## 8 Calibration Procedure

**Note: Calibration is required following the replacement of any electrical component. Ensure that the PCB Assembly is fitted within the plastic case and that the fixings screws are tightened to the specified torque**

### 8.1 Equipment Required

Item	Description	Tellit P/n	Qty	Remarks
1	IBM Compatible PC with Pentium 100 or higher, fitted with 32 MB RAM and CD ROM Drive and Mouse		1	
2*	Cable Assembly 9W D Plug – 9W D Socket	xxxxx	1	
3*	Cable Assembly 25W D Plug – 25W D Socket	xxxxx	1	
4*	Mains Charger or PSU set to 6V 600mA max	xxxxx	1	
5	RF Communications Test Set		1	HP 8920B or similar
6*	Cable Assembly 50Ω BNC Plug - 50Ω BNC Plug		3	
7	Power Supply Unit 12 V dc Hum & Noise < 50 mV pp		1	
8*	Test Interface Box A66/A77		1	
9*	Cable Assembly 37W D Plug to 37W D Plug		1	
10*	Test Fixture A66 Phone		1	
11	Coaxial Adapter SMA Socket – N Plug		1	
12	Coaxial Lead Assembly 50Ω BNC Plug - 50Ω BNC Plug		1	
13	Digital Multimeter		2	
14*	Test Lead 4mm Plug – 4mm Plug Red	xxxxx	3	
15*	Test Lead 4mm Plug – 4mm Plug Black	xxxxx	3	

### 8.2 Connecting the Equipment

8.2.1 Connect the equipment as shown in Figure 8-1 below.

### 8.3 Starting up the Diagnostics Software

8.3.1 Start the Tellit Service and Diagnostic Software by clicking the icon. The TELLIT logo screen is displayed. Click on “CLICK TO CONTINUE”.

### 8.4 Get Phone Details

8.4.1 The Get Phone Details window is displayed. Select the appropriate frequency band corresponding to the band of the phone to be calibrated, e.g. Band 1, by checking the required band option.

8.4.2 The transmit and receive radio frequencies corresponding to the selected band, together with a list of countries, are displayed.

8.4.3 Select the model of the phone to be calibrated by checking the required model option.

8.4.4 The version of the software in the phone is automatically displayed in the text window.

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8.4.5 Once frequency band and phone type have been selected click "OK" to proceed.

8.5 Main Menu

8.5.1 Click the "CALIBRATE" button to proceed to the Calibration Menu.

8.6 Calibration Menu

***Note: When calibrating the phone ensure that all calibration functions are performed in the order in which the calibration function buttons are presented. Start at TX Freq and finish at SAT Dev ensuring that all calibrations are performed.***

8.7 TX Frequency

8.7.1 Click "TX FREQ".

8.7.2 Read the upper text area of the window to receive guidance on the calibration procedure.

8.7.3 Measure the transmitter frequency using the RF Communication Test Set (the mobile terminal's transmitter is automatically keyed on).

8.7.4 Adjust the "SET TX FREQUENCY" slider at the bottom of the window until the transmitter frequency displayed on the RF Communication Test Set corresponds as near as possible to the frequency value shown in the text box. This can be done by repeatedly clicking the left or right arrows on either side of the slider or by continuously left-clicking the slider control and dragging it across its range.

8.7.5 When satisfied with the frequency value, click on the "SAVE CAL" button to store the calibration value.

8.7.6 Click the "QUIT" button to return to the calibration menu.

8.8 RX RSSI

8.8.1 Click "RX RSSI".

8.8.2 Read the instructions shown in the text box.

8.8.3 Adjust the RF Communication Test set to produce an unmodulated RF output at a level of +20 dB $\mu$ V 1 with the frequency requested on the PC display.

8.8.4 Click the "SAVE CAL" button to store the calibration value.

8.8.5 Increment the RF level in steps of +10 dB up to +70 dB clicking the "UPDATE" button after each step, verifying that the displayed RF level in the window is correct to within the tolerance as stated within the text window.

8.8.6 Click the "QUIT" button to return to the calibration menu.

8.9 TX Power

8.9.1 Click "TX POWER".

8.9.2 Refer to the instructions shown in the text box.

8.9.3 Measure the TX Power using the RF Communications Test Set.

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- 8.9.4 If necessary, adjust the "SET TX POWER" slider to obtain and output as stated within the text window.
- 8.9.5 Click the "SAVE CAL" button to store the calibration value.
- 8.9.6 Click the "QUIT" button to return to the calibration menu.
- 8.10 RX Audio Level
  - 8.10.1 Click "RX AUDIO LEVEL".
  - 8.10.2 Read the upper text area of the window to receive guidance on the calibration procedure.
  - 8.10.3 Set up the RF Communications Test Set to output a signal as instructed with the frequency, level and modulation requested.
  - 8.10.4 Adjust the "SET RX AUDIO LEVEL" slider at the bottom of the window until the audio output level displayed on the RF Communications Test Set corresponds as near as possible to the value shown in the text box. This can be done by repeatedly clicking the left or right arrows on either side of the slider or by continuously left-clicking the slider control and dragging it across its range.
  - 8.10.5 Click the "SAVE CAL" button to store the calibration value.
  - 8.10.6 Click the "QUIT" button to return to the calibration menu.
- 8.11 TX Max Deviation
  - 8.11.1 Click "TX MAX DEV".
  - 8.11.2 Following the on-screen instructions, set the audio signal (from the RF Communications Test Set to TXAF\_IN of the mobile terminal) to the values stated in the text box on the PC screen. Ensure that the RF Communications Test Set filters and detector settings are as instructed. Measure the frequency deviation as stated ensuring the filters in the RF Communications Test Set are set correctly.
  - 8.11.3 Adjust the "SET MAX TX DEVIATION" slider at the bottom of the window until the frequency deviation displayed on the RF Communications Test Set corresponds as near as possible to the target value shown in the text box. This can be done by repeatedly clicking the left or right arrows on either side of the slider or by continuously left-clicking the slider control and dragging it across its range.
  - 8.11.4 Click the "SAVE CAL" button to save the calibration value.
  - 8.11.5 Click the "QUIT" button to return to the calibration menu.
- 8.12 TX Audio Deviation
  - 8.12.1 Click "TX AUDIO DEVIATION".
  - 8.12.2 Following the on-screen instructions, connect the stated audio source to AF IN of the mobile terminal. Measure the frequency deviation as stated ensuring the filters in the RF Communications Test Set are set correctly.
  - 8.12.3 Adjust the "SET TX NORMAL DEVIATION" slider at the bottom of the window until the frequency deviation displayed on the RF Communications Test Set corresponds as near as possible to the target value shown in the text box. This can be done by repeatedly clicking the left or right arrows on either side of the slider or by continuously left-clicking the slider control and dragging it across its range.

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- 8.12.4 Click the "SAVE CAL" button to store the calibration value.
- 8.12.5 Click the "QUIT" button to return to the calibration menu.
- 8.13 FFSK Deviation
  - 8.13.1 Click "FFSK DEV".
  - 8.13.2 Following the on-screen instructions, measure the frequency deviation using the RF Communications Test Set. Ensure that the filter values and deviation units stated in the text box are set on the RF Communications Test Set.
  - 8.13.3 Adjust the "SET TX FFSK LEVEL" slider at the bottom of the window until the frequency deviation displayed on the RF Communications Test Set corresponds as near as possible to the target value shown in the text box. This can be done by repeatedly clicking the left or right arrows on either side of the slider or by continuously left-clicking the slider control and dragging it across its range.
  - 8.13.4 Click the "SAVE CAL" button to store the calibration values.
  - 8.13.5 Click the "QUIT" button to return to the calibration menu.
- 8.14 SAT Dev
  - 8.14.1 Click "SAT DEV".
  - 8.14.2 Read the upper text area of the window to receive guidance on the calibration procedure. Set up the RF Communications Test Set as instructed.
  - 8.14.3 Inject a RF signal with a level, frequency and deviation as stated in the text box. Measure the frequency deviation of the transmitter using the RF Communications Test Set to the filter values stated in the text box.
  - 8.14.4 Adjust the "SET SAT DEVIATION" slider at the bottom of the window until the frequency deviation displayed on the RF Communications Test Set corresponds as near as possible to the target value shown in the text box. This can be done by repeatedly clicking the left or right arrows on either side of the slider or by continuously left-clicking the slider control and dragging it across its range.
  - 8.14.5 Click the "SAVE CAL" button to store the calibration value.
  - 8.14.6 Click the "QUIT" button to return to the calibration menu.

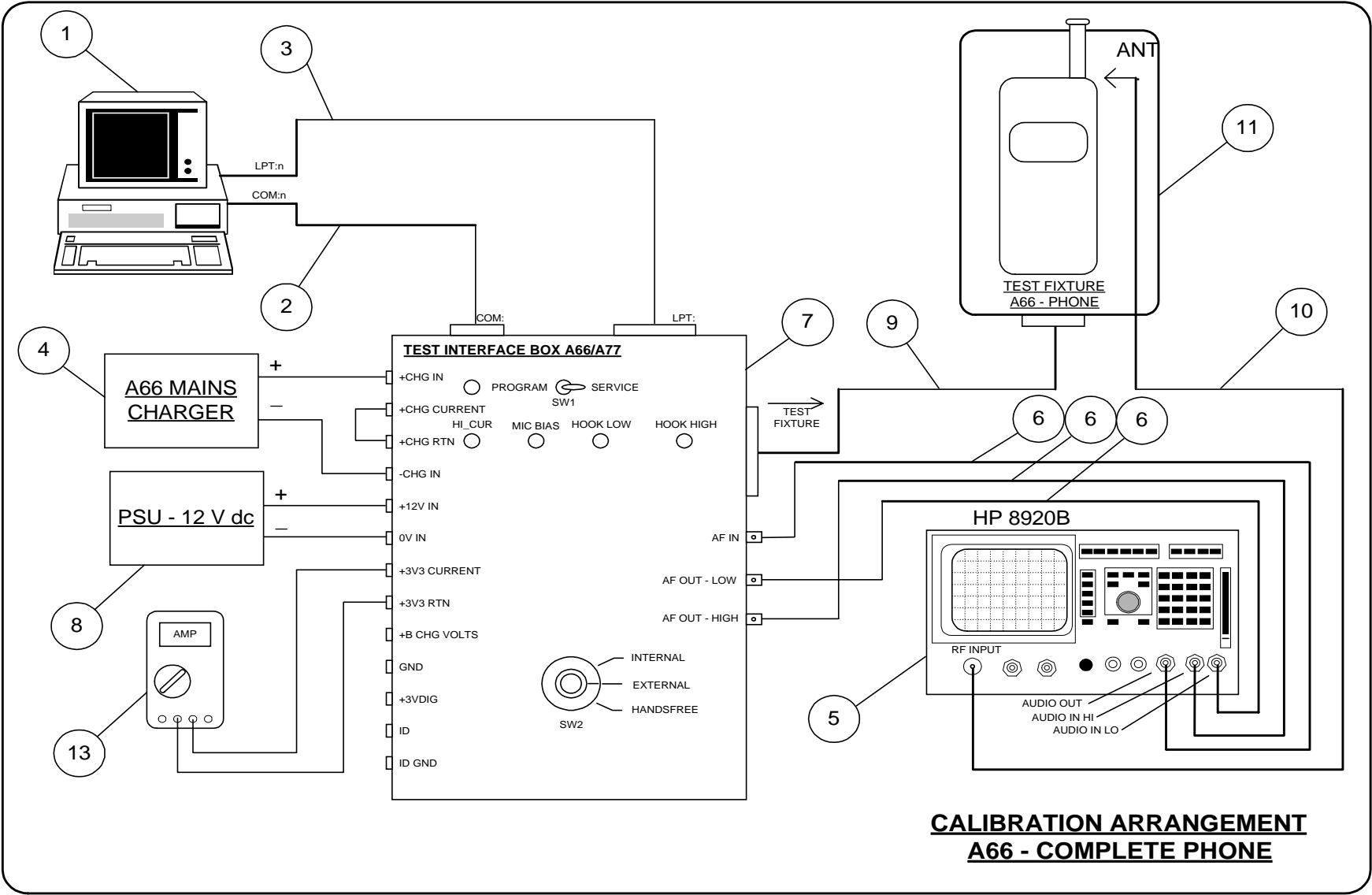


Figure 8-1

## 9 Programming Procedure

**Note: Programming of the phone is required following the replacement of the main processor (U301) or the external EEPROM (U302). If either of these devices have been changed the phone must be programmed before any other testing can be conducted. Programming may be performed with the PCB contained within the case or alternatively, if required, with the PCB removed from the case.**

**Note: Failure of the main processor, failure of the external EEPROM or programming the phone will erase the contents of the phone book. Before changing either of these devices or programming the phone attempt to save the contents of the phone book using the configuration tool Forte.**

**Note: Programming the phone will result in the loss of the calibration values stored in the internal EEPROM.**

**Following programming you must recalibrate the phone.**

### 9.1 Equipment Required

Item	Description	Tellit P/n	Qty	Remarks
1	IBM Compatible PC with Pentium 100 or higher fitted with 32 MB RAM and CD ROM Drive and Mouse		1	
2*	Cable Assembly 9W D Plug – 9W D Socket	xxxxx	1	
3*	Cable Assembly 25W D Plug – 25W D Socket	xxxxx	1	
4*	Mains Charger	xxxxx		
7	Power Supply Unit 12 V dc Hum & Noise < 50 mV pp		1	
8*	Test Interface Box A66/A77	xxxxx	1	
9*	Cable Assembly 37W D Plug to 37W D Plug	xxxxx	1	
10*	Test Fixture A66 Phone	xxxxx	1	
11*	Test Fixture A66 PCB	xxxxx	1	
14	Digital Multimeter		2	
15*	Test Lead 4mm Plug – 4mm Plug Red	xxxxx	3	
16*	Test Lead 4mm Plug – 4mm Plug Black	xxxxx	3	

### 9.2 Connecting the Equipment

9.2.1 Connect the equipment as shown in Figure 9-1 below.

### 9.3 Starting up the Diagnostics Software

9.3.1 Start the Tellit Service and Diagnostic software by clicking the icon. The TELLIT logo screen is displayed. Click on "CLICK TO CONTINUE".

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- 9.4 Get Phone Details
  - 9.4.1 The Get Phone Details window is displayed. Select the appropriate frequency band corresponding to the band of the phone to be programmed, e.g. Band 1, by checking the required band option.
  - 9.4.2 The transmit and receive radio frequencies corresponding to the selected band, with a list of countries, are displayed.
  - 9.4.3 Select the model of phone to be programmed by checking the required model option.
  - 9.4.4 The version of the software in the phone is automatically displayed in the text window.
  - 9.4.5 Once frequency band and phone type has been selected; click “OK” to proceed.
- 9.5 Main Menu
  - 9.5.1 Click the “PROGRAM” button to launch the Atmel ISP programming utility.
  - 9.5.2 Follow the onscreen instructions to set switch SW [RDL2] on the Test Interface Box to position “PROGRAM”.
- 9.6 Programming
  - 9.6.1 From the Atmel AVR ISP menu bar choose Project – Open Project or alternatively choose the Open Project tool on the tool bar.
  - 9.6.2 From the pop-up Option [RDL1] Box navigate to the programming project file e.g. A66\_276.avr.

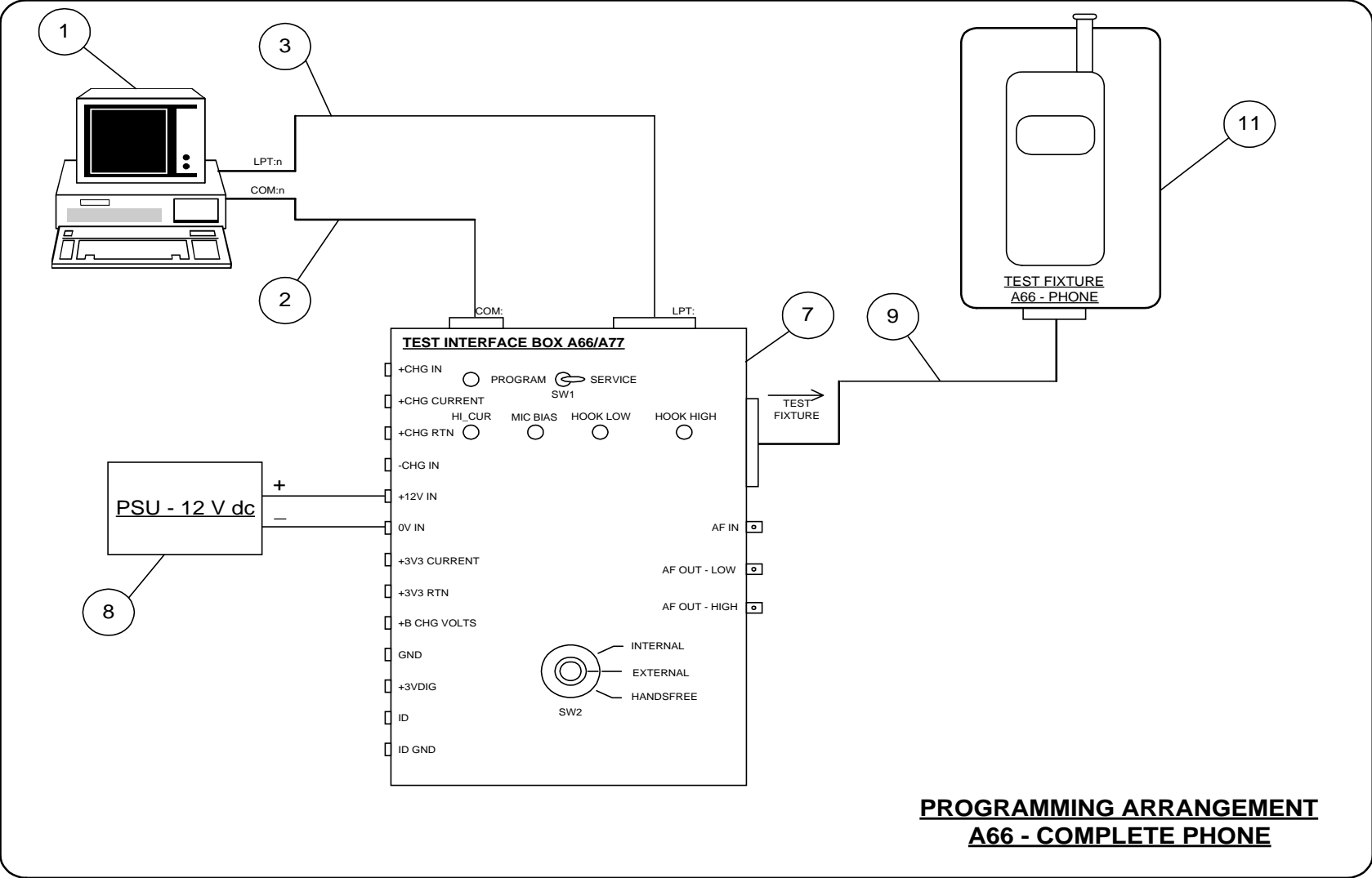
**Note: The file naming convention used for programming project files is as follows:**

**Example – A66\_276.avr**  
: :.....**Software Version**  
:.....**Phone Model**

Double click the file to open it.

- 9.6.3 From the menu bar choose Program – Program Device. Observe the progress bar as the programming of the device proceeds.
- 9.6.4 When the message box “Program Complete – No errors” appears click the “OK” button.
- 9.6.5 Click on the right hand top of screen to close program function.
- 9.6.6 Follow the onscreen instructions to set switch SW [RDL2] on the Test Interface Box to position “SYSTEM”.

**Note: Following programming perform calibration and test of the phone.**



**PROGRAMMING ARRANGEMENT  
A66 - COMPLETE PHONE**

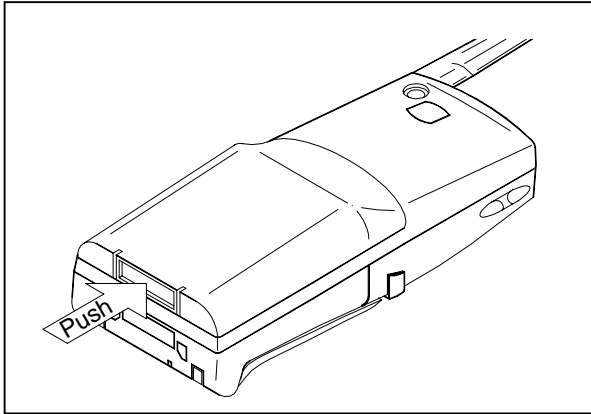
Figure 9-1



10 Basic Servicing Procedure -

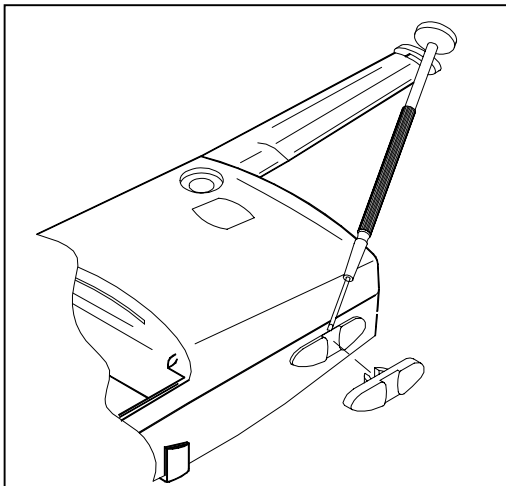
2

10.1 Removing the Battery Pack



**Figure 10-1**

- 10.1.1 Push the Battery Release Catch as shown in Figure 10-1 above.
- 10.1.2 Lift the Battery Pack off the phone.
- 10.2 Removing the Volume Button
- 10.2.1 Lever out the Volume Button using a small Jeweller's screwdriver inserted into the position on the volume button as shown in Figure 10-2.



**Figure 10-2**

**Caution – Take care not to damage the plastic case of the phone.**

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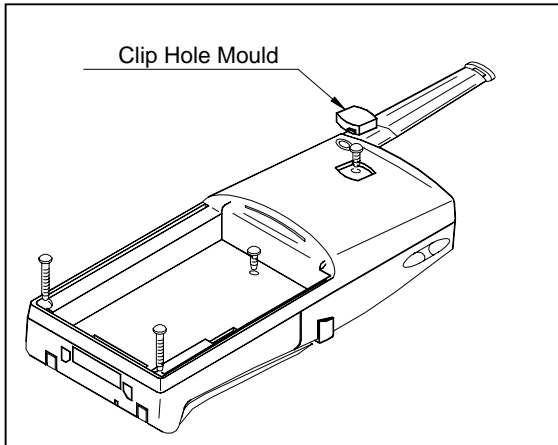
## 10.3 Removing the Back Moulding

10.3.1 Remove the volume button as described in 10.2 above.

10.3.2 Remove the Clip Hole Mould using a small Jeweller's screwdriver as described in Figure 10.3 below.

10.3.3 Unscrew 4 screws using a small Torx™ screwdriver size T6 X 60 and retain screws.

10.3.4 Carefully lift off the back moulding.



**Figure 10-3**

## 10.4 Removing the PCB

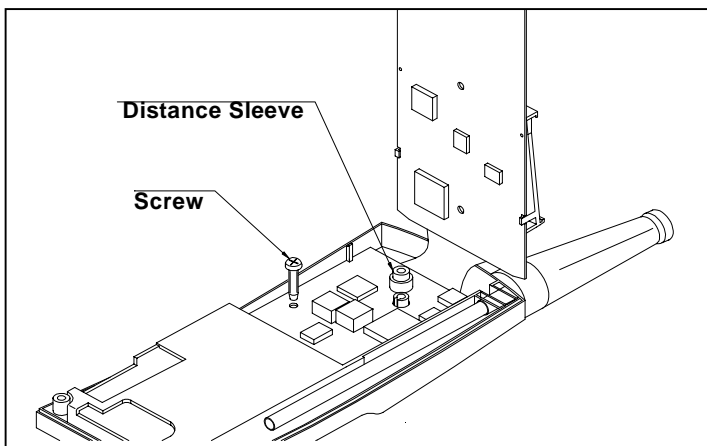
10.4.1 Remove the volume button as described in 10.2 above.

10.4.2 Remove the back moulding as described in 10.3 above.

10.4.3 Hinge the PCB up and remove screw and distance sleeve as shown in Figure 10-4 below. Retain the screw and distance sleeve.

10.4.4 Lift the PCB assembly out taking care not to damage the antenna contact.

10.4.5 Store the PCB assembly in an anti-static bag.

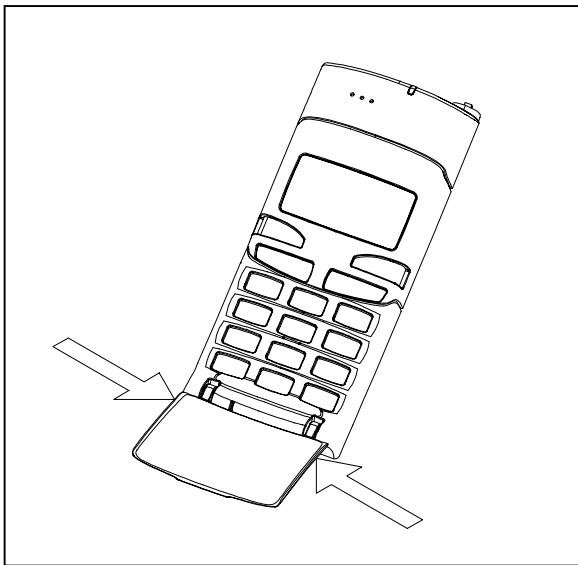


**Figure 10-4**

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### 10.5 Changing the Cover Moulding

10.5.1 Squeeze the sides of the cover moulding as shown in Figure 10-5 below and lift out.



**Figure 10-5**

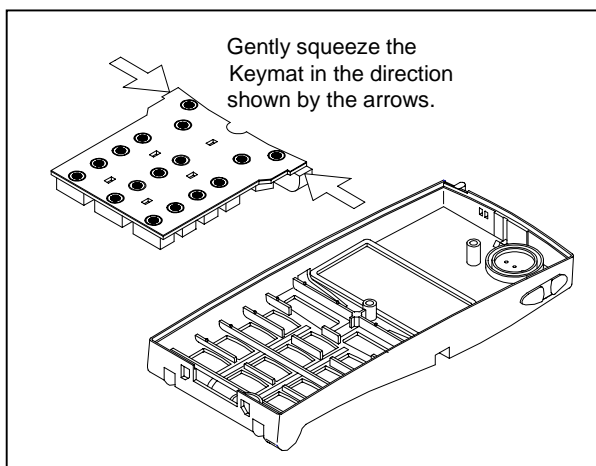
### 10.6 Changing the Keymat

10.6.1 Remove the volume button as described in 10.2 above.

10.6.2 Remove the back moulding as described in 10.3 above.

10.6.3 Remove the keymat from the front case/window assembly.

10.6.4 Fit new keymat as shown in Figure 10-6 below and reassemble the phone in reverse order.

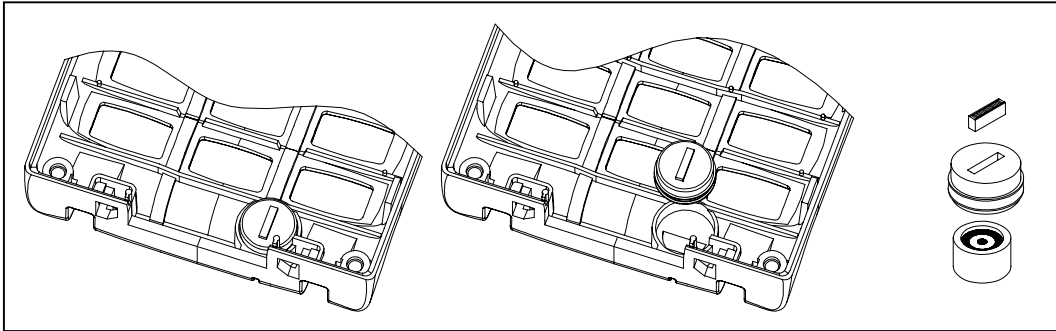


**Figure 10-6**

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### 10.7 Changing the Microphone

10.7.1 Remove the volume button as described in 10.2 above.



**Figure 10-7**

10.7.2 Remove the back moulding as described in 10.3 above.

10.7.3 Remove the microphone assembly out of the recess in the front case using tweezers as shown in Figure 10-7 above.

10.7.4 Extract the microphone from inside the microphone gasket and retain the zebra strip and microphone gasket.

10.7.5 Fit new microphone into the microphone gasket. Ensure that the end of the microphone having the gold coaxial contacts is inserted first into the microphone gasket (see Figure 10-7 above) and that the microphone is fully inserted into the microphone gasket.

10.7.6 Insert zebra strip into the slot at the top of the microphone boot. Ensure that the conductive stripes on the zebra strip are visible. See Figure 10-7 above.

10.7.7 Fit the microphone assembly in the recess in the front case ensuring that the zebra strip is oriented as shown in Figure 10-7 above.

**Caution – Take care not to damage the front face of the Microphone.**

### 10.8 Changing the Speaker

10.8.1 Remove the volume button as described in 10.2 above.

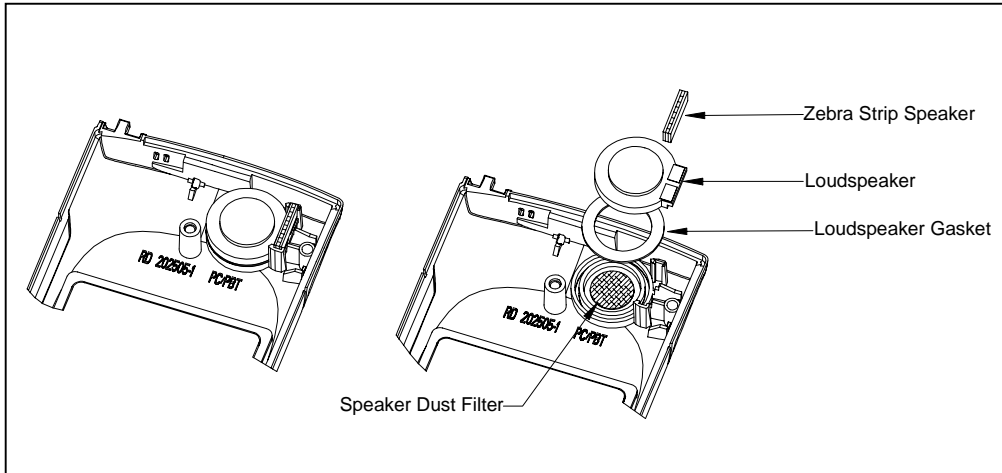
10.8.2 Remove the back moulding as described in 10.3 above.

10.8.3 Remove the PCB assembly as described in 10.4 above.

10.8.4 Lift out the zebra strip and retain.

10.8.5 Prise the Speaker from the front case/window assembly using a small jewellers screwdriver or similar.

10.8.6 Re-assemble as shown in Figure 10-8 overleaf.



**Figure 10.8**

10.9 Changing the LCD Panel

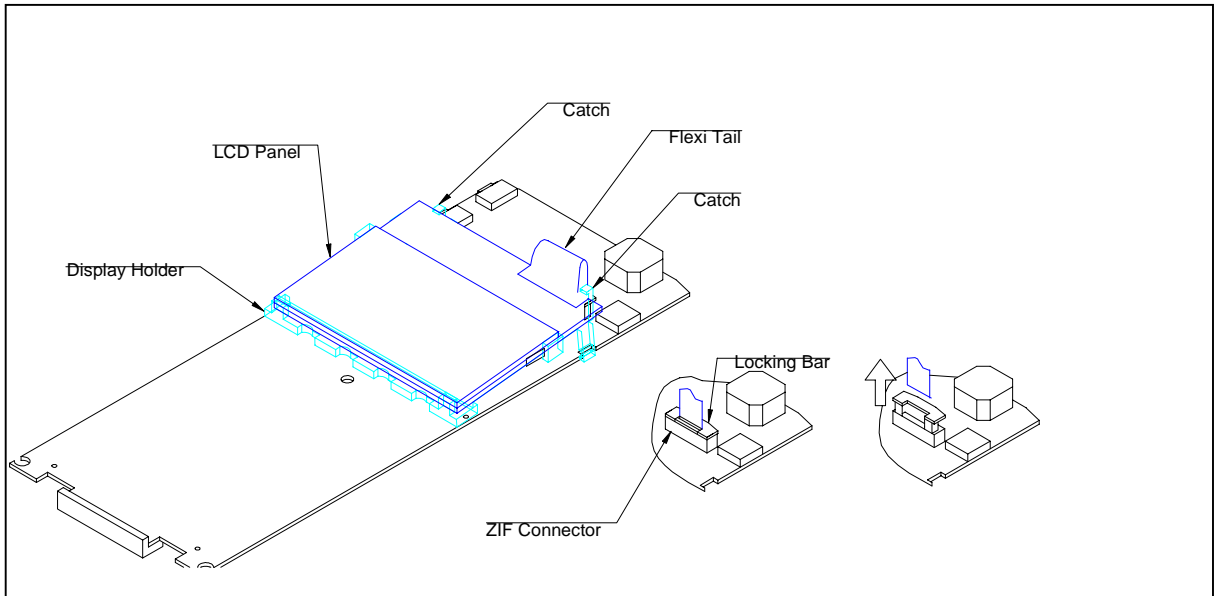
10.9.1 Remove the volume button as described in 10.2 above.

10.9.2 Remove the back moulding as described in 10.3 above.

10.9.3 Remove the PCB assembly as described in 10.4 above.

10.9.4 Release 2 catches as shown in Figure 10-9 below and remove the LCD panel from the display holder.

10.9.5 Lift the ZIF connector-locking bar and extract the LCD panel flexi-tail.



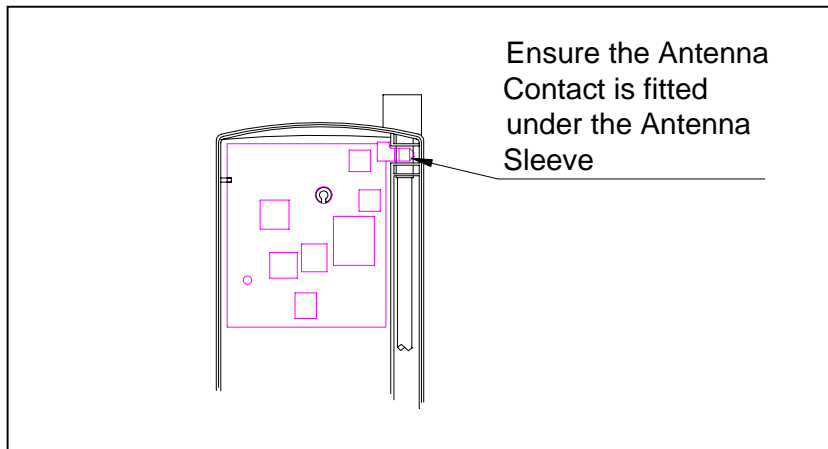
**Figure 10-9**

10.9.6 Reassemble in reverse order taking care to ensure that the LCD panel flexi tail is fully inserted into the ZIF connector before the locking bar is pushed down.

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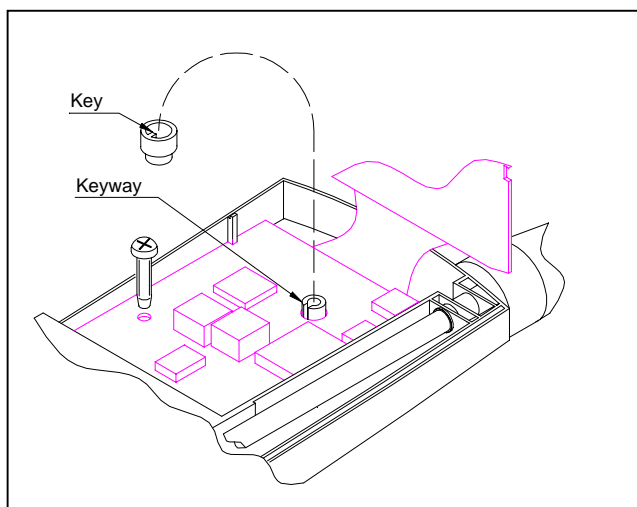
### 10.10 Reassembling the phone

- 10.10.1 Fit the transceiver part of the PCB assembly into the back moulding, as shown in Figure 10-10 below taking care to ensure that the antenna contact is not damaged.



**Figure 10-10**

- 10.10.2 Fit the screw, as shown in Figure 10-11 below, and tighten to a torque setting of 0.32 Nm using a torque driver fitted with a T6 X 60 adapter.
- 10.10.3 Fit the distance sleeve ensuring that it is orientated correctly as shown in Figure 10-11 below.



**Figure 10-11**

- 10.10.4 Fold the main part of the PCB assembly flat onto the back moulding ensuring the fixing holes in the PCB align with the appropriate holes in the back moulding. Ensure that locating spigots on the back moulding engage in the appropriate holes in the PCB assembly.
- 10.10.5 Offer the front case/window assembly to the back moulding and PCB engaging the tongue on the front case, adjacent to the antenna mounting, into the recess in the back moulding. Lower the front case onto the back moulding.

Drawing showing how to assemble the front and rear case goes here – not yet drawn.

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- 10.10.6 Insert 3 screws 12mm long and 1 screw 5mm long as shown in Figure 10-12. Tighten to a torque of 0.32 Nm using a torque driver fitted with a T6 X 60 adapter.

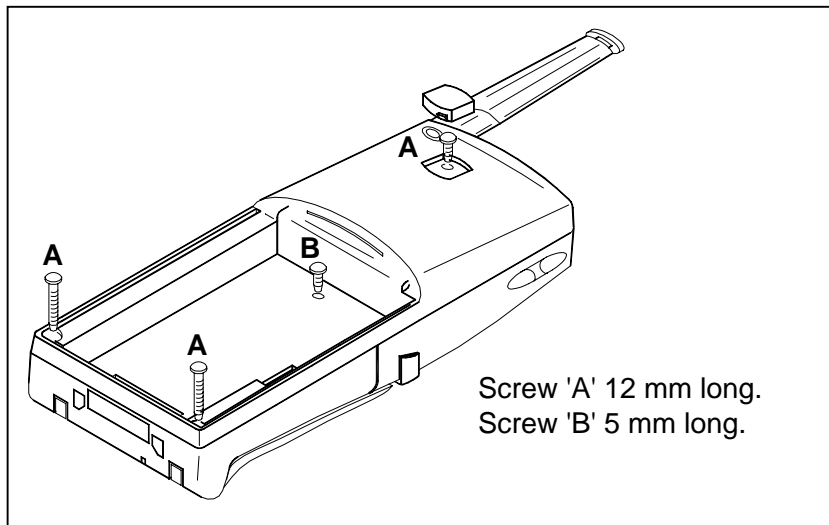


Figure 10-12

- 10.10.7 Refit the clip hole moulding.
- 10.10.8 Refit the battery pack.
- 10.10.9 Perform basic functional testing of the phone.

**11      Fault Diagnosis**

**NOTES**



12 Mechanical Assembly Diagrams and Parts Lists

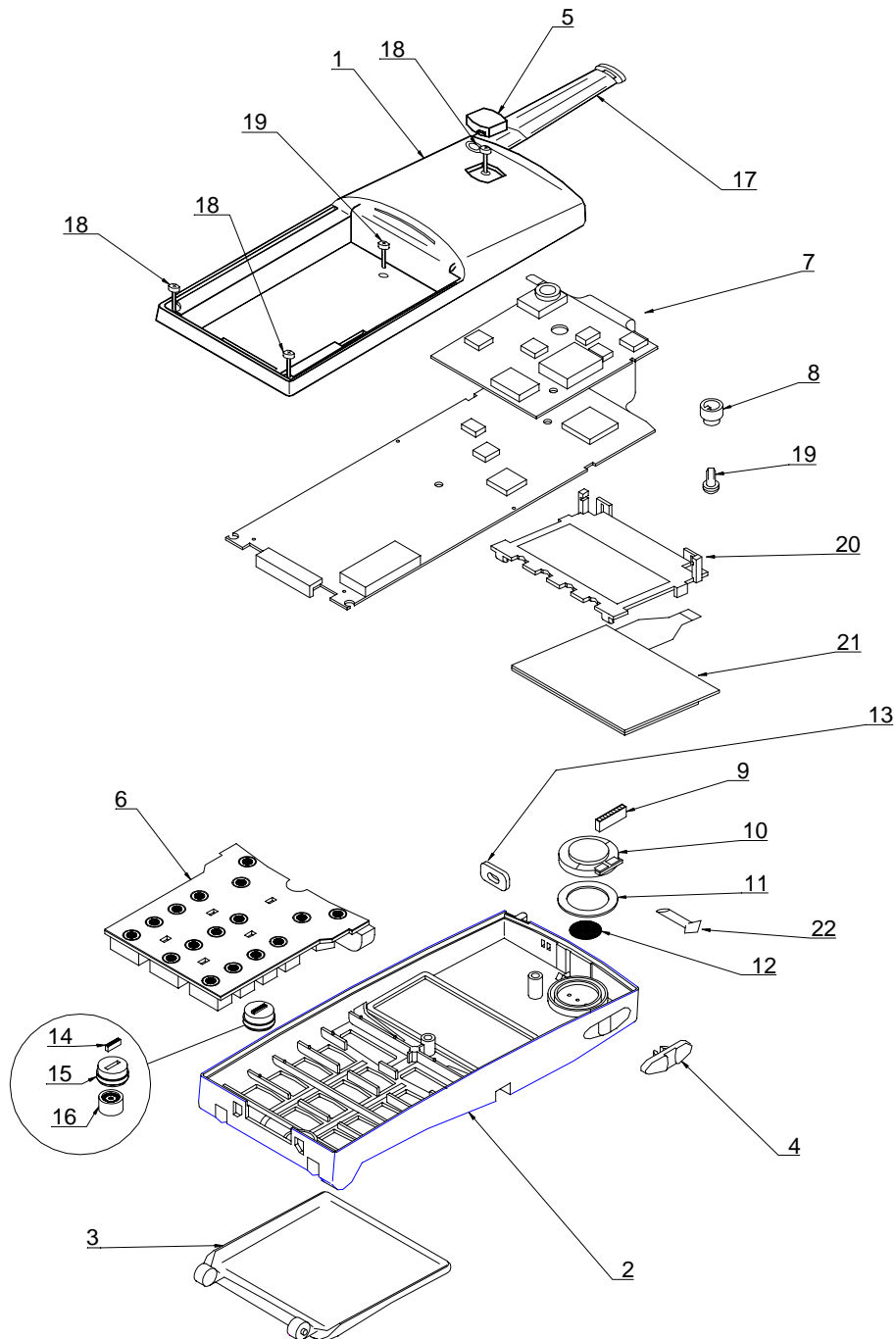


Figure 12-1

## COMPANY CONFIDENTIAL

Item	Description	Qty	Part Number
	Back Moulding Metalised	1	31005-001
2	Front Case/Window Assy	1	See Table 15-2
3	Cover Mould	1	See Table 15-2
4	Volume Button	1	32001-001
5	Clip Hole Mould	1	32002-001
6	Terminal A1 Keyboard Hard	1	See Table 15-2
7	PCB Assembly	1	See Table 15-3
8	Distance Sleeve	1	32003-001
9	Zebra Strip Speaker	1	73901-001
10	Loudspeaker	1	68002-001
11	Loudspeaker Gasket	1	35303-001
12	Speaker Dust Filter	1	35501-001
13	Gasket Buzzer	1	35304-001
14	Zebra Strip – Microphone 2.7	1	73902-001
15	Microphone Gasket 2.7 mm	1	35301-001
16	Microphone	1	68003-001
17	Terminal A1 Antenna	1	See Table 15-3
18	Screw Torx Hd 2.2mm X	3	82002-120
19	Screw Torx Hd 2.2mm X 5mm	2	82002-050

Table 12-1

Item	Description	Colour/Branding	Part Number
2a	Front Case/Window Assy	Black RDL A66	08501-001
2b		Green RDL A66	08501-002
2c		Blue RDL A66	08501-003
2d		Grey RDL A66	08501-004
3a	Cover Moulding	Black RDL	31003-001
3b		GreenRDL	31003-002
3c		Blue RDL	31003-003
3d		Grey RDL	31003-004
6a	Keymat	Latin	35201-001
6b		Cyrillic	35201-002

Table 12-2

Item	Description	Band	Part Number
	PCB Assembly	Band 1:3	21001.001
7b	PCB Assembly	Band 5	21001-005
17a	Terminal A1 Antenna	Band 1:3	7901-001
17b	Terminal A1 Antenna	Band 5	7901-001

Table 12-3

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## 13 Circuit Diagrams, PCB Assembly Diagrams and Parts Lists

CCT ref	Tellit P/n.	Description	Value	Toleranc e	Rating	Type	Side	X Position	Y Position
BU1	68001-001	SOUNDER					Side 1	32.9	101.0
C1	53306-151	CAP CER	150pF	+/-5%	50V		Side 1	12.0	142.9
C101	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	13.3	9.3
C102	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	20.2	9.9
C103	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	17.6	9.9
C104	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	18.9	9.9
C105	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	16.4	9.9
C106	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	21.5	9.9
C107	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	22.7	9.9
C108	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	24.0	9.9
C109	53309-102	CAP CER	1nF	+/-10%	50V		Side 2	25.3	9.9
C110	53309-102	CAP CER	1nF	+/-10%	50V		Side 2	27.0	9.9
C111	53311-104	CAP CER	100nF	+/-10%	16V		Side 1	26.3	95.6
C112	53311-104	CAP CER	100nF	+/-10%	50V		Side 1	35.0	90.2
C113	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	8.3	27.4
C114	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	7.1	27.4
C115	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	2.6	32.8
C116	53306-101	CAP CER	100pF	+/-5%	50V		Side 2	4.7	26.8
C201	54303-226	CAP TANT	22uF	+/-20%	6V		Side 2	40.8	7.5
C202	53212-105	CAP CER	1uF	+/-10%	10V		Side 2	2.9	62.0
C203	54103-225	CAP TANT	2.2uF	+/-20%	10V		Side 2	31.2	63.5
C204	54203-106	CAP TANT	10uF	+/-20%	6V		Side 2	21.7	63.6
C205	54203-106	CAP TANT	10uF	+/-20%	6V		Side 2	18.4	63.6
C206	53311-104	CAP CER	100nF	+/-10%	16V		Side 2	3.9	67.8

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C207	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	26.6	68.1
C208	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	11.0	71.3
C209	54103-225	CAP TANT	2.2uF	+/-20%	10V	Side 2	36.3	73.7
C211	54103-225	CAP TANT	2.2uF	+/-20%	10V	Side 2	28.4	74.7
C212	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	37.2	65.9
C213	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	30.2	65.8
C214	54103-225	CAP TANT	2.2uF	+/-20%	10V	Side 2	35.4	63.5
C301	53304-220	CAP CER	22pF			Side 1	4.8	80.2
C302	53304-220	CAP CER	22pF			Side 1	8.6	80.3
C303	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	11.3	83.1
C304	53306-331	CAP CER	330pF	+/-5%	50V	Side 1	32.3	76.8
C305	53311-104	CAP CER	100nF	+/-10%	16V	Side 1	29.8	87.9
C306	53311-104	CAP CER	100nF	+/-10%	16V	Side 1	31.8	88.0
C307	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	26.2	79.4
C308	53309-103	CAP CER	10nF	+/-10%	50V	Side 1	32.5	83.4
C309	53309-103	CAP CER	10nF	+/-10%	50V	Side 1	35.8	82.8
C310	53309-102	CAP CER	1nF	+/-10%	50V	Side 1	33.0	87.8
C311	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	31.7	84.4
C312	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	31.9	82.7
C313	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	36.4	97.9
C314	53311-104	CAP CER	100nF	+/-10%	16V	Side 1	32.8	75.3
C315	53309-103	CAP CER	10nF	+/-10%	50V	Side 1	2.5	64.3
C316	53311-224	CAP CER	220nF	+/-10%	16V	Side 1	4.1	70.1
C317	53306-471	CAP CER	470pF	+/-5%	50V	Side 1	11.8	73.1
C318	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	14.6	9.5
C319	53309-103	CAP CER	10nF	+/-10%	50V	Side 1	34.3	62.1
C320	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	22.7	66.7
C401	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	3.5	86.0
C402	53306-101	CAP CER	100pF	+/-5%	50V	Side 2	3.6	84.5
C403	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	4.2	83.4
C404	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	11.4	75.1
C405	53304-220	CAP CER	22pF			Side 2	10.7	85.2

## COMPANY CONFIDENTIAL

C406	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	6.2	85.9
C407	53311-473	CAP CER	47nF	+/-10%	16V	Side 2	18.6	102.2
C408	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	8.1	72.7
C409	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	5.0	72.6
C410	53311-473	CAP CER	47nF	+/-10%	16V	Side 2	13.2	84.2
C411		NOTFITTED				Side 2	19.9	85.4
C414	53311-473	CAP CER	47nF	+/-10%	16V	Side 2	4.3	88.5
C415	53306-221	CAP CER	220pF	+/-5%	50V	Side 2	20.8	95.9
C420	53309-102	CAP CER	1nF	+/-10%	50V	Side 1	10.1	95.8
C421	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	22.1	97.8
C422	53311-473	CAP CER	47nF	+/-10%	16V	Side 1	15.9	98.8
C423	53309-103	CAP CER	10nF	+/-10%	50V	Side 1	12.6	95.8
C424	53311-473	CAP CER	47nF	+/-10%	16V	Side 2	7.2	102.4
C425	53311-104	CAP CER	100nF	+/-10%	16V	Side 1	8.4	92.5
C426	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	2.1	92.1
C427	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	6.3	87.5
C428	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	2.1	88.9
C429	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	3.8	96.4
C430	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	2.2	94.2
C431		NOTFITTED				Side 1	11.7	93.2
C440	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	31.6	97.7
C441		NOTFITTED				Side 2	4.8	100.7
C442	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	2.4	102.1
C443	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	11.1	104.2
C444	53306-101	CAP CER	100pF	+/-5%	50V	Side 2	10.3	102.1
C445	53309-103	CAP CER	10nF	+/-10%	50V	Side 1	6.8	72.1
C446	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	15.8	102.1
C447	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	15.8	100.8
C501	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	17.4	127.9
C502	53309-102	CAP CER	1nF	+/-10%	50V	Side 1	16.3	120.2
C503	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	11.0	123.8
C504	53309-102	CAP CER	1nF	+/-10%	50V	Side 1	12.9	120.3

## COMPANY CONFIDENTIAL

C505	54104-335	CAP TANT	3.3uF	+/-20%	6V	Side 1	1.5	126.0
C506	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	1.3	119.5
C507	53306-471	CAP CER	470pF	+/-5%	50V	Side 1	2.0	122.5
C508	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	9.8	116.5
C509	54104-335	CAP TANT	3.3uF	+/-20%	6V	Side 1	10.4	118.2
C510	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	9.8	119.8
C511	61302-100	INDUCTOR	10nH	2%		Side 1	14.2	116.4
C512	53301-082	CAP CER	8.2pF	+/-0.25pF	50V	Side 1	16.8	116.2
C513	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	20.9	120.1
C514	54203-106	CAP CER	10uF	+/-20%	6V	Side 1	23.9	120.8
C515	53301-047	CAP CER	4.7pF			Side 1	27.4	116.9
C516	53301-056	CAP CER	5.6pF			Side 1	25.5	117.4
C517	53301-047	CAP CER	4.7pF			Side 2	35.0	120.5
C518	53306-151	CAP CER	150pF	+/-5%	50V	Side 2	29.7	122.0
C519	53311-473	CAP CER	47nF	+/-10%	16V	Side 2	7.8	114.7
C521	53306-151	CAP CER	150pF	+/-5%	50V	Side 2	27.5	117.1
C601	54104-335	CAP CER	3.3uF	+/-20%	6V	Side 1	22.0	143.2
C602	53306-471	CAP CER	470pF	+/-5%	50V	Side 1	15.0	136.7
C603	54104-335	CAP TANT	3.3uF	+/-20%	6V	Side 2	21.4	131.5
C604	53309-103	CAP CER	10nF	+/-10%	50V	Side 1	18.7	128.1
C605	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	36.0	139.7
C606	53304-150	CAP CER	15pF			Side 1	22.5	132.2
C607	53311-473	CAP CER	47nF	+/-10%	16V	Side 1	15.1	140.9
C608	53311-104	CAP CER	100nF	+/-10%	16V	Side 1	15.2	143.8
C609	54104-335	CAP TANT	3.3uF	+/-20%	6V	Side 1	1.6	134.7
C610	53309-332	CAP CER	3.3nF	+/-10%	50V	Side 1	1.6	140.1
C611	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	16.8	131.9
C612	53309-103	CAP CER	10nF	+/-10%	50V	Side 1	4.7	150.2
C613	53311-104	CAP CER	100nF	+/-10%	16V	Side 1	4.6	151.8
C614	54104-335	CAP TANT	3.3uF	+/-20%	6V	Side 1	20.3	148.7
C615	53306-471	CAP CER	470pF	+/-5%	50V	Side 1	4.7	148.4
C616	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	21.8	153.1

## COMPANY CONFIDENTIAL

C617	53311-224	CAP CER	220nF	+/-10%	16V	Side 1	15.1	142.3
C618	53306-151	CAP CER	150pF	+/-5%	50V	Side 2	36.0	137.2
C619	53306-471	CAP CER	470pF	+/-5%	50V	Side 1	15.0	138.9
C620	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	20.8	116.4
C621	54104-335	CAP TANT	3.3uF	+/-20%	6V	Side 2	18.8	119.7
C622	53311-104	CAP CER	100nF	+/-10%	16V	Side 1	29.6	148.9
C623	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	26.2	121.9
C624	54104-335	CAP TANT	3.3uF	+/-20%	6V	Side 1	30.6	152.1
C701	53301-082	CAP CER	8.2pF	+/-0.25pF	50V	Side 1	33.1	131.7
C702	53309-332	CAP CER	3.3nF	+/-10%	50V	Side 1	30.3	131.3
C703	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	29.2	129.5
C704	53309-332	CAP CER	3.3nF	+/-10%	50V	Side 1	29.0	140.2
C705	53309-332	CAP CER	3.3nF	+/-10%	50V	Side 1	34.4	131.5
C706	53301-027	CAP CER	2.7pF			Side 1	31.9	137.1
C707	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	28.8	136.1
C708	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	28.0	143.7
C718	53309-102	CAP CER	1nF	+/-10%	50V	Side 2	17.2	130.6
C719	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	17.5	128.6
C720	53309-102	CAP CER	1nF	+/-10%	50V	Side 2	5.3	122.5
C721	53309-102	CAP CER	1nF	+/-10%	50V	Side 2	14.6	136.0
C722	54104-335	CAP TANT	3.3uF	+/-20%	6V	Side 2	20.5	134.7
C723	53212-105	CAP CER	1uF	+/-10%	10V	Side 2	13.6	122.2
C724	53309-102	CAP CER	1nF	+/-10%	50V	Side 2	12.0	137.0
C725	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	12.4	135.2
C726	53309-102	CAP CER	1nF	+/-10%	50V	Side 2	13.2	137.0
C727	53309-102	CAP CER	1nF	+/-10%	50V	Side 2	8.1	121.2
C728	53301-056	CAP CER	5.6pF			Side 1	33.0	153.8
C729	53301-022	CAP CER	2.2pF			Side 1	28.3	155.5
C730	53311-104	CAP CER	100nF	+/-10%	16V	Side 2	25.5	146.9
C731	53306-151	CAP CER	150pF	+/-5%	50V	Side 2	27.6	146.5
C732	53306-680	CAP CER	68pF			Side 2	25.6	149.6
C733	53304-330	CAP CER	33pF			Side 2	27.5	150.3

## COMPANY CONFIDENTIAL

C734	53304-120	CAP CER	12pF			Side 2	26.2	151.6
C735	53304-220	CAP CER	22pF			Side 2	24.4	148.2
C736	53301-082	CAP CER	8.2pF			Side 2	22.4	151.8
C737	53304-220	CAP CER	22pF			Side 2	12.3	154.9
C738	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	4.9	151.4
C739	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	6.2	154.0
C740	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	1.7	147.9
C741	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	12.9	148.2
C742	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	3.4	136.3
C743	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	4.5	125.1
C744	53306-221	CAP CER	220pF	+/-5%	50V	Side 2	3.4	135.0
C745	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	1.5	126.1
C747	53301-056	CAP CER	5.6pF			Side 2	3.8	148.4
C748	53301-100	CAP CER	10pF			Side 2	8.9	151.1
C749	53309-102	CAP CER	1nF	+/-10%	50V	Side 2	17.2	126.7
C750	53306-151	CAP CER	150pF	+/-5%	50V	Side 1	30.1	154.5
C751		NOTFITTED				Side 2	33.4	154.4
C752	53301-010	CAP CER	1pF			Side 2	32.2	154.4
C753	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	5.5	127.6
C754	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	4.5	130.6
C755	53309-103	CAP CER	10nF	+/-10%	50V	Side 2	31.0	149.2
D101	59002-001	DIODE			BAV99W	Side 1	33.5	5.5
D102	59002-001	DIODE			BAV99W	Side 2	6.0	33.0
D201	59003-001	DIODE SCOTTKY			STPS340U	Side 1	21.5	2.5
D202	59002-001	DIODE			BAV99W	Side 2	4.6	70.5
D204	59004-001	DIODE SCOTTKY			MBR520LT	Side 2	1.5	69.8
D301	59002-001	DIODE			BAV99W	Side 1	36.3	67.2
D302	59002-001	DIODE			BAV99W	Side 1	28.8	68.3
D303	59701-001	DIODE-LED RED/GREEN			CL-155UR/G-D-T	Side 1	25.7	99.0
D305	59703-001	DIODE-LED			CL-190YG-CD-T	Side 1	21.5	45.3
D306	59703-001	DIODE-LED			CL-190YG-CD-T	Side 1	14.6	32.9



## COMPANY CONFIDENTIAL

D307	59703-001	DIODE-LED		CL-190YG-CD-T	Side 1	28.4	32.9
D308	59703-001	DIODE-LED		CL-190YG-CD-T	Side 1	14.6	16.0
D309	59703-001	DIODE-LED		CL-190YG-CD-T	Side 1	28.4	16.0
D310	59702-001	DIODE-LED YELL/GREEN		CL-220YG-C-TS	Side 1	8.7	57.0
D311	59702-001	DIODE-LED YELL/GREEN		CL-220YG-C-TS	Side 1	17.2	57.0
D312	59702-001	DIODE-LED YELL/GREEN		CL-220YG-C-TS	Side 1	25.7	57.0
D313	59702-001	DIODE-LED YELL/GREEN		CL-220YG-C-TS	Side 1	34.2	57.0
D314	59002-001	DIODE		BAV99W	Side 2	27.2	62.8
D700	59002-001	DIODE		BAV99W	Side 1	33.3	128.7
J101	73101-001	BATTERY CONNECTOR			Side 2	4.4	16.1
J102	73301-001	CONNECTOR 52 8 POL			Side 1	32.1	93.3
J104	73102-001	CONNECTOR 85			Side 2	21.5	2.0
L501	61701-001	FERRITE-BEAD			Side 1	2.1	128.7
L502	61202-470	INDUCTOR	47nH		Side 1	4.2	121.7
L503	53204-150	CAP CER	15pF		Side 1	16.4	117.6
L504	61202-270	INDUCTOR	27nH		Side 1	21.5	117.2
L505	61701-001	FERRITE-BEAD			Side 1	24.3	118.6
L506	61202-180	INDUCTOR	18nH		Side 2	34.7	122.7
L507	61202-180	INDUCTOR	18nH		Side 2	32.1	121.3
L508	61202-100	INDUCTOR	10nH	2%	Side 1	25.1	116.0
L601	61701-001	FERRITE-BEAD			Side 1	21.3	130.2
L602	61701-001	FERRITE-BEAD			Side 1	1.5	131.3
L603	61701-001	FERRITE-BEAD			Side 1	19.6	150.6
L604	61202-270	INDUCTOR	27nH		Side 1	11.8	128.3
L605	61701-001	FERRITE-BEAD			Side 1	16.9	138.6
L701	61301-018	INDUCTOR	1.8nH		Side 1	29.9	133.9
L703	61202-180	INDUCTOR	18nH		Side 1	31.7	131.5
L704	61202-330	INDUCTOR	33nH		Side 1	29.6	137.7
L707	61202-330	INDUCTOR	33nH		Side 2	33.6	152.2
L709	61701-001	FERRITE-BEAD			Side 2	16.2	134.2

## COMPANY CONFIDENTIAL

L710	61202-470	INDUCTOR	47nH		Side 1	33.7	151.7
L711	61110-471	INDUCTOR	0.47nH		Side 2	28.2	148.5
L712	61110-471	INDUCTOR	0.47nH		Side 2	22.6	148.5
L713	61110-561	INDUCTOR	0.56nH		Side 2	13.8	152.1
L714	61202-470	INDUCTOR	47nH		Side 2	3.4	133.6
L715	61701-001	FERRITE-BEAD			Side 2	4.2	154.1
L716	61701-001	FERRITE-BEAD			Side 2	1.4	134.4
L719	61701-001	FERRITE-BEAD			Side 1	27.5	141.8
L720	61110-152	INDUCTOR	1.5uH		Side 2	2.0	151.3
L721	61110-821	INDUCTOR	0.82nH		Side 2	11.2	151.4
L722	61701-001	FERRITE-BEAD			Side 2	26.0	144.3
L723	61202-470	INDUCTOR	47nH		Side 1	32.3	155.3
Q101	69001-001	TRANSISTOR NPN		BC848CW	Side 2	40.1	17.1
Q102	69002-001	TRANSISTOR PNP		BC857BW	Side 2	41.4	13.8
Q103	69002-001	TRANSISTOR PNP		BC857BW	Side 2	40.4	19.9
Q201	69008-001	TRANSISTOR P-MOS		SI3443DV	Side 2	2.4	29.1
Q202	69001-001	TRANSISTOR NPN		BC848CW	Side 2	14.1	75.8
Q203	69002-001	TRANSISTOR PNP		BC857BW	Side 1	21.6	64.3
Q204	69002-001	TRANSISTOR PNP		BC857BW	Side 1	18.2	64.2
Q301	69001-001	TRANSISTOR NPN		BC848CW	Side 1	3.4	66.7
Q302	69007-001	TRANSISTOR N-MOS		TN0200T	Side 1	2.9	75.1
Q304	69001-001	TRANSISTOR NPN		BC848CW	Side 1	39.2	86.2
Q305	69006-001	TRANSISTOR P-MOS		TP0101T	Side 1	38.8	71.6
Q306	69001-001	TRANSISTOR NPN		BC848CW	Side 1	35.4	70.9
Q307	69001-001	TRANSISTOR NPN		BC848CW	Side 1	33.2	65.8
Q308	69001-001	TRANSISTOR NPN		BC848CW	Side 1	25.5	67.4
Q309	69001-001	TRANSISTOR NPN		BC848CW	Side 2	35.9	85.6
Q501	69009-001	TRANSISTOR UHF		BFG10W/X	Side 1	19.4	117.0
Q601	69006-001	TRANSISTOR P-MOS		TP0101T	Side 1	25.7	153.7
Q701	69004-001	TRANSISTOR UHF		BFP420	Side 1	32.5	134.4
Q702	69005-001	GaAs Dual Gate FET		CF739	Side 2	30.2	151.9

## COMPANY CONFIDENTIAL

Q703	69003-001	TRANSISTOR RF NPN				BFR92AW	Side 2	6.6	149.5
Q704	69003-001	TRANSISTOR RF NPN				BFR92AW	Side 2	9.9	147.7
Q705	69003-001	TRANSISTOR RF NPN				BFR92AW	Side 2	3.1	128.5
R101	64301-101	RES CHIP	100R	+/-1%	0.1W		Side 2	15.7	7.0
R102	64301-101	RES CHIP	100R	+/-1%	0.1W		Side 2	17.0	7.0
R103	64301-101	RES CHIP	100R	+/-1%	0.1W		Side 2	18.3	7.0
R104	64301-101	RES CHIP	100R	+/-1%	0.1W		Side 2	19.5	7.0
R105	64301-101	RES CHIP	100R	+/-1%	0.1W		Side 2	20.8	7.0
R106	64301-101	RES CHIP	100R	+/-1%	0.1W		Side 2	22.1	7.0
R107	64301-100	RES CHIP	10R	+/-1%	0.1W		Side 2	23.4	7.0
R108	64301-101	RES CHIP	100R	+/-1%	0.1W		Side 2	24.6	7.0
R109	64301-101	RES CHIP	100R	+/-1%	0.1W		Side 2	27.0	7.0
R110	64301-104	RES CHIP	100k	+/-1%	0.1W		Side 2	7.9	34.0
R111	64301-474	RES CHIP	470k	+/-1%	0.1W		Side 2	30.0	93.6
R112	64301-104	RES CHIP	100k	+/-1%	0.1W		Side 2	29.6	7.0
R113	64301-104	RES CHIP	100k	+/-1%	0.1W		Side 2	16.3	72.6
R114	64301-103	RES CHIP	10k	+/-1%	0.1W		Side 1	37.7	62.1
R115	64301-103	RES CHIP	10k	+/-1%	0.1W		Side 2	42.2	17.1
R116	64301-104	RES CHIP	100k	+/-1%	0.1W		Side 2	41.4	11.6
R117	64301-104	RES CHIP	100k	+/-1%	0.1W		Side 2	39.5	12.1
R118	64301-104	RES CHIP	100k	+/-1%	0.1W		Side 2	2.3	34.7
R119	64301-223	RES CHIP	22k	+/-1%	0.1W		Side 2	8.0	31.6
R120	64301-102	RES CHIP	1k0	+/-1%	0.1W		Side 1	40.1	63.1
R121	64301-102	RES CHIP	1k0	+/-1%	0.1W		Side 2	39.5	14.4
R122	64301-000	RES CHIP	0R				Side 2	39.9	30.9
R201	64301-471	RES CHIP	470R	+/-1%	0.1W		Side 2	4.9	29.7
R202	64301-471	RES CHIP	470R	+/-1%	0.1W		Side 2	6.2	29.8
R203	64301-564	RES CHIP	560k	+/-1%	0.1W		Side 2	2.7	31.6
R204	64301-224	RES CHIP	220k	+/-1%	0.1W		Side 2	14.5	73.8
R205	64301-471	RES CHIP	470R	+/-1%	0.1W		Side 2	7.5	71.2
R207	64301-224	RES CHIP	220k	+/-1%	0.1W		Side 2	16.4	75.9

## COMPANY CONFIDENTIAL

R208	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 2	26.7	76.0
R209	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	24.7	76.3
R210	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	23.4	76.2
R211	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	27.4	70.6
R212	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 1	21.5	99.6
R213	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 1	20.3	99.6
R215	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 2	15.3	64.9
R216	64301-224	RES CHIP	220k	+/-1%	0.1W	Side 1	20.6	62.1
R217	64301-224	RES CHIP	220k	+/-1%	0.1W	Side 1	23.0	62.2
R218	64301-224	RES CHIP	220k	+/-1%	0.1W	Side 1	17.1	66.4
R219	64301-224	RES CHIP	220k	+/-1%	0.1W	Side 1	18.3	67.8
R220	64301-473	RES CHIP	47k	+/-1%	0.1W	Side 1	20.0	65.7
R221	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 1	23.7	64.1
R222	64301-224	RES CHIP	220k	+/-1%	0.1W	Side 2	31.1	80.5
R223	64301-000	RES CHIP	0R			Side 2	28.8	79.2
R224		NOTFITTED				Side 2	36.5	76.6
R238	64301-393	RES CHIP	39k	+/-1%	0.1W	Side 2	35.3	70.0
R239	67101-001	RES CHIP	10k	+/-1%	0.1W	Side 2	36.6	70.0
R240	64301-100	RES CHIP	10R	+/-1%	0.1W	Side 2	27.8	68.7
R241	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 2	30.2	68.4
R242	64301-683	RES CHIP	68k	+/-1%	0.1W	Side 2	28.9	68.7
R243	64301-114	RES CHIP	110k	+/-1%	0.1W	Side 2	34.1	70.0
R244	64301-223	RES CHIP	22k	+/-1%	0.1W	Side 1	10.5	65.7
R245	64301-223	RES CHIP	22k	+/-1%	0.1W	Side 1	10.5	64.5
R246	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	1.6	65.2
R247	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	2.9	65.2
R248	64301-000	RES CHIP	0R			Side 1	8.9	98.8
R249	64301-000	RES CHIP	0R			Side 2	32.8	70.0
R300	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 1	29.7	89.1
R301	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 1	13.9	97.5
R302	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 2	29.8	101.6
R303	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 2	34.8	101.1

## COMPANY CONFIDENTIAL

R304	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 2	34.2	97.2
R305	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 1	12.9	93.2
R306	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 2	32.5	101.2
R307	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 1	38.7	66.5
R308	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 1	37.3	87.4
R309	64301-102	RES CHIP	1k0	+/-1%	0.1W	Side 1	36.5	85.1
R310	64301-471	RES CHIP	470R	+/-1%	0.1W	Side 2	26.3	84.0
R311	64301-224	RES CHIP	220k	+/-1%	0.1W	Side 1	32.7	71.6
R312	64301-000	RES CHIP	0R			Side 1	35.0	87.6
R313	64301-474	RES CHIP	470k	+/-1%	0.1W	Side 1	32.2	80.1
R314	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 1	38.9	69.6
R315	64301-102	RES CHIP	1k0	+/-1%	0.1W	Side 2	36.2	93.2
R316	64301-224	RES CHIP	220k	+/-1%	0.1W	Side 1	33.1	69.7
R317	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 1	31.7	79.0
R318	64301-471	RES CHIP	470R	+/-1%	0.1W	Side 1	9.7	101.1
R319	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 1	13.0	73.3
R320	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	16.3	71.6
R321	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	15.6	68.8
R322	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	18.9	70.9
R323	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	19.5	68.4
R324	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	20.4	70.9
R325	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	8.0	72.3
R326	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	9.2	73.2
R327	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	10.7	70.8
R328	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	5.2	77.0
R329	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 1	17.1	99.4
R330	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 1	6.2	67.1
R331	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 1	1.8	70.1
R332	64301-472	RES CHIP	4k7	+/-1%	0.1W	Side 1	5.1	63.9
R333	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 1	1.8	72.4
R334	64301-391	RES CHIP	390k	+/-1%	0.1W	Side 2	26.4	97.5
R335	64301-391	RES CHIP	390k	+/-1%	0.1W	Side 2	28.7	99.7

## COMPANY CONFIDENTIAL

R336	64301-152	RES CHIP	1k5	+/-1%	0.1W	Side 1	25.6	70.3
R337	64301-152	RES CHIP	1k5	+/-1%	0.1W	Side 1	23.0	70.9
R338	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 1	21.8	70.9
R339	64301-180	RES CHIP	18R	+/-1%	0.1W	Side 1	31.3	66.2
R340	64301-180	RES CHIP	18R	+/-1%	0.1W	Side 1	23.6	68.2
R341	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 1	29.6	71.6
R342	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 1	30.7	70.1
R343	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 1	38.1	83.1
R344	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 1	31.8	74.2
R345	64301-102	RES CHIP	1k0	+/-1%	0.1W	Side 1	32.5	82.3
R346	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 2	33.2	86.6
R347	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 2	36.2	82.6
R348	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 1	33.0	85.6
R349	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 1	36.5	83.9
R350	64301-333	RES CHIP	33k	+/-1%	0.1W	Side 2	25.3	86.6
R351	64301-100	RES CHIP	10R	+/-1%	0.1W	Side 2	28.9	85.9
R352	64301-100	RES CHIP	10R	+/-1%	0.1W	Side 2	36.2	81.3
R354	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	29.0	83.4
R355	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 1	27.6	90.2
R356	64301-471	RES CHIP	470R	+/-1%	0.1W	Side 2	20.8	81.5
R357	64301-471	RES CHIP	470R	+/-1%	0.1W	Side 1	16.2	93.5
R380	67101-001	RES CHIP	10k	+/-1%		Side 1	32.6	84.5
R381	67201-001	RES-CHIP Voltage Suppressor 9Vwm				Side 1	40.9	68.7
R401	64301-102	RES CHIP	1k0	+/-1%	0.1W	Side 2	2.5	87.5
R402	64301-222	RES CHIP	2k2	+/-1%	0.1W	Side 2	1.5	85.4
R403	64301-153	RES CHIP	15k	+/-1%	0.1W	Side 2	1.7	83.4
R404	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 2	9.4	84.8
R405	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	8.2	84.1
R406	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	7.0	84.1
R407	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 2	12.6	102.7
R408	64301-224	RES CHIP	220k	+/-1%	0.1W	Side 2	12.6	101.6

## COMPANY CONFIDENTIAL

R410	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	17.0	85.3
R411	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 2	18.6	85.4
R412	64301-100	RES CHIP	10R	+/-1%	0.1W	Side 2	1.3	75.3
R413	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 2	1.5	80.9
R414	64301-104	RES CHIP	100k	+/-1%	0.1W	Side 2	1.0	77.7
R420	64301-105	RES CHIP	1M0	+/-1%	0.1W	Side 1	10.7	98.4
R421	64301-473	RES CHIP	47k	+/-1%	0.1W	Side 1	11.9	98.4
R422	64301-473	RES CHIP	47k	+/-1%	0.1W	Side 1	11.4	95.8
R423	64301-332	RES CHIP	3k3	+/-1%	0.1W	Side 1	10.4	93.2
R424	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 1	11.0	91.3
R425	64301-563	RES CHIP	56k	+/-1%	0.1W	Side 2	2.2	90.6
R429	64301-100	RES CHIP	10R	+/-1%	0.1W	Side 1	9.6	76.9
R430	64301-103	RES CHIP	10R	+/-1%	0.1W	Side 2	4.7	102.6
R431	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	5.7	99.5
R432	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	9.1	101.8
R433	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	5.9	102.8
R434	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	10.8	72.5
R435	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 2	13.8	81.5
R440		NOTFITTED				Side 2	12.8	73.2
R501	64301-821	RES CHIP	820R	+/-1%	0.1W	Side 1	13.9	119.0
R502	64301-152	RES CHIP	1k5	+/-1%	0.1W	Side 1	17.2	119.1
R503	64301-221	RES CHIP	220R	+/-1%	0.1W	Side 1	22.9	116.6
R504		NOTFITTED				Side 1	19.8	119.6
R505	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 2	8.4	116.7
R506	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	10.2	115.3
R603	64301-154	RES CHIP	150k	+/-1%	0.1W	Side 1	23.8	136.4
R604	64301-822	RES CHIP	8k2	+/-1%	0.1W	Side 1	17.7	143.9
R605	64301-333	RES CHIP	33k	+/-1%	0.1W	Side 1	12.7	144.0
R606	64301-221	RES CHIP	220R	+/-1%	0.1W	Side 1	15.5	130.8
R607	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	14.9	127.9
R608	64301-180	RES CHIP	18R	+/-1%	0.1W	Side 1	15.5	129.6
R609	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	16.2	127.9

## COMPANY CONFIDENTIAL

R610		NOTFITTED				Side 1	17.3	141.8
R611	64301-153	RES CHIP	15k	+/-1%	0.1W	Side 1	2.5	150.9
R612	64301-154	RES CHIP	150k	+/-1%	0.1W	Side 1	6.6	149.3
R613	64301-221	RES CHIP	220R	+/-1%	0.1W	Side 1	19.3	153.1
R614	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	19.1	152.0
R615	64301-180	RES CHIP	18R	+/-1%	0.1W	Side 1	19.3	155.0
R616	64301-331	RES CHIP	330R	+/-1%	0.1W	Side 1	22.5	155.0
R617	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 1	25.0	151.5
R618	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 1	27.3	151.4
R619	64301-472	RES CHIP	4k7	+/-1%	0.1W	Side 1	23.9	140.3
R620	64301-472	RES CHIP	4k7	+/-1%	0.1W	Side 1	22.1	141.5
R701	64301-822	RES CHIP	8k2	+/-1%	0.1W	Side 1	35.7	131.4
R702	64301-153	RES CHIP	15k	+/-1%	0.1W	Side 1	30.5	128.2
R703	64301-823	RES CHIP	82k	+/-1%	0.1W	Side 1	28.4	131.2
R704	64301-101	RES CHIP	100R	+/-1%	0.1W	Side 1	27.0	136.7
R705	64301-391	RES CHIP	390R	+/-1%	0.1W	Side 1	29.6	139.1
R706	64301-470	RES CHIP	47R	+/-1%	0.1W	Side 1	30.6	135.7
R707	64301-000	RES CHIP	0R			Side 1	32.1	148.8
R708		NOTFITTED				Side 1	34.0	148.3
R709		NOTFITTED				Side 1	33.9	149.5
R710	64301-471	RES CHIP	470R	+/-1%	0.1W	Side 1	33.6	137.6
R711	64301-120	RES CHIP	12R	+/-1%	0.1W	Side 1	33.1	139.4
R712	64301-471	RES CHIP	470R	+/-1%	0.1W	Side 1	31.4	140.2
R713	64301-683	RES CHIP	68k	+/-1%	0.1W	Side 2	6.6	125.3
R714	64301-564	RES CHIP	560k	+/-1%	0.1W	Side 2	18.1	132.5
R715	64301-154	RES CHIP	150k	+/-1%	0.1W	Side 2	10.9	124.0
R716	64301-154	RES CHIP	150k	+/-1%	0.1W	Side 2	15.3	123.7
R717	64301-123	RES CHIP	12k	+/-1%	0.1W	Side 2	16.0	121.9
R718	64301-154	RES CHIP	150k	+/-1%	0.1W	Side 2	10.0	122.8
R722	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	6.1	152.8
R723	64301-223	RES CHIP	22k	+/-1%	0.1W	Side 2	8.1	153.6
R724	64301-333	RES CHIP	33k	+/-1%	0.1W	Side 2	9.4	153.6

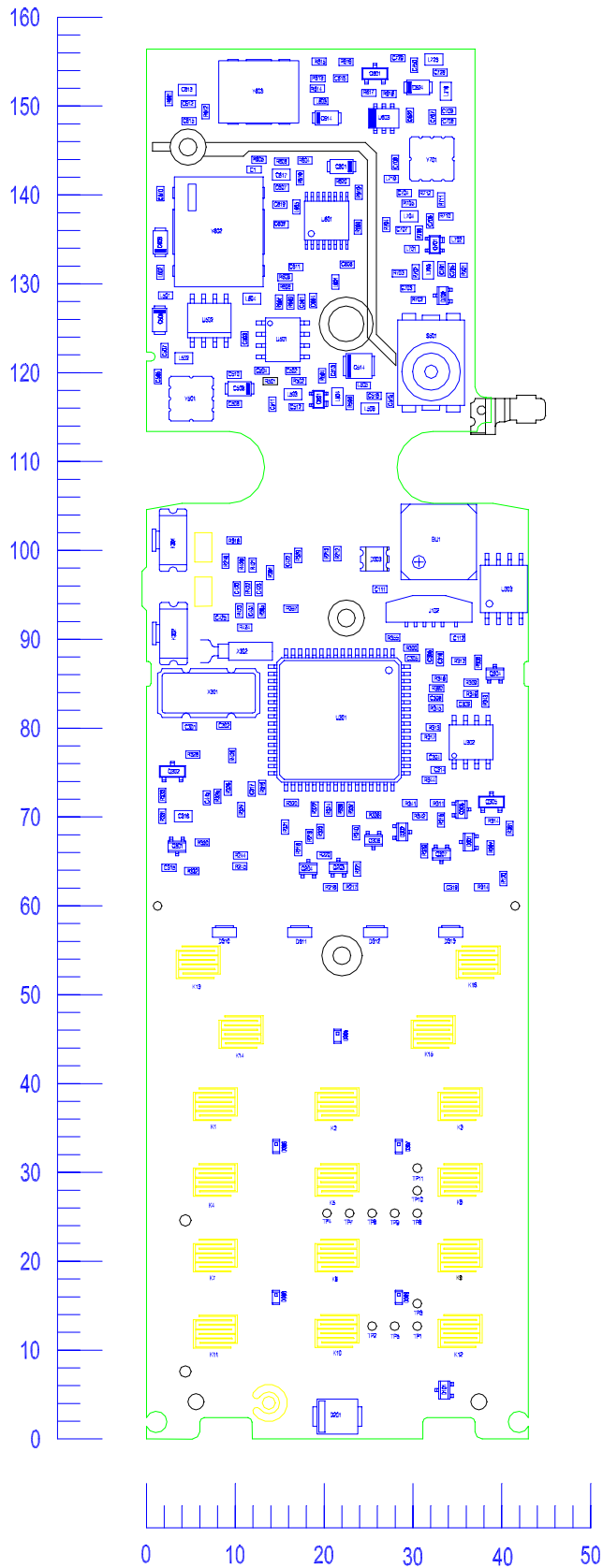


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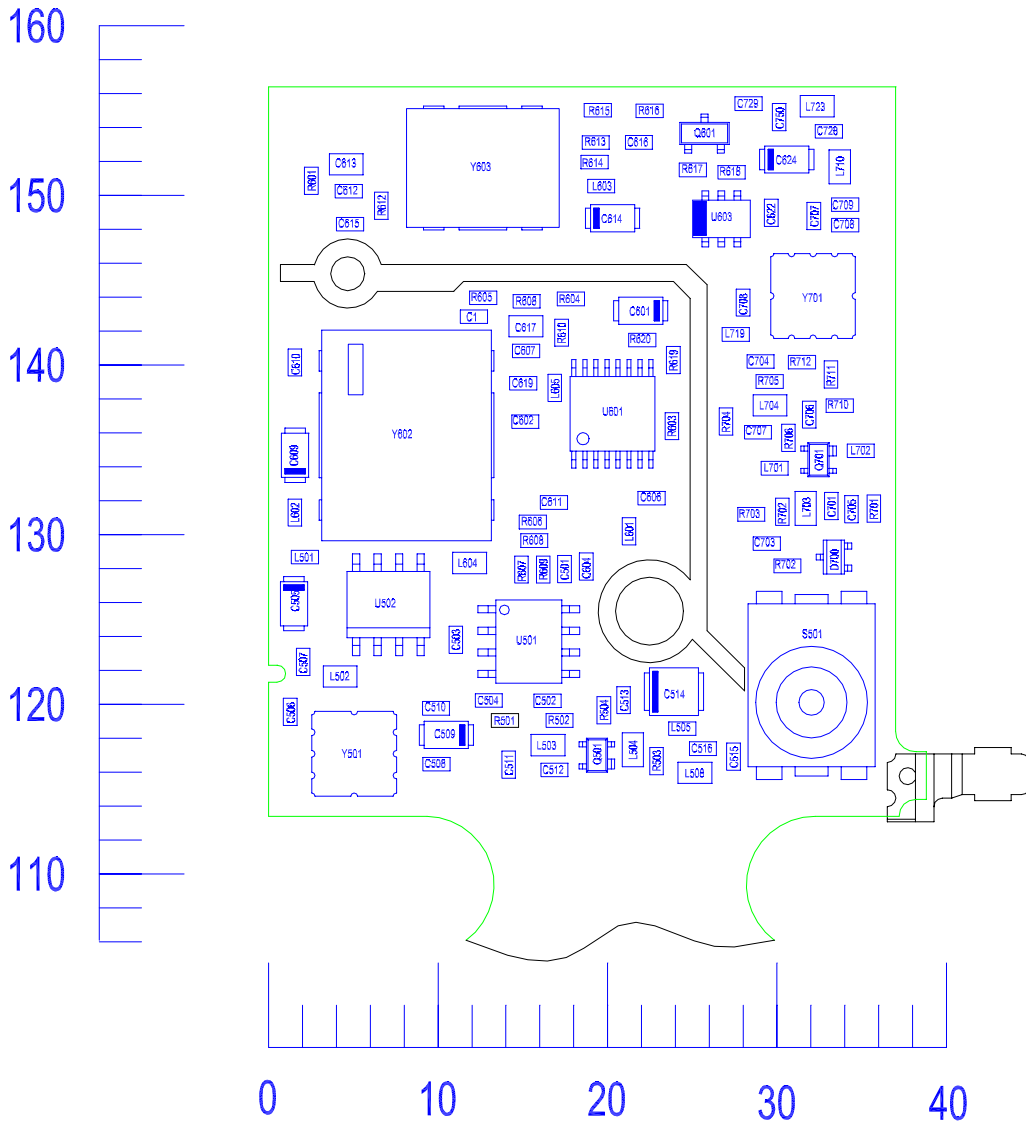
R725	64301-102	RES CHIP	1k0	+/-1%	0.1W	Side 2	12.9	147.0
R726	64301-102	RES CHIP	1k0	+/-1%	0.1W	Side 2	2.4	154.0
R727	64301-393	RES CHIP	39k	+/-1%	0.1W	Side 2	2.0	132.2
R728	64301-153	RES CHIP	15k	+/-1%	0.1W	Side 2	3.3	124.4
R729	64301-102	RES CHIP	1k0	+/-1%	0.1W	Side 2	2.1	123.7
R730	64301-102	RES CHIP	1k0	+/-1%	0.1W	Side 2	4.3	132.2
R731	64301-222	RES CHIP	2k2	+/-1%	0.1W	Side 2	27.3	153.0
R732	64301-391	RES CHIP	390R	+/-1%	0.1W	Side 2	32.3	149.2
R733	64301-103	RES CHIP	10k	+/-1%	0.1W	Side 2	6.4	134.1
R734	64301-470	RES CHIP	47R	+/-1%	0.1W	Side 1	35.0	135.0
S0301	74001-001	SWITCH				Side 1	3.0	101.1
S0302	74001-001	SWITCH				Side 1	3.0	90.7
S0501	73103-001	CONNECTOR 12 COAX				Side 1	32.0	121.1
U201	51101-001	IC-PWR			TPS9104IPTR	Side 2	9.7	65.8
U202	52201-001	IC DIG 74VHC595MTC			74VHC595MTC	Side 2	22.3	72.0
U203	50001-001	IC-REG INV			MAX868EUB	Side 2	33.8	66.8
U204	51103-001	IC-REG LDO 5.0V 0,25-1A			TPS7250QD	Side 2	32.4	76.4
U301	52001-001	IC-MICROCONTR. 8-BIT			ATMEGA103L-4A1	Side 1	21.7	80.9
U302	52101-001	EEPROM 8k x 8 bits			AT24C64N-10SI-2.7	Side 1	36.5	78.4
U303	52901-001	IC-MICROCONTR Programmed			52901-001	Side 1	40.2	95.7
U401	51202-001	IC AUDIO PROCESSOR			AK2339	Side 2	12.1	93.2
U501	49201-001	IC ATTENUATOR VARIABLE			AT113	Side 1	15.3	123.7
U502	49301-001	IC-AMPL 3V PWR			MRFIC2006	Side 1	7.1	125.9
U503	51302-001	IC-OPAMP			MAX4165EUK-T	Side 2	11.4	118.4
U601	49001-001	IC-DUAL SYNTHESISER 1,1G/			LMX2335LTM	Side 1	20.3	137.1
U602	51102-001	IC-REG LDO 3.0V			TK11230BMCL	Side 2	23.2	119.1
U603	51102-001	IC-REG LDO 3.0V			TK11230BMCL	Side 1	26.7	148.6

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U701	49101-001	IC-FM RECEIVER LQFP-32	MC13150FTB	Side 2	11.1	129.6
X0301	58001-001	CRYSTAL 4.80 MHz CS20		Side 1	7.0	84.0
X0302	58901-001	MS1V-TK 32.768KHZ 12.5PF		Side 1	10.7	88.7
Y501	60905-001	FILTER-SAW TX		Side 1	5.0	117.1
Y502	60904-001	FILTER-SAW RX		Side 2	33.3	126.7
Y503	60905-001	FILTER-SAW TX		Side 2	31.4	117.2
Y601	63901-001	OSC-VC/TCXO14.85MHZ, Sa		Side 2	29.8	136.2
Y602	63101-001	VCO TX NORDIC 12,4x10MM		Side 1	8.1	135.8
Y603	63102-001	OSC-RX VCO 509MHZ, NORDIC		Side 1	12.7	151.7
Y701	60904-001	FILTER-SAW RX		Side 1	32.1	144.1
Y702	60002-001	FILTER-IF 450KHZ		Side 2	13.2	141.6
Y703	60002-001	FILTER-IF 450KHZ		Side 2	20.6	139.9
Y704	60001-001	FILTER-IF 45MHZ 4-POL		Side 2	18.4	150.8

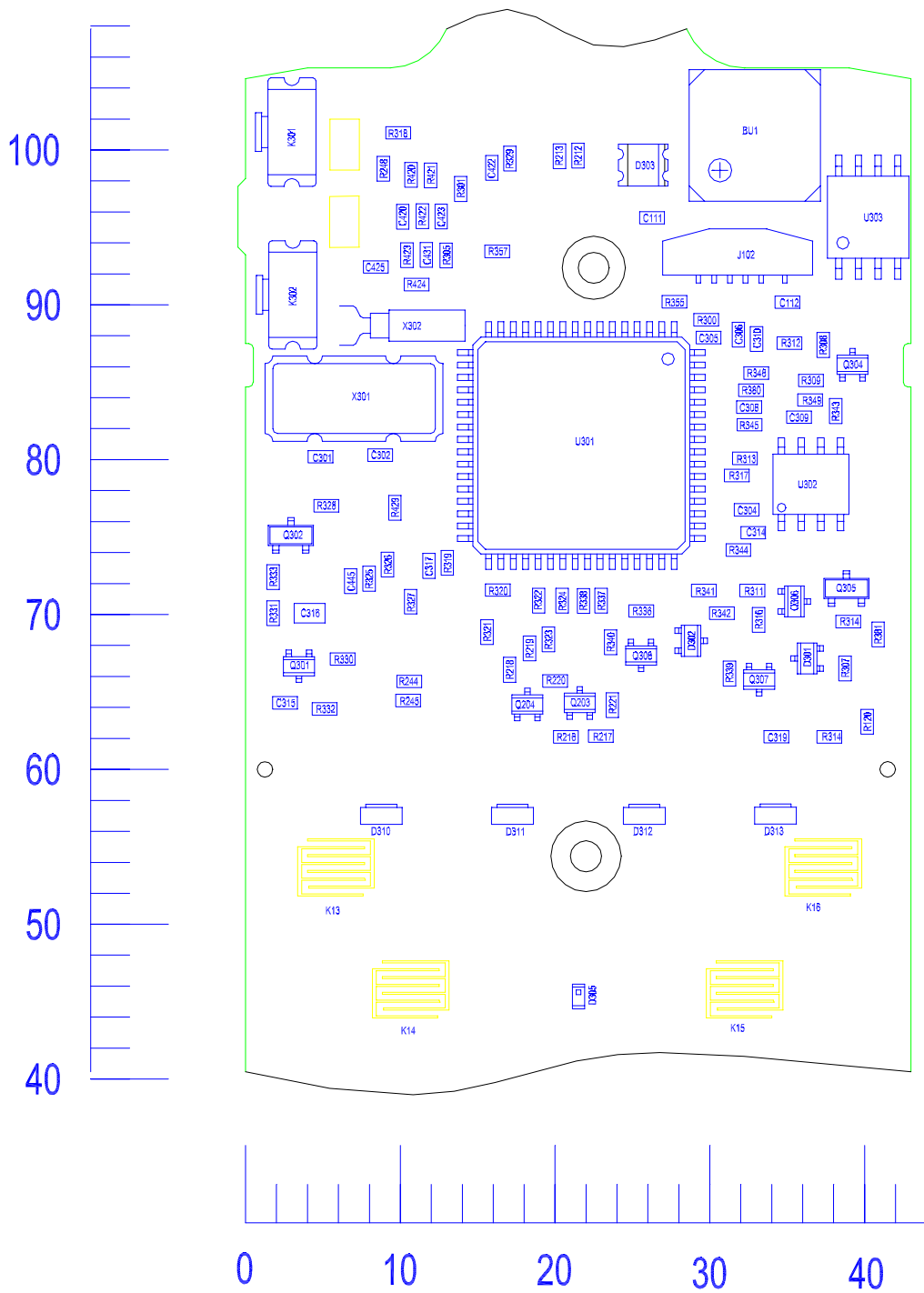


**PCB Assembly**  
**Side 1**

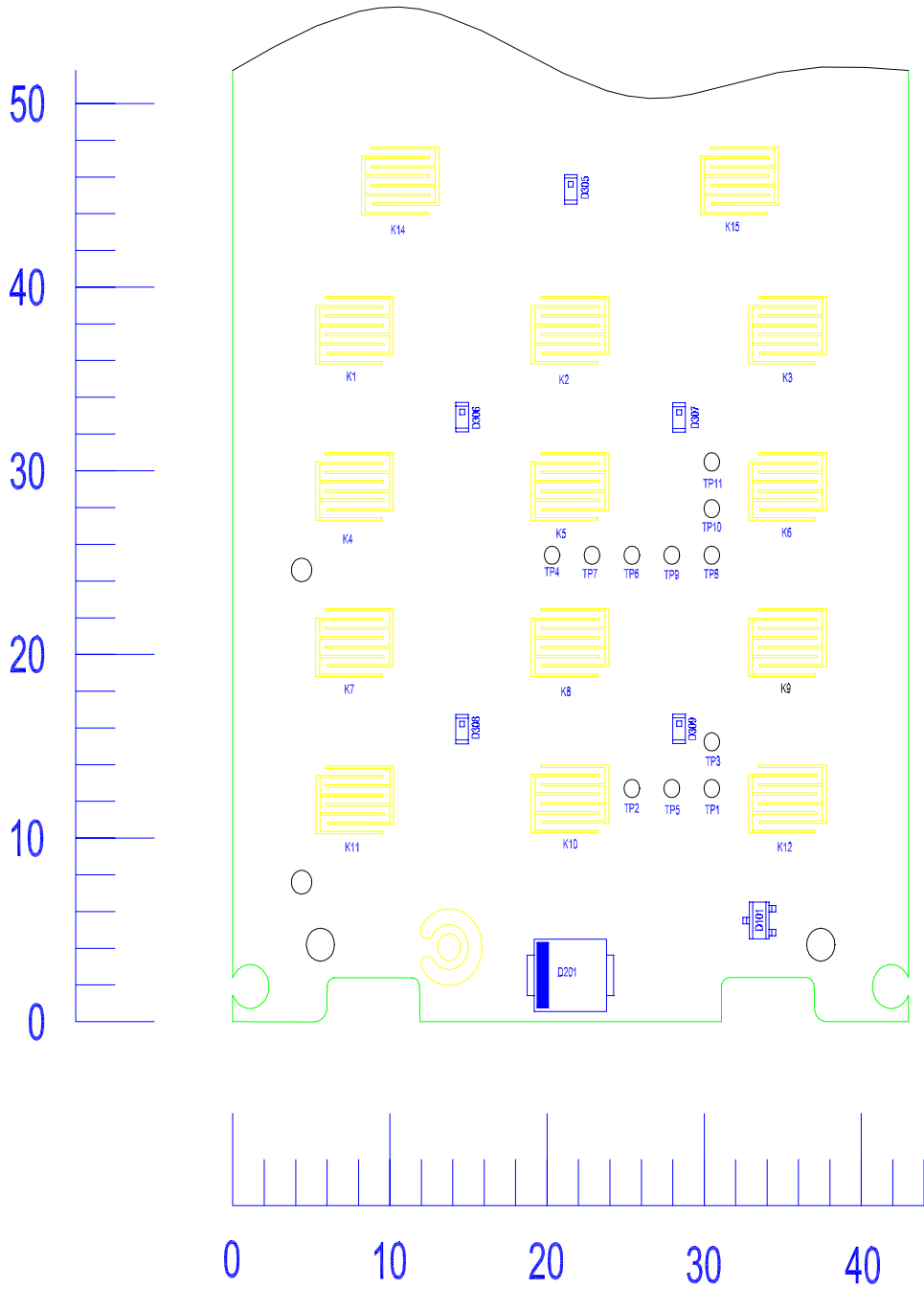


# PCB Assembly

## Side 1 - Part 1

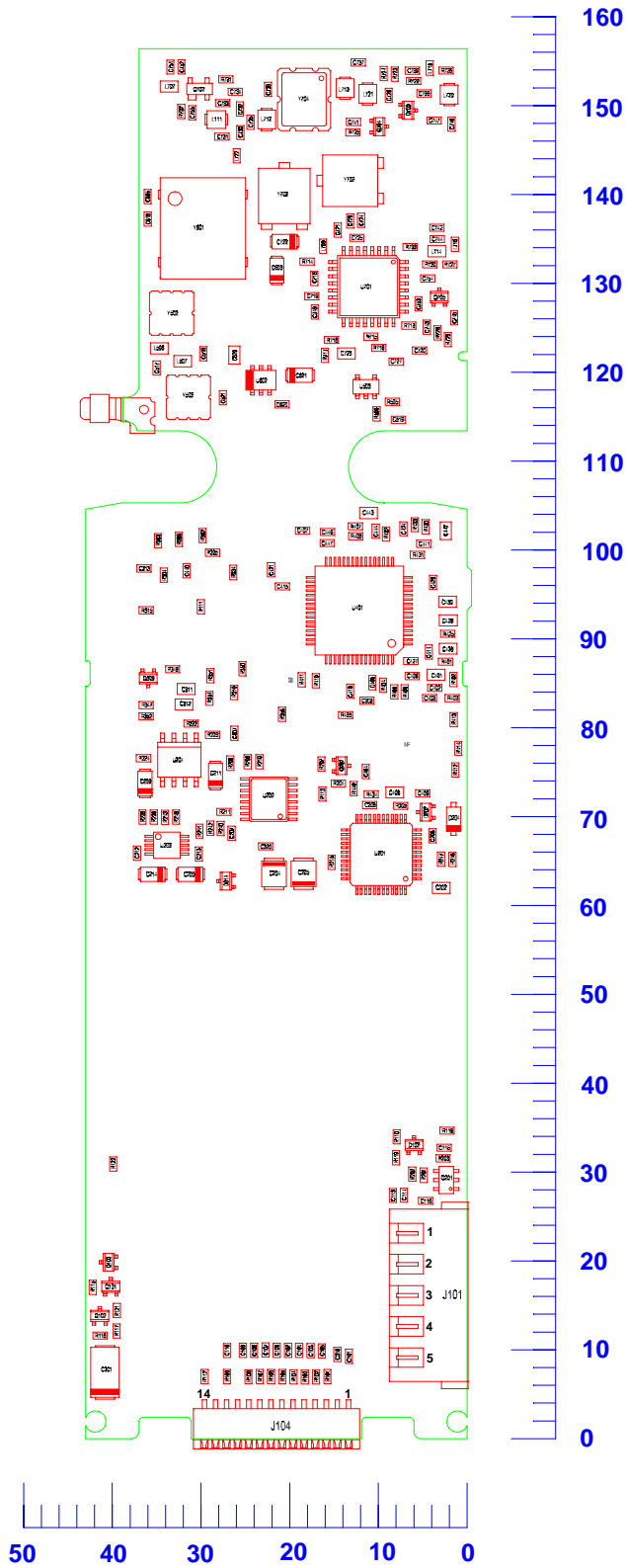


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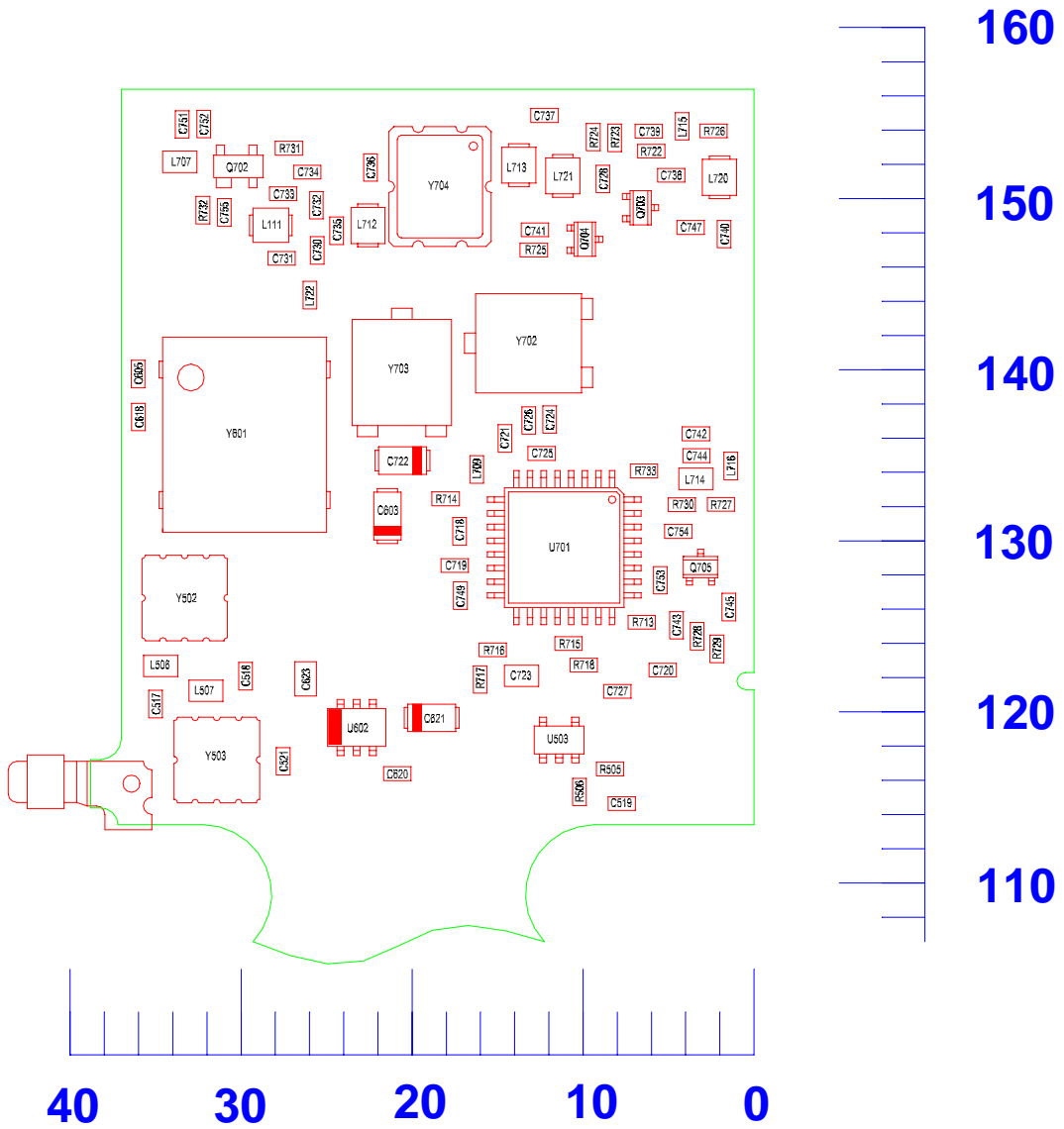


# PCB Assembly

## Side 1 - Part 3



# PCB Assembly Side 2



# PCB Assembly Side 2 - Part 1



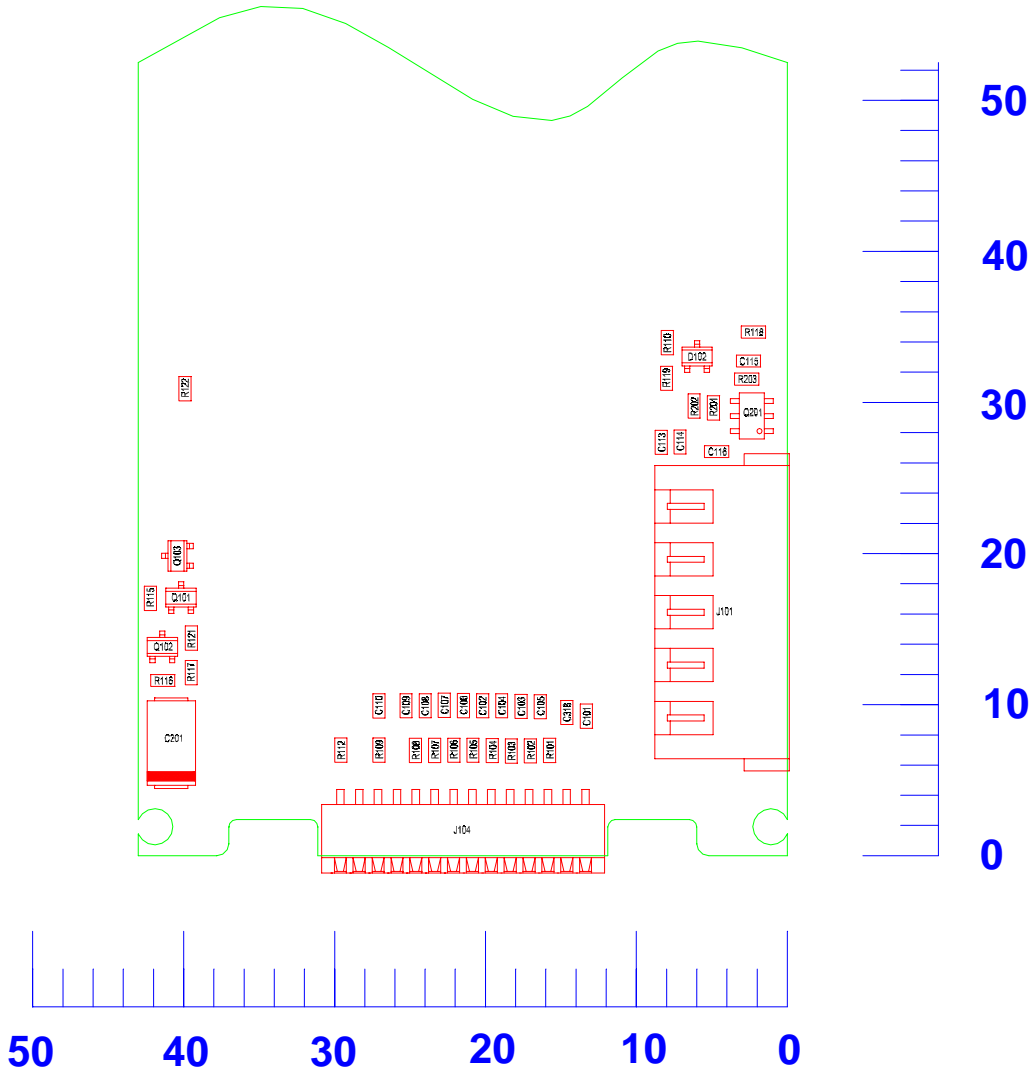


# PCB Assembly

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## Side 2 - Part 2

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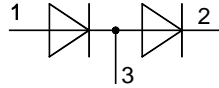
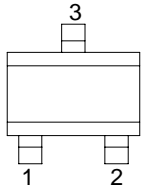
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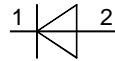
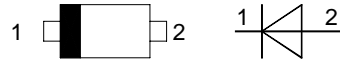
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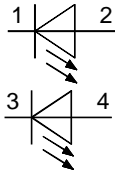
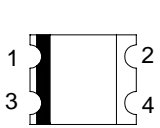
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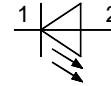
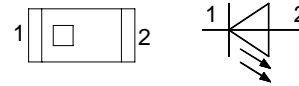
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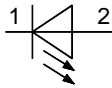
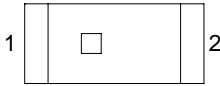
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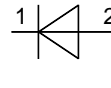
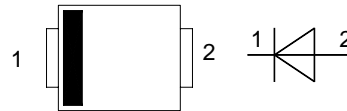
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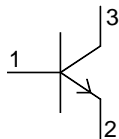
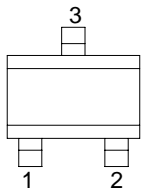
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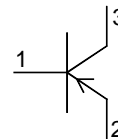
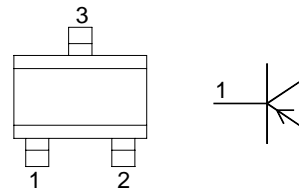
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**SMB**



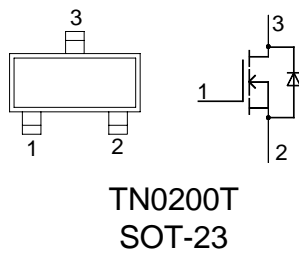
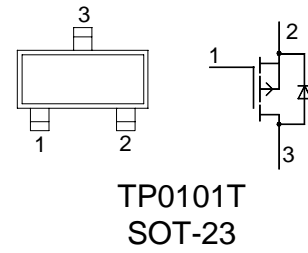
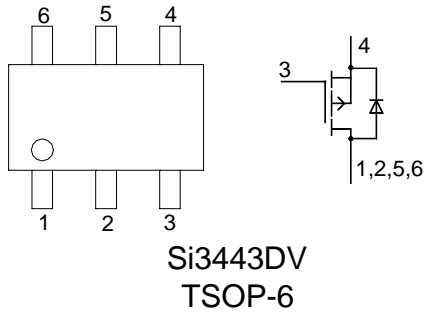
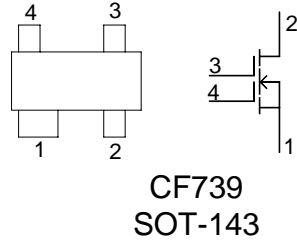
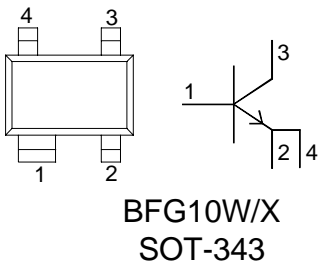
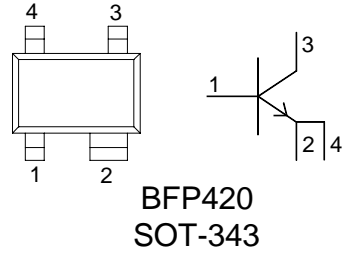
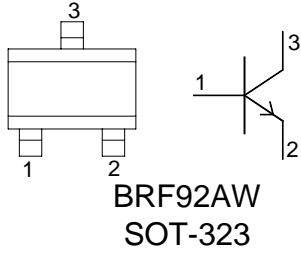
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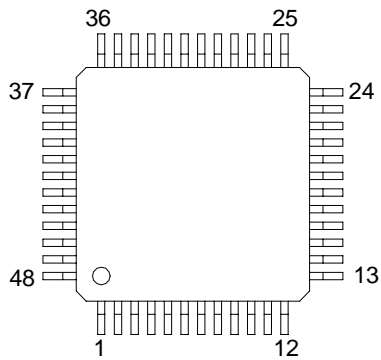
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**Device Pin Outs**  
**Sheet 1 of 5**

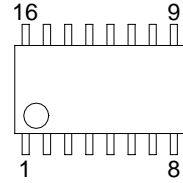
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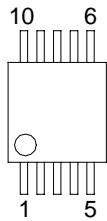
**Device Pin Outs**  
**Sheet 2 of 5**



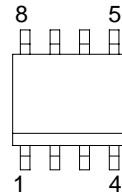
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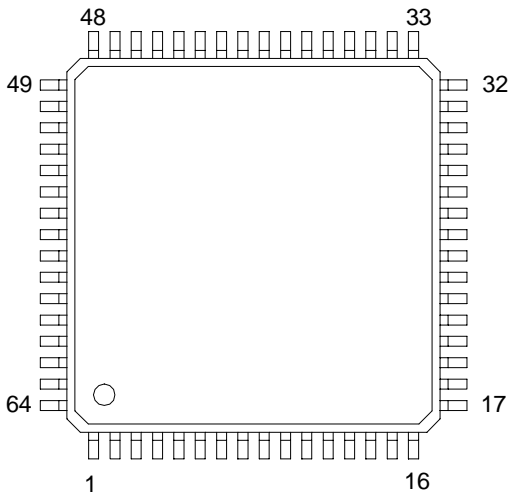
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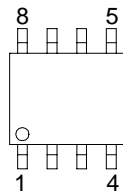
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R-PDS0-G8

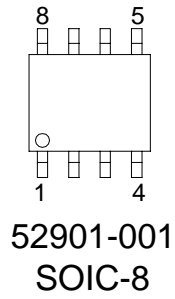


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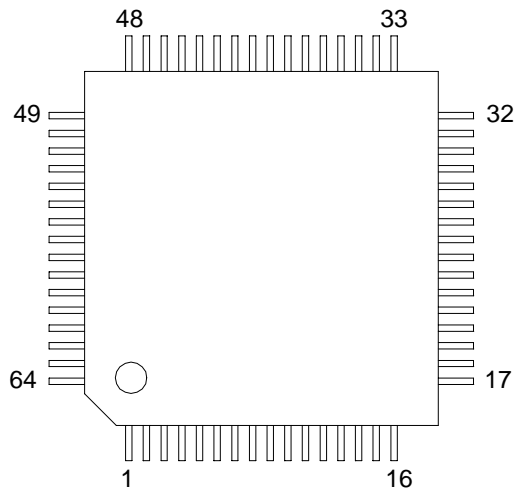


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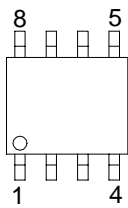
**Device Pin Outs**  
**Sheet 3 of 5**



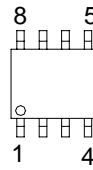
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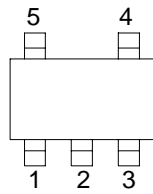
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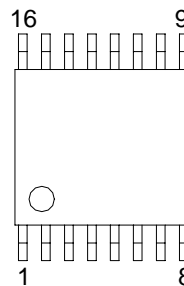
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MRFIC2006  
SO-8

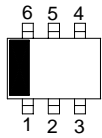


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SOT-23-5

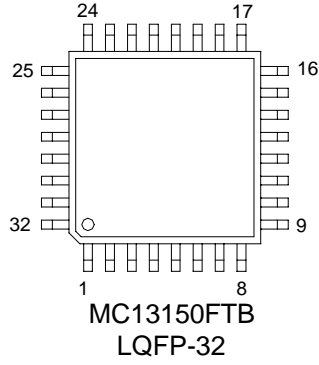


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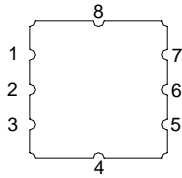
**Device Pin Outs**  
**Sheet 4 of 5**



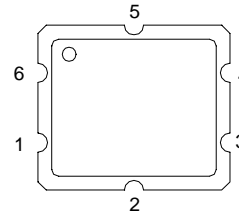
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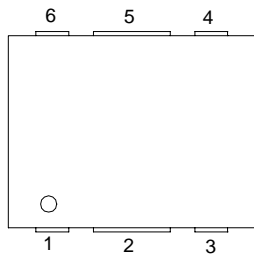
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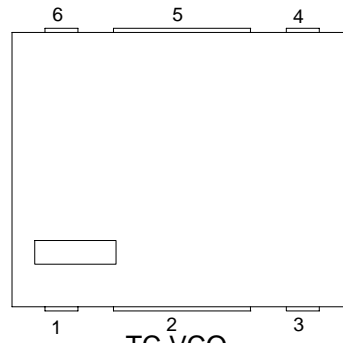
SAW Filter



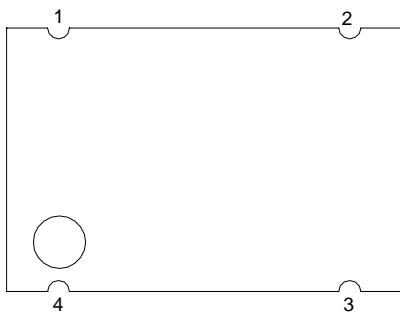
45 MHz Filter



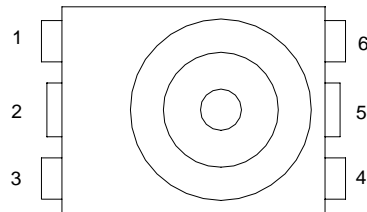
RX VCO



TC VCO



VCTCXO



Antenna Connector

**Device Pin Outs**  
**Sheet 5 of 5**

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**14      Ordering Spare Parts**

Not yet written

**15      Returning Units/Assemblies to Tellit Communications  
Limited**

Not yet written

**16      Service Reports**

Not yet written



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## 17 A66 BLOCK DIAGRAM DESCRIPTION

### Introduction

When reading this section reference should be made to the Block Diagram Figure 17-1.

#### 17.1 Transmitter

##### Specification

Direct generation of the final transmit frequency from ganged synthesiser U601.  
Frequency modulation by means of the modulation input to the TX VCO.

##### Glossary

##### VCO (Y602)

Produces the TX carrier frequency. Outputs a power level of -8 dBm.

##### Attenuator (U501)

Provides gain control, under command of the microprocessor

##### Gain Controlled Amplifier (U502)

Provides power gain and gain control under command of the microprocessor.

##### Band Pass Filter (Y501)

Attenuates noise side bands of the TX VCO occurring within the RX frequency band

##### Power Amplifier (Q501)

Provides power gain to a level of approximately 200 mW

##### Duplexer (Y503 & Y502)

Comprises 2 band pass filters. Y503 passes the TX band of frequencies. Y502 passes the RX band of frequencies. Thus the transmitter and receiver may share a common antenna.

#### 17.2 Receiver

##### Specification

Dual conversion superhetrodyne. Uses Surface Acoustic Wave (SAW) filters at the receive frequency, a quartz filter at the 1<sup>st</sup> IF frequency and ceramic filters at the 2<sup>nd</sup> IF frequency. 1<sup>st</sup> local oscillator frequency generated by means of a synthesiser under the command of the microprocessor. 2<sup>nd</sup> Local Oscillator generated from the 14.85 MHz VTXCO by means of a X3 frequency multiplier stage.

##### Glossary

##### LNA (Q701)

Provides low noise amplification of the receive band of frequencies

##### Band Pass Filter (Y701)

Attenuates received signals out side of the receive band of Frequencies.

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## 1<sup>st</sup> Mixer (Q702)

Down converts the selected receive frequency to the 1<sup>st</sup> IF frequency of 45 MHz. Local oscillator injection frequency is 45 MHz above the selected receive channel.

## 1<sup>st</sup> IF Band Pass Filter (Y704)

Selects the 45 MHz component of the output of the 1<sup>st</sup> Mixer.  
Provides adjacent channel rejection.

## 1<sup>st</sup> IF Amplifier (Q703 & Q704)

Provides low noise amplification of the 1<sup>st</sup> IF.

## 2<sup>nd</sup> Mixer, 2<sup>nd</sup> IF Amplifier, Limiter, Demodulator & RSSI (U701)

Down converts the 1<sup>st</sup> IF signal to the 2<sup>nd</sup> IF frequency of 450 kHz.  
Provides further adjacent channel rejection by means of Band Pass Filter Y703.

2<sup>nd</sup> IF Amplifier Provides gain at 2<sup>nd</sup> IF frequency with adjacent channel rejection by means of Band Pass filter Y704.  
Provides amplitude limiter in order to remove amplitude modulation from the received signal and provide constant signal amplitude to the Demodulator stage.  
Demodulator recovers the audio signal from the frequency modulated received carrier.  
Receive Signal Strength Indicator (RSSI) produces a dc level proportional to the received signal carrier level.

## 2<sup>nd</sup> Local Oscillator Frequency Multiplier (Q705)

Multiplies the VTXCO frequency of 14.85 MHz by a factor of 3 so as to produce the required 2<sup>nd</sup> local oscillator frequency of 44.55 MHz.

## 17.3 Synthesiser

### RX

Runs at a frequency of 45 MHz above the required receive frequency. The VCO's output frequency is controlled by a control voltage derived from the RX Phased Locked Loop (RX PLL) via a low pass filter. A sample of the RX VCO output is fed to the Phase Lock Loop (RX PLL).  
The PLL compares the VCO frequency, divided down by a ratio determined on command from the microprocessor, with the frequency of the Voltage Tuned Crystal Oscillator (VTXCO) and produces a control voltage.  
The control voltage causes the VCO to phase lock to the VTXCO frequency.

### TX

Runs at the transmitter final frequency. The VCO's output frequency is controlled by a control voltage derived from the TX PLL via a low pass filter. A sample of the TX VCO output is fed to the TX PLL.  
The TX PLL compares the VCO frequency, divided down by a ratio determined on command from the microprocessor, with the frequency of the VTXCO and produces a control voltage.  
The control voltage causes the VCO to phase lock to the VTXCO frequency.  
A separate modulation input to the VCO, derived from the TX Base Band circuit, produces frequency modulation of the VCO output.

### Control

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Interfaces to the SPI buss so as to enable control of the synthesiser by the microprocessor.

## +3VIF Regulator

A 3V linear voltage regulator U603 provides a 3 V dc supply used to power the IF Demodulator (U401). This regulator is enabled under microprocessor control via line 3V\_IF\_EN.

## +3VRX Switch

A MOSFET switch (Q602) enabled under control of the microprocessor provides +3V to power the receiver front-end.

## +3VTX

A 3V linear voltage regulator U602 provides 3 V dc supplies used to power the low-level stages of the transmitter. ). This regulator is enabled under microprocessor control via line 3V\_TX\_EN.

## 17.4 BaseBand Processor

### Receive Audio Path

Accepts audio from the demodulator: -

- 1/ Provides a -6-dB/octave de-emphasis over the audio frequency range of 300 Hz to 3.4 kHz.
- 2/ Provides band pass filter having a pass band of 300 Hz to 3.4 kHz.
- 3/ Provides an expander selectable under control of the microprocessor. The expander provides a 1:2 expansion of the RX audio (i.e. a 1-dB step in the audio level into the expander results in a 2-dB step in the output level from the expander).
- 4/ Buffer amplifiers - one to drive the Speaker Amplifier (part of U201) - the other to drive the RX\_OUT line to the I/O connector.

### Transmit Audio Path

Selects TX audio source either from the Microphone Amplifier or the TX\_IN line of the I/O connector under control of the microprocessor: -

- 1/ Provides band pass filtering having a pass band of 300 Hz to 3.4 kHz.
- 2/ Provides a compressor selectable under control of the microprocessor. The compressor provides a 2:1 compression of the TX audio (i.e. a 2-dB step in the audio level into the compressor results in a 1-dB step in the output level from the compressor).
- 3/ An emphasis circuit providing a +6 dB/octave emphasis over the frequency range of 300 Hz to 3.4 kHz.
- 4/ An amplitude limiter which prevents over modulation of the transmitter carrier.
- 5/ The output of the limiter drives the modulation input of the TXVCO.

### FFSK RX

Provides demodulation of the 1200-baud Fast Frequency Shift Keyed (FFSK) data transmissions used to provide data signalling between the base station and the mobile station.

### FFSK TX

Provides modulation of the 1200 baud FFSK data transmission used to provide data signalling between the mobile station and the base station.

### Ø Signal

The Ø Signal, comprising a tone at a frequency of one of 4 possible frequencies (3055, 3985, 4015 and 4045 Hz), is originated at the base station transmitter under the control of the Mobile Telephone Exchange (MTX). The use of 4 alternative Ø -signals allows the

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mobile to differentiate between channels in use at the local cell and channels used at more distant cells. When received at the mobile station it is filtered and then inserted back into the mobile station's transmission. Thus the Ø Signal is looped back to the base station receiver where it is used to assess the performance of the radio path. If the fixed part of the radio telephone system determines that the radio path performance is too poor to provide an acceptable speech quality the system will scan adjacent cell sites seeking an alternative site, thus providing improved speech quality. When an adjacent site has been located, the system initiates hand-off of the mobile to the adjacent cell on an alternative traffic channel.

## 8-Bit DAC

Provides digital to analogue conversion of data sent over the serial bus from the microprocessor. 3 DAC channels are provided VTXCO, POWER\_CTRL and PA\_Bias.

## Control

Provides interface to the SPI, enabling control of the Audio Processor by the microprocessor.

## 17.5 Processor

### Introduction

The processor used is the Atmel Atmega103L. This device provides the following facilities used within the phone;

- Atmel AVR<sup>®</sup> Enhanced RISC architecture.
- 121 powerful instructions – most single clock cycle execution.
- 128k bytes of in-system re-programmable flash program memory.
- SPI interface for in-system programming.
- 4k bytes of internal EEPROM.
- 4k bytes of internal SRAM.
- 32 X 8 general-purpose working registers + peripheral control registers.
- 32 X 8 programmable I/O lines, 8-output lines 8 input lines.
- Programmable serial UART + SPI serial interface.
- Fully static operation.
- RTC with separate oscillator.
- Two 8-bit Timer/Counters with separate prescaler and PWM.
- One 16-bit Timer/Counter with separate prescaler, compare, capture modes and dual 8, 9 or 10 bit PWM.
- Programmable watchdog timer with on-chip oscillator.
- On-chip analog comparator.
- 8-channel 10-bit ADC.
- Low power idle, power save and power down modes.
- Software selectable clock frequency.
- Program lock for software security.

### Clock Frequencies

Two clock frequencies, selectable under software control are provided. Under normal operation the processor operates at an instruction execution cycle rate defined by the 4.8 MHz quartz crystal (X301). Whilst in sleep mode. (I.e. phone powered down,) the processor runs at a lower instruction cycle rate defined by the 32.788 kHz ceramic resonator.

### External EEPROM

External EEPROM (64k) is provided by U302. This memory is used to store various user configurable settings e.g. the phone book.

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## SIM

The Subscriber Identification Module (SIM), comprising an 8-bit microprocessor (U303), is provided in order to prevent the illicit use of the mobile telephone's identification number. At certain stages during a mobile originated call an authentication procedure takes place. During this procedure a Secret Authentication Key (SAK), stored in the SIM is used to authenticate the use of the telephone and prevent fraud. The SAK is programmed into the SIM by Tellit during its manufacture. **In the event of the failure of the SIM a replacement SIM, programmed by Tellit, together with a replacement Rear Equipment Label, must be obtained and fitted. Associated with each programmed SIM is a serial number – the SIS number. When the SIM is replaced it will be necessary to register the SIS number of the replacement SIM with the System Operator.**

## Keyboard

The Keyboard comprises an array of printed switches arranged in matrix on the PCB activated by conductive rubber pads on the keymat. The state of the switches is scanned by the microprocessor by means of column and row lines.

## LCD Module

A LCD display panel-having graphics display capability is provided. The display interfaces to the microprocessor via serial clock (SCL) and serial data (SDL) lines. A series of LEDs are fitted to provide illumination for improved visibility. These also serve to illuminate the keypad.

## -4.8V Generator

A voltage converter stage (U203) generates a –4.8 V supply required as a power supply to the LCD display.

## 17.6 Power

### Speaker Amplifier

An audio frequency power amplifier located within U201 drives the speaker.

### Ringer Amplifier

An audio frequency power amplifier located within U201 drives the ringer.

### Reset Generator

Reset Generator circuit located within U201 provides a reset signal to the microprocessor. This causes the microprocessor to perform a power on reset initializing all I/O registers and the program counter. Once a normal power on reset has been completed, program execution proceeds with the processor in sleep mode.

### +3VA Regulator

A 3V linear voltage regulator located within U201 provides the +3VA supply line.

### +3VDIG Regulator

A 3V linear voltage regulator located within U201 provides the +3VDIG supply line.

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### 8-Bit Shift Register

The 8-bit shift register (U202) decodes commands sent by the microprocessor over the serial bus. These commands are used to control the following functions:

- HI\_CUR\_EN
- BATT\_TYPE
- 3V\_IF\_EN
- /3V\_RX\_EN
- 3V\_TX\_EN
- BUZZER\_EN
- SPEAKER\_EN

## 17.7 Connections

### System Connector (J104)

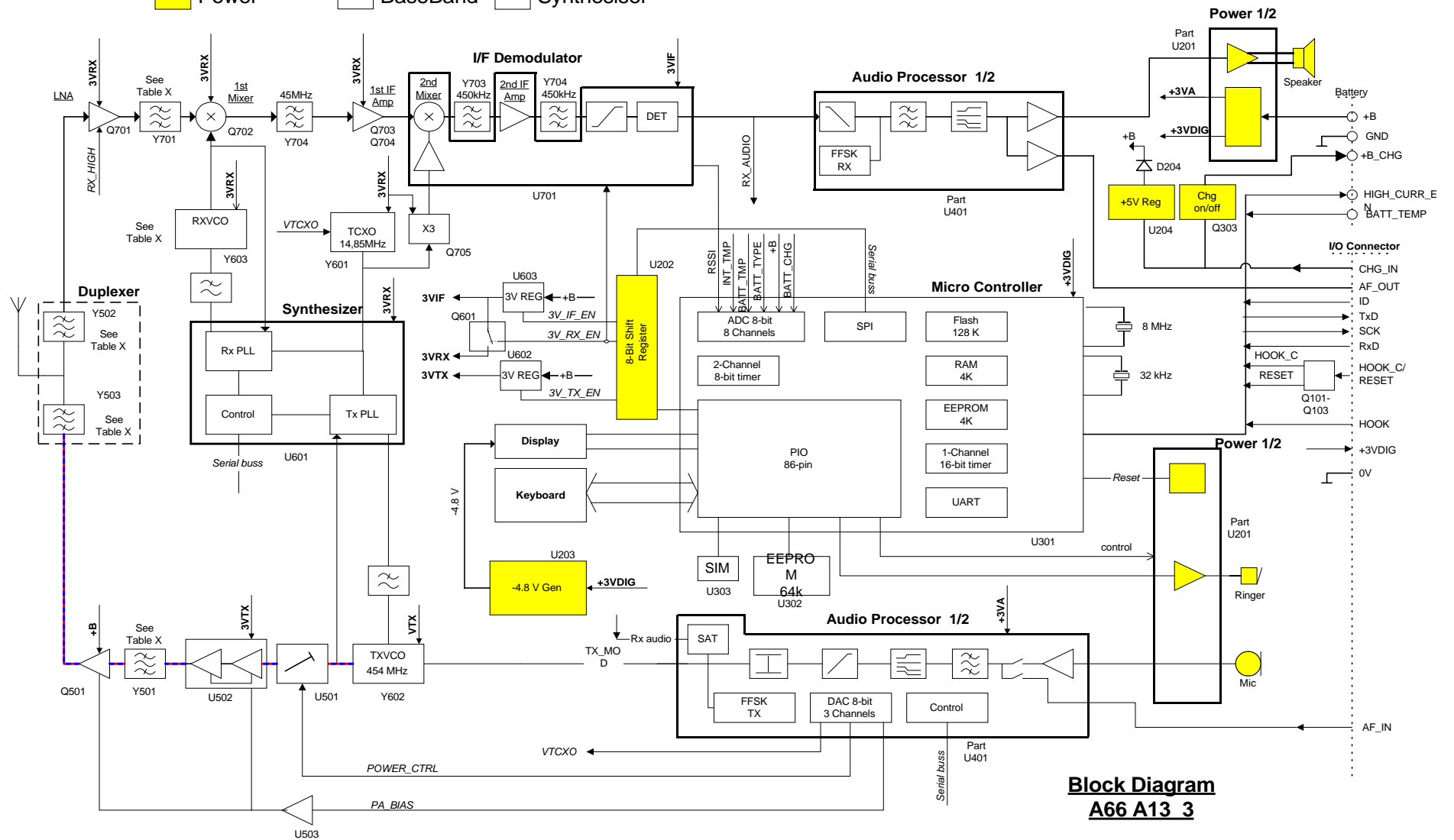
A 14 pole System Connector is provided for the use of various phone accessories and to enable the configuration, programming and test and diagnostic equipment.

### HOOK\_C/RESET Interface

The HOOK\_C/RESET interface is made up of Q101, Q103 & Q103. Signals input via the HOOK\_C/Reset level are decoded into two signals zero V for actuation and -4V for programming and processor reset.

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- Connections
- Power
- Processor
- BaseBand
- Transmitter
- Synthesiser
- Receiver



**Block Diagram  
A66 A13 3**

**Figure 17-1**